

### Mixed-Signal 32KB ISP FLASH MCU Family

#### - SAR ADC

- 12-Bit (C8051F000/1/2, C8051F005/6/7)
- 10-bit (C8051F010/1/2, C8051F015/6/7)
- ±1LSB INL; No Missing Codes
- Programmable Throughput up to 100ksps
- Up to 8 External Inputs; Programmable as Single-Ended or Differential
- Programmable Amplifier Gain: 16, 8, 4, 2, 1, 0.5
- Data Dependent Windowed Interrupt Generator
- Built-in Temperature Sensor  $(\pm 3^{\circ}C)$
- Two 12-bit DACs
- Two Analog Comparators
  - Programmable Hysteresis Values
  - Configurable to Generate Interrupts or Reset
- Voltage Reference
  - 2.4V; 15 ppm/°C
  - Available on External Pin
- Precision VDD Monitor/Brown-out Detector

#### **ON-CHIP JTAG DEBUG & BOUNDARY SCAN**

- On-Chip Debug Circuitry Facilitates Full Speed, Non-Intrusive In-System Debug (No Emulator Required!)
- Provides Breakpoints, Single Stepping, Watchpoints, Stack Monitor
- Inspect/Modify Memory and Registers
- Superior Performance to Emulation Systems Using ICE-Chips, Target Pods, and Sockets
- IEEE1149.1 Compliant Boundary Scan
- Low Cost Development Kit

#### HIGH SPEED 8051 µC CORE

- Pipelined Instruction Architecture; Executes 70% of Instruction Set in 1 or 2 System Clocks
- Up to 25MIPS Throughput with 25MHz Clock
- 21 Vectored Interrupt Sources

#### MEMORY

- 256 Bytes Internal Data RAM (F000/01/02/10/11/12)
- 2304 Bytes Internal Data RAM (F005/06/07/15/16/17)
- 32k Bytes FLASH; In-System Programmable in 512 byte Sectors

#### **DIGITAL PERIPHERALS**

- 4 Byte-Wide Port I/O; All are 5V tolerant
- Hardware SMBus<sup>™</sup> (I2C<sup>™</sup> Compatible), SPI<sup>™</sup>, and UART Serial Ports Available Concurrently
- Programmable 16-bit Counter/Timer Array with Five Capture/Compare Modules
- Four General Purpose 16-bit Counter/Timers
- Dedicated Watch-Dog Timer
- Bi-directional Reset

#### **CLOCK SOURCES**

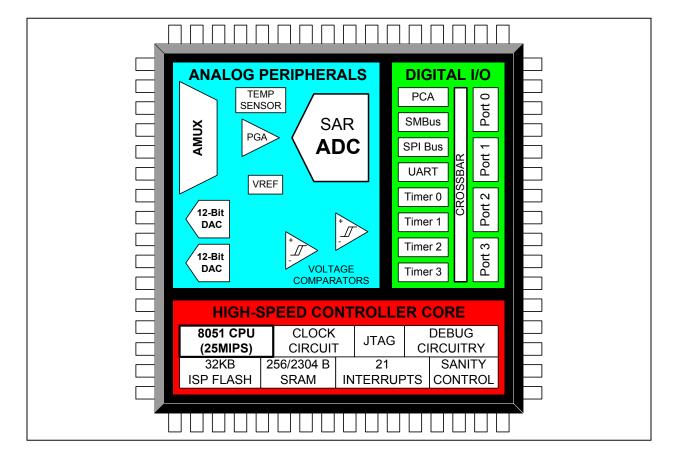
- Internal Programmable Oscillator: 2-to-16MHz
- External Oscillator: Crystal, RC,C, or Clock
- Can Switch Between Clock Sources on-the-fly; Useful in Power Saving Modes

#### SUPPLY VOLTAGE .....2.7V to 3.6V

- Typical Operating Current: 12.5mA @ 25MHz
- Multiple Power Saving Sleep and Shutdown Modes

#### 64-Pin TQFP, 48-Pin TQFP, 32-Pin LQFP

Temperature Range: -40°C to +85°C



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### 1. SYSTEM OVERVIEW

The C8051F000 family are fully integrated mixed-signal System on a Chip MCUs with a true 12-bit multi-channel ADC (F000/01/02/05/06/07), or a true 10-bit multi-channel ADC (F010/11/12/15/16/17). See the Product Selection Guide in Table 1.1 for a quick reference of each MCUs' feature set. Each has a programmable gain pre-amplifier, two 12-bit DACs, two voltage comparators (except for the F002/07/12/17, which have one), a voltage reference, and an 8051-compatible microcontroller core with 32kbytes of FLASH memory. There are also I2C/SMBus, UART, and SPI serial interfaces implemented in hardware (not "bit-banged" in user software) as well as a Programmable Counter/Timer Array (PCA) with five capture/compare modules. There are also 4 general-purpose 16-bit timers and 4 byte-wide general-purpose digital Port I/O. The C8051F000/01/02/10/11/12 have 256 bytes of RAM and execute up to 20MIPS, while the C8051F005/06/07/15/16/17 have 2304 bytes of RAM and execute up to 25MIPS.

With an on-board VDD monitor, WDT, and clock oscillator, the MCUs are truly stand-alone System-on-a-Chip solutions. Each MCU effectively configures and manages the analog and digital peripherals. The FLASH memory can be reprogrammed even in-circuit, providing non-volatile data storage, and also allowing field upgrades of the 8051 firmware. Each MCU can also individually shut down any or all of the peripherals to conserve power.

On-board JTAG debug support allows non-intrusive (uses no on-chip resources), full speed, in-circuit debug using the production MCU installed in the final application. This debug system supports inspection and modification of memory and registers, setting breakpoints, watchpoints, single stepping, and run and halt commands. All analog and digital peripherals are fully functional when using JTAG debug.

Each MCU is specified for 2.7V-to-3.6V operation over the industrial temperature range (-45C to +85C). The Port I/Os, /RST, and JTAG pins are tolerant for input signals up to 5V. The C8051F000/05/10/15 are available in the 64-pin TQFP (see block diagram in Figure 1.1). The C8051F001/06/11/16 are available in the 48-pin TQFP (see block diagram in Figure 1.2). The C8051F002/07/12/17 are available in the 32-pin LQFP (see block diagram in Figure 1.3).

	MIPS (Peak)	FLASH Memory	RAM	SMBus/I2C	SPI	UART	Timers (16-bit)	Programmable Counter Array	Digital Port I/O's	ADC Resolution (bits)	ADC Max Speed (ksps)	ADC Inputs	Voltage Reference	Temperature Sensor	DAC Resolution	DAC Outputs	Voltage Comparators	Package
C8051F000	20	32k	256		$\checkmark$	$\checkmark$	4		32	12	100	8	$\checkmark$	$\checkmark$	12	2	2	64TQFP
C8051F001	20	32k	256		$\checkmark$		4		16	12	100	8	$\checkmark$	$\checkmark$	12	2	2	48TQFP
C8051F002	20	32k	256		$\checkmark$		4		8	12	100	4	$\checkmark$	$\checkmark$	12	2	1	32LQFP
C8051F005	25	32k	2304		$\checkmark$	$\checkmark$	4		32	12	100	8	$\checkmark$	$\checkmark$	12	2	2	64TQFP
C8051F006	25	32k	2304		$\checkmark$		4		16	12	100	8	$\checkmark$	$\checkmark$	12	2	2	48TQFP
C8051F007	25	32k	2304	$\checkmark$	$\checkmark$		4		8	12	100	4	$\checkmark$	$\checkmark$	12	2	1	32LQFP
C8051F010	20	32k	256		$\checkmark$		4		32	10	100	8	$\checkmark$	$\checkmark$	12	2	2	64TQFP
C8051F011	20	32k	256				4		16	10	100	8	$\checkmark$	$\checkmark$	12	2	2	48TQFP
C8051F012	20	32k	256				4		8	10	100	4	$\checkmark$	$\checkmark$	12	2	1	32LQFP
C8051F015	25	32k	2304				4		32	10	100	8	$\checkmark$	$\checkmark$	12	2	2	64TQFP
C8051F016	25	32k	2304				4		16	10	100	8	$\checkmark$	$\checkmark$	12	2	2	48TQFP
C8051F017	25	32k	2304		$\checkmark$	$\checkmark$	4		8	10	100	4	$\checkmark$	$\checkmark$	12	2	1	32LQFP

 Table 1.1. Product Selection Guide



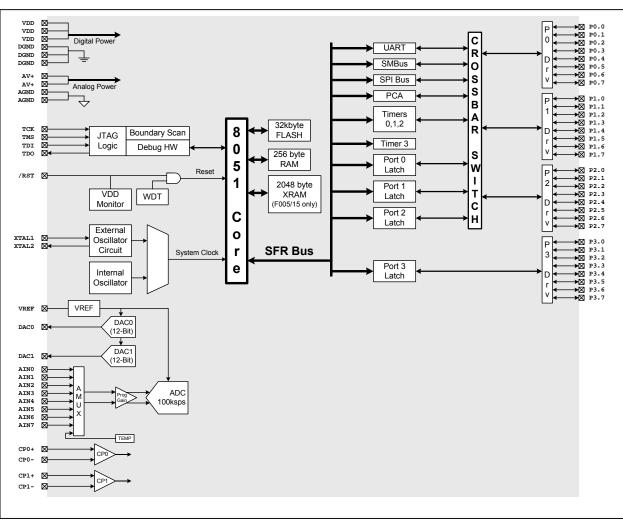


Figure 1.1. C8051F000/05/10/15 Block Diagram



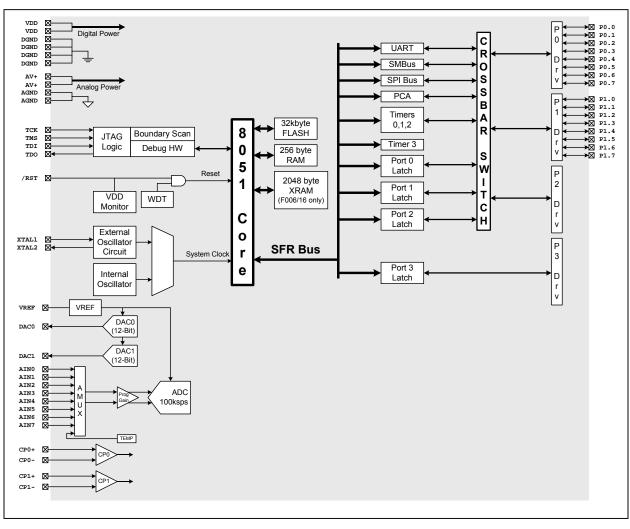


Figure 1.2. C8051F001/06/11/16 Block Diagram



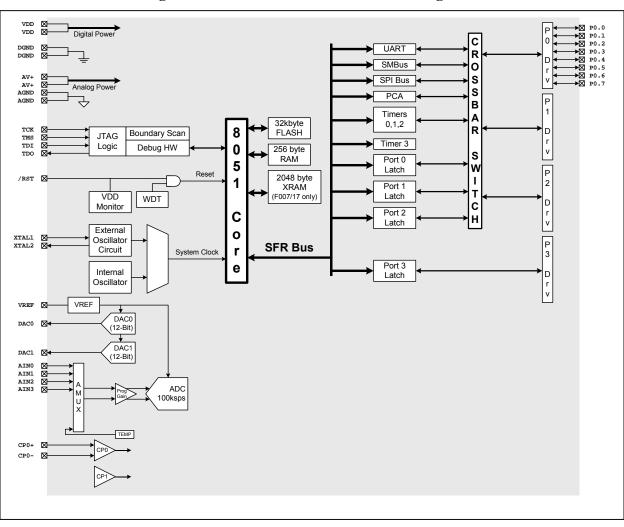


Figure 1.3. C8051F002/07/12/17 Block Diagram



### 1.1. $CIP-51^{TM} CPU$

#### 1.1.1. Fully 8051 Compatible

The C8051F000 family utilizes Silicon Laboratories' proprietary CIP-51 microcontroller core. The CIP-51 is fully compatible with the MCS-51<sup>TM</sup> instruction set. Standard 803x/805x assemblers and compilers can be used to develop software. The core has all the peripherals included with a standard 8052, including four 16-bit counter/timers, a full-duplex UART, 256 bytes of internal RAM space, 128 byte Special Function Register (SFR) address space, and four byte-wide I/O Ports.

#### **1.1.2.** Improved Throughput

The CIP-51 employs a pipelined architecture that greatly increases its instruction throughput over the standard 8051 architecture. In a standard 8051, all instructions except for MUL and DIV take 12 or 24 system clock cycles to execute with a maximum system clock of 12-to-24MHz. By contrast, the CIP-51 core executes 70% of its instructions in one or two system clock cycles, with only four instructions taking more than four system clock cycles.

The CIP-51 has a total of 109 instructions. The number of instructions versus the system clock cycles to execute them is as follows:

Instructions	26	50	5	14	7	3	1	2	1
Clocks to Execute	1	2	2/3	3	3/4	4	4/5	5	8

With the CIP-51's maximum system clock at 25MHz, it has a peak throughput of 25MIPS. Figure 1.4 shows a comparison of peak throughputs of various 8-bit microcontroller cores with their maximum system clocks.

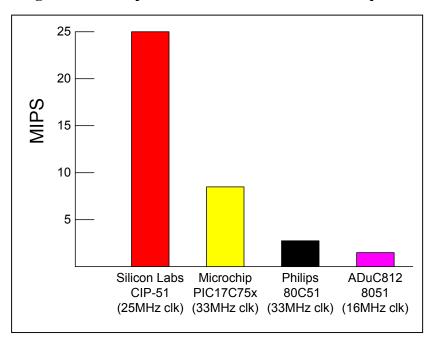


Figure 1.4. Comparison of Peak MCU Execution Speeds



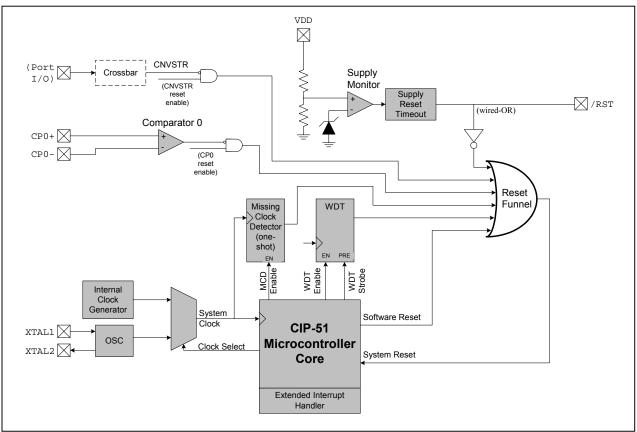
#### **1.1.3.** Additional Features

The C8051F000 MCU family has several key enhancements both inside and outside the CIP-51 core to improve its overall performance and ease of use in the end applications.

The extended interrupt handler provides 21 interrupt sources into the CIP-51 (as opposed to 7 for the standard 8051), allowing the numerous analog and digital peripherals to interrupt the controller. An interrupt driven system requires less intervention by the MCU, giving it more effective throughput. The extra interrupt sources are very useful when building multi-tasking, real-time systems.

There are up to seven reset sources for the MCU: an on-board VDD monitor, a Watchdog Timer, a missing clock detector, a voltage level detection from Comparator 0, a forced software reset, the CNVSTR pin, and the /RST pin. The /RST pin is bi-directional, accommodating an external reset, or allowing the internally generated POR to be output on the /RST pin. Each reset source except for the VDD monitor and Reset Input Pin may be disabled by the user in software. The WDT may be permanently enabled in software after a power-on reset during MCU initialization.

The MCU has an internal, stand alone clock generator which is used by default as the system clock after any reset. If desired, the clock source may be switched on the fly to the external oscillator, which can use a crystal, ceramic resonator, capacitor, RC, or external clock source to generate the system clock. This can be extremely useful in low power applications, allowing the MCU to run from a slow (power saving) external crystal source, while periodically switching to the fast (up to 16MHz) internal oscillator as needed.



### Figure 1.5. On-Board Clock and Reset

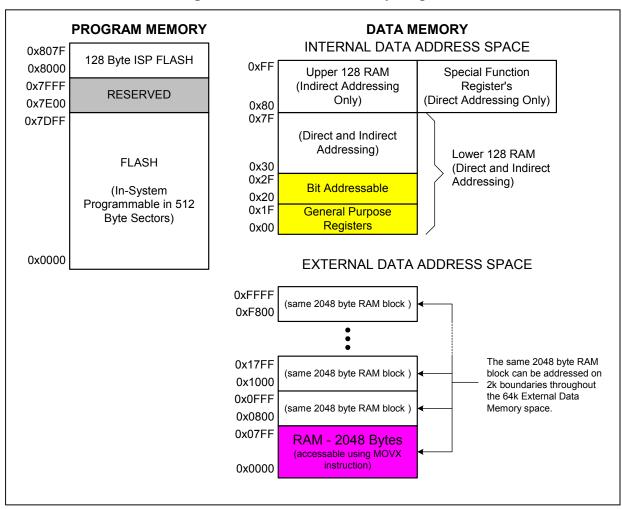


#### 1.2. On-Board Memory

The CIP-51 has a standard 8051 program and data address configuration. It includes 256 bytes of data RAM, with the upper 128 bytes dual-mapped. Indirect addressing accesses the upper 128 bytes of general purpose RAM, and direct addressing accesses the 128 byte SFR address space. The lower 128 bytes of RAM are accessible via direct and indirect addressing. The first 32 bytes are addressable as four banks of general-purpose registers, and the next 16 bytes can be byte addressable or bit addressable.

The CIP-51 in the C8051F005/06/07/15/16/17 MCUs additionally has a 2048 byte RAM block in the external data memory address space. This 2048 byte block can be addressed over the entire 64k external data memory address range (see Figure 1.6).

The MCU's program memory consists of 32k + 128 bytes of FLASH. This memory may be reprogrammed insystem in 512 byte sectors, and requires no special off-chip programming voltage. The 512 bytes from addresses 0x7E00 to 0x7FFF are reserved for factory use. There is also a single 128-byte sector at address 0x8000 to 0x807F, which may be useful as a small table for software constants or as additional program space. See Figure 1.6 for the MCU system memory map.



#### Figure 1.6. On-Board Memory Map



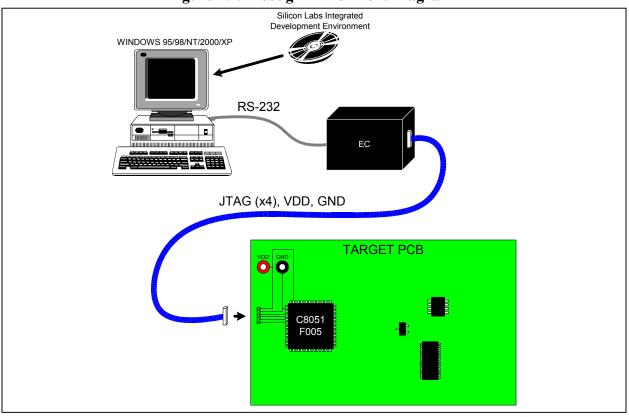
### 1.3. JTAG Debug and Boundary Scan

The C8051F000 family has on-chip JTAG and debug circuitry that provide *non-intrusive, full speed, in-circuit debug using the production part installed in the end application* using the four-pin JTAG I/F. The JTAG port is fully compliant to IEEE 1149.1, providing full boundary scan for test and manufacturing purposes.

Silicon Labs' debug system supports inspection and modification of memory and registers, breakpoints, watchpoints, a stack monitor, and single stepping. No additional target RAM, program memory, timers, or communications channels are required. All the digital and analog peripherals are functional and work correctly while debugging. All the peripherals (except for the ADC) are stalled when the MCU is halted, during single stepping, or at a breakpoint in order to keep them in sync.

The C8051F000DK, C8051F005DK, C8051F010DK, and C8051F015DK are development kits with all the hardware and software necessary to develop application code and perform in-circuit debug with the C8051F000/1/2, F005/6/7, F010/1/2, and F015/6/7 MCUs respectively. The kit includes software with a developer's studio and debugger, an integrated 8051 assembler, and an RS-232 to JTAG protocol translator module referred to as the EC. It also has a target application board with the associated MCU installed and a large prototyping area, plus the RS-232 and JTAG cables, and wall-mount power supply. The Development Kit requires a Windows 95/98/NT/2000/XP computer with one available RS-232 serial port. As shown in Figure 1.7, the PC is connected via RS-232 to the EC. A six-inch ribbon cable connects the EC to the user's application board, picking up the four JTAG pins and VDD and GND. The EC takes its power from the application board. It requires roughly 20mA at 2.7-3.6V. For applications where there is not sufficient power available from the target board, the provided power supply can be connected directly to the EC.

This is a vastly superior configuration for developing and debugging embedded applications compared to standard MCU Emulators, which use on-board "ICE Chips" and target cables and require the MCU in the application board to be socketed. Silicon Labs' debug environment both increases ease of use and preserves the performance of the precision analog peripherals.







#### 1.4. Programmable Digital I/O and Crossbar

The standard 8051 Ports (0, 1, 2, and 3) are available on the MCUs. All four ports are pinned out on the F000/05/10/15. Ports 0 and 1 are pinned out on the F001/06/11/16, and only Port 0 is pinned out on the F002/07/12/17. The Ports not pinned out are still available for software use as general purpose registers. The Port I/O behave like the standard 8051 with a few enhancements.

Each Port I/O pin can be configured as either a push-pull or open-drain output. Also, the "weak pull-ups" which are normally fixed on an 8051 can be globally disabled, providing additional power saving capabilities for low power applications.

Perhaps the most unique enhancement is the Digital Crossbar. This is essentially a large digital switching network that allows mapping of internal digital system resources to Port I/O pins on P0, P1, and P2. (See Figure 1.8.) Unlike microcontrollers with standard multiplexed digital I/O, all combinations of functions are supported.

The on-board counter/timers, serial buses, HW interrupts, ADC Start of Conversion input, comparator outputs, and other digital signals in the controller can be configured to appear on the Port I/O pins specified in the Crossbar Control registers. This allows the user to select the exact mix of general purpose Port I/O and digital resources needed for his particular application.

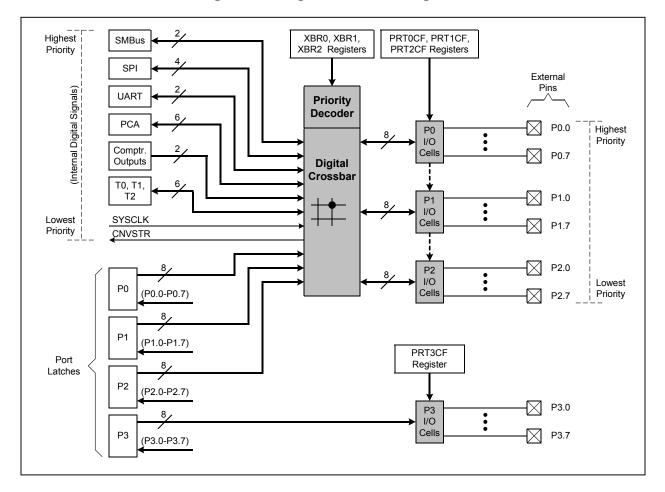


Figure 1.8. Digital Crossbar Diagram



#### **1.5. Programmable Counter Array**

The C8051F000 MCU family has an on-board Programmable Counter/Timer Array (PCA) in addition to the four 16-bit general-purpose counter/timers. The PCA consists of a dedicated 16-bit counter/timer timebase with 5 programmable capture/compare modules. The timebase gets its clock from one of four sources: the system clock divided by 12, the system clock divided by 4, Timer 0 overflow, or an External Clock Input (ECI).

Each capture/compare module can be configured to operate in one of four modes: Edge-Triggered Capture, Software Timer, High Speed Output, or Pulse Width Modulator. The PCA Capture/Compare Module I/O and External Clock Input are routed to the MCU Port I/O via the Digital Crossbar.

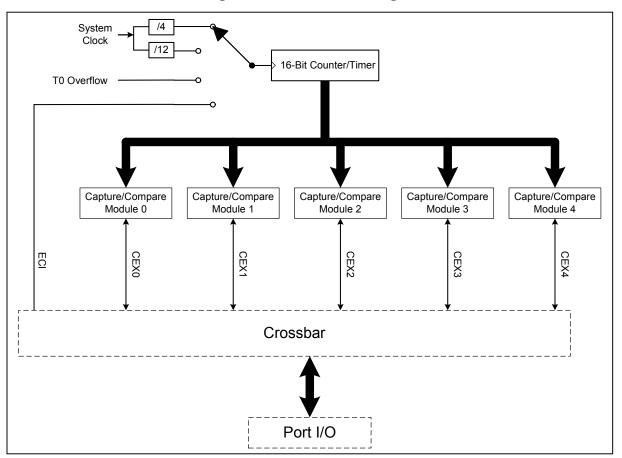


Figure 1.9. PCA Block Diagram

#### 1.6. Serial Ports

The C8051F000 MCU Family includes a Full-Duplex UART, SPI Bus, and I2C/SMBus. Each of the serial buses is fully implemented in hardware and makes extensive use of the CIP-51's interrupts, thus requiring very little intervention by the CPU. The serial buses do not "share" resources such as timers, interrupts, or Port I/O, so any or all of the serial buses may be used together.



#### **1.7.** Analog to Digital Converter

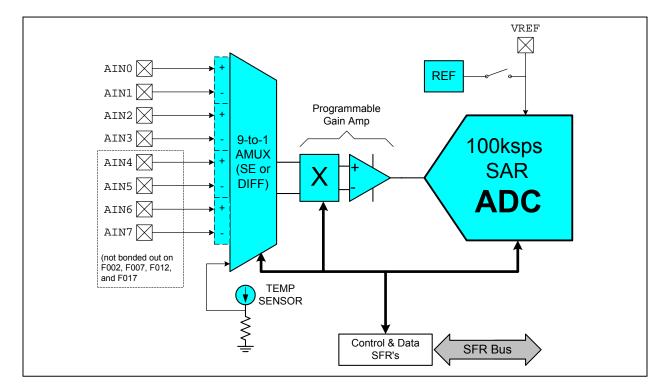
The C8051F000/1/2/5/6/7 has an on-chip 12-bit SAR ADC with a 9-channel input multiplexer and programmable gain amplifier. With a maximum throughput of 100ksps, the ADC offers true 12-bit accuracy with an INL of  $\pm$ 1LSB. The ADC in the C8051F010/1/2/5/6/7 is similar, but with 10-bit resolution. Each ADC has a maximum throughput of 100ksps. Each ADC has an INL of  $\pm$ 1LSB, offering true 12-bit accuracy with the C8051F00x, and true 10-bit accuracy with the C8051F01x. There is also an on-board 15ppm voltage reference, or an external reference may be used via the VREF pin.

The ADC is under full control of the CIP-51 microcontroller via the Special Function Registers. One input channel is tied to an internal temperature sensor, while the other eight channels are available externally. Each pair of the eight external input channels can be configured as either two single-ended inputs or a single differential input. The system controller can also put the ADC into shutdown to save power.

A programmable gain amplifier follows the analog multiplexer. The gain can be set in software from 0.5 to 16 in powers of 2. The gain stage can be especially useful when different ADC input channels have widely varied input voltage signals, or when it is necessary to "zoom in" on a signal with a large DC offset (in differential mode, a DAC could be used to provide the DC offset).

Conversions can be started in four ways; a software command, an overflow on Timer 2, an overflow on Timer 3, or an external signal input. This flexibility allows the start of conversion to be triggered by software events, external HW signals, or convert continuously. A completed conversion causes an interrupt, or a status bit can be polled in software to determine the end of conversion. The resulting 10 or 12-bit data word is latched into two SFRs upon completion of a conversion. The data can be right or left justified in these registers under software control.

Compare registers for the ADC data can be configured to interrupt the controller when ADC data is within a specified window. The ADC can monitor a key voltage continuously in background mode, but not interrupt the controller unless the converted data is within the specified window.



#### Figure 1.10. ADC Diagram



### **1.8.** Comparators and DACs

The C8051F000 MCU Family has two 12-bit DACs and two comparators on chip (the second comparator, CP1, is not bonded out on the F002, F007, F012, and F017). The MCU data and control interface to each comparator and DAC is via the Special Function Registers. The MCU can place any DAC or comparator in low power shutdown mode.

The comparators have software programmable hysteresis. Each comparator can generate an interrupt on its rising edge, falling edge, or both. The comparators' output state can also be polled in software. These interrupts are capable of waking up the MCU from idle mode. The comparator outputs can be programmed to appear on the Port I/O pins via the Crossbar.

The DACs are voltage output mode and use the same voltage reference as the ADC. They are especially useful as references for the comparators or offsets for the differential inputs of the ADC.

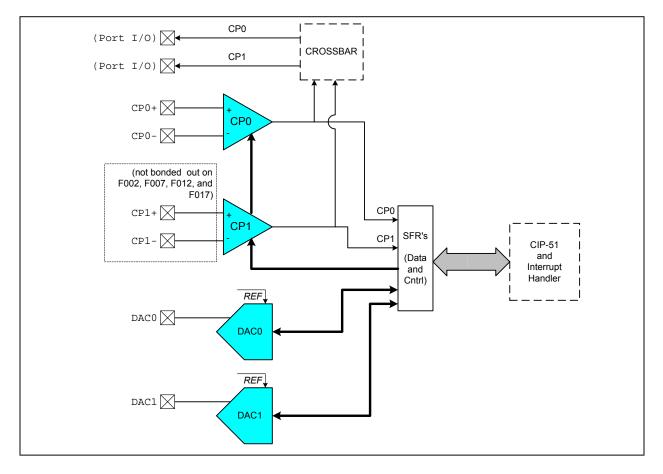


Figure 1.11. Comparator and DAC Diagram



### 2. ABSOLUTE MAXIMUM RATINGS\*

Ambient temperature under bias	55 to 125°C
Storage Temperature	-65 to 150°C
Voltage on any Pin (except VDD and Port I/O) with respect to DGND	$\dots -0.3$ V to (VDD + 0.3V)
Voltage on any Port I/O Pin or /RST with respect to DGND	-0.3V to 5.8V
Voltage on VDD with respect to DGND	0.3V to 4.2V
Maximum Total current through VDD, AV+, DGND and AGND	800mA
Maximum output current sunk by any Port pin	100mA
Maximum output current sunk by any other I/O pin	25mA
Maximum output current sourced by any Port pin	100mA
Maximum output current sourced by any other I/O pin	25mA

\*Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the devices at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

### 3. GLOBAL DC ELECTRICAL CHARACTERISTICS

PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
Analog Supply Voltage	(Note 1)	2.7	3.0	3.6	V
Analog Supply Current	Internal REF, ADC, DAC, Comparators all active		1	2	mA
Analog Supply Current with analog sub-systems inactive	Internal REF, ADC, DAC, Comparators all disabled, oscillator disabled		5	20	μΑ
Analog-to-Digital Supply Delta (   VDD – AV+   )				0.5	V
Digital Supply Voltage		2.7	3.0	3.6	V
Digital Supply Current with	VDD = 2.7V, Clock=25MHz		12.5		mA
CPU active	VDD = 2.7V, Clock=1MHz		0.5		mA
	VDD = 2.7V, Clock=32kHz		10		μΑ
Digital Supply Current	Oscillator not running		5		μΑ
(shutdown)					
Digital Supply RAM Data Retention Voltage			1.5		V
Specified Operating Temperature Range		-40		+85	°C
SYSCLK (System Clock Frequency)	C8051F005/6/7, C8051F015/6/7 (Note 2)	0		25	MHz
SYSCLK (System Clock Frequency)	C8051F000/1/2, C8051F010/1/2 (Note 2)	0		20	MHz
Tsysl (SYSCLK Low Time)		18			ns
Tsysh (SYSCLK High Time)		18			ns

-40°C to +85°C unless otherwise specified.

Note 1: Analog Supply AV+ must be greater than 1V for VDD monitor to operate. Note 2: SYSCLK must be at least 32 kHz to enable debugging.



### 4. PINOUT AND PACKAGE DEFINITIONS

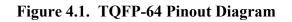
### Table 4.1. Pin Definitions

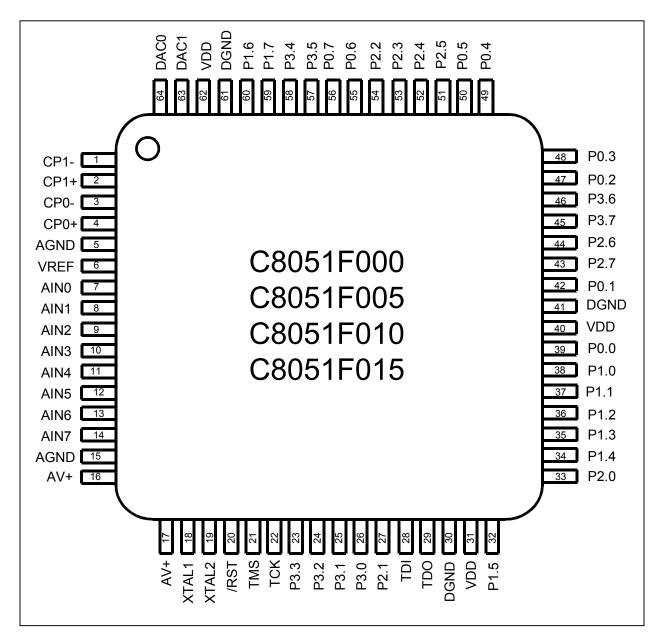
	Pin Numbers				
Name	F000 F005	F001 F006	F002 F007	Туре	Description
1 vanie	F010	F011	F012	Type	Description
VDD	F015	F016	F017		Digital Voltage Supply.
VDD	31, 40,	23, 32	18, 20		Digital voltage supply.
	40, 62	52	20		
DGND	30,	22,	17,		Digital Ground.
DOMD	41,	33,	21		Digital Orbana.
	61	27,	21		
		19			
AV+	16,	13,	9,		Positive Analog Voltage Supply.
	17	43	29		
AGND	5,	44,	8,		Analog Ground.
	15	12	30		
TCK	22	18	14	D In	JTAG Test Clock with internal pull-up.
TMS	21	17	13	D In	JTAG Test-Mode Select with internal pull-up.
TDI	28	20	15	D In	JTAG Test Data Input with internal pull-up. TDI is latched on a rising edge of TCK.
TDO	29	21	16	D Out	JTAG Test Data Output with internal pull-up. Data is shifted out on TDO on the falling edge of TCK. TDO output is a tri-state driver.
XTAL1	18	14	10	A In	Crystal Input. This pin is the return for the internal oscillator circuit for a crystal or ceramic resonator. For a precision internal clock, connect a crystal or ceramic resonator from XTAL1 to XTAL2. If overdriven by an external CMOS clock, this becomes the system clock.
XTAL2	19	15	11	A Out	Crystal Output. This pin is the excitation driver for a crystal or ceramic resonator.
/RST	20	16	12	D I/O	Chip Reset. Open-drain output of internal Voltage Supply monitor. Is driven low when VDD is < 2.7V. An external source can force a system reset by driving this pin low.
VREF	6	3	3	A I/O	Voltage Reference. When configured as an input, this pin is the voltage reference for the MCU. Otherwise, the internal reference drives this pin.
CP0+	4	2	2	A In	Comparator 0 Non-Inverting Input.
CP0-	3	1	1	A In	Comparator 0 Inverting Input.
CP1+	2	45		A In	Comparator 1 Non-Inverting Input.
CP1-	1	46		A In	Comparator 1 Inverting Input.
DAC0	64	48	32	A Out	Digital to Analog Converter Output 0. The DAC0 voltage output. (See Section 7 DAC Specification for complete description).
DAC1	63	47	31	A Out	Digital to Analog Converter Output 1. The DAC1 voltage output. (See Section 7 DAC Specification for complete description).
AIN0	7	4	4	A In	Analog Mux Channel Input 0. (See ADC Specification for complete description).
AIN1	8	5	5	A In	Analog Mux Channel Input 1. (See ADC Specification for complete description).
AIN2	9	6	6	A In	Analog Mux Channel Input 2. (See ADC Specification for complete description).
AIN3	10	7	7	A In	Analog Mux Channel Input 3. (See ADC Specification for complete description).
AIN4	11	8		A In	Analog Mux Channel Input 4. (See ADC Specification for complete description).
AIN5	12	9		A In	Analog Mux Channel Input 5. (See ADC Specification for complete description).



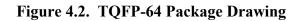
	Pin	Numb	oers		
Name	F000 F005 F010 F015	F001 F006 F011 F016	F002 F007 F012 F017	Туре	Description
AIN6	13	10	1017	A In	Analog Mux Channel Input 6. (See ADC Specification for complete
					description).
AIN7	14	11		A In	Analog Mux Channel Input 7. (See ADC Specification for complete description).
P0.0	39	31	19	D I/O	Port0 Bit0. (See the Port I/O Sub-System section for complete description).
P0.1	42	34	22	D I/O	Port0 Bit1. (See the Port I/O Sub-System section for complete description).
P0.2	47	35	23	D I/O	Port0 Bit2. (See the Port I/O Sub-System section for complete description).
P0.3	48	36	24	D I/O	Port0 Bit3. (See the Port I/O Sub-System section for complete description).
P0.4	49	37	25	D I/O	Port0 Bit4. (See the Port I/O Sub-System section for complete description).
P0.5	50	38	26	D I/O	Port0 Bit5. (See the Port I/O Sub-System section for complete description).
P0.6	55	39	27	D I/O	Port0 Bit6. (See the Port I/O Sub-System section for complete description).
P0.7	56	40	28	D I/O	Port0 Bit7. (See the Port I/O Sub-System section for complete description).
P1.0	38	30		D I/O	Port1 Bit0. (See the Port I/O Sub-System section for complete description).
P1.1	37	29		D I/O	Port1 Bit1. (See the Port I/O Sub-System section for complete description).
P1.2	36	28		D I/O	Port1 Bit2. (See the Port I/O Sub-System section for complete description).
P1.3	35	26		D I/O	Port1 Bit3. (See the Port I/O Sub-System section for complete description).
P1.4	34	25		D I/O	Port1 Bit4. (See the Port I/O Sub-System section for complete description).
P1.5	32	24		D I/O	Port1 Bit5. (See the Port I/O Sub-System section for complete description).
P1.6	60	42		D I/O	Port1 Bit6. (See the Port I/O Sub-System section for complete description).
P1.7	59	41		D I/O	Port1 Bit7. (See the Port I/O Sub-System section for complete description).
P2.0	33			D I/O	Port2 Bit0. (See the Port I/O Sub-System section for complete description).
P2.1	27			D I/O	Port2 Bit1. (See the Port I/O Sub-System section for complete description).
P2.2	54			D I/O	Port2 Bit2. (See the Port I/O Sub-System section for complete description).
P2.3	53			D I/O	Port2 Bit3. (See the Port I/O Sub-System section for complete description).
P2.4	52			D I/O	Port2 Bit4. (See the Port I/O Sub-System section for complete description).
P2.5	51			D I/O	Port2 Bit5. (See the Port I/O Sub-System section for complete description).
P2.6	44			D I/O	Port2 Bit6. (See the Port I/O Sub-System section for complete description).
P2.7	43			D I/O	Port2 Bit7. (See the Port I/O Sub-System section for complete description).
P3.0	26			D I/O	Port3 Bit0. (See the Port I/O Sub-System section for complete description).
P3.1	25			D I/O	Port3 Bit1. (See the Port I/O Sub-System section for complete description).
P3.2	24			D I/O	Port3 Bit2. (See the Port I/O Sub-System section for complete description).
P3.3	23			D I/O	Port3 Bit3. (See the Port I/O Sub-System section for complete description).
P3.4	58			D I/O	Port3 Bit4. (See the Port I/O Sub-System section for complete description).
P3.5	57			D I/O	Port3 Bit5. (See the Port I/O Sub-System section for complete description).
P3.6	46			D I/O	Port3 Bit6. (See the Port I/O Sub-System section for complete description).
P3.7	45			D I/O	Port3 Bit7. (See the Port I/O Sub-System section for complete description).











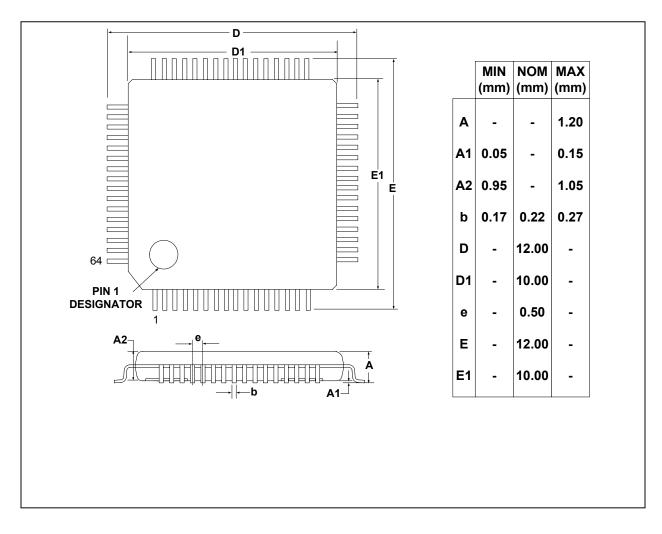
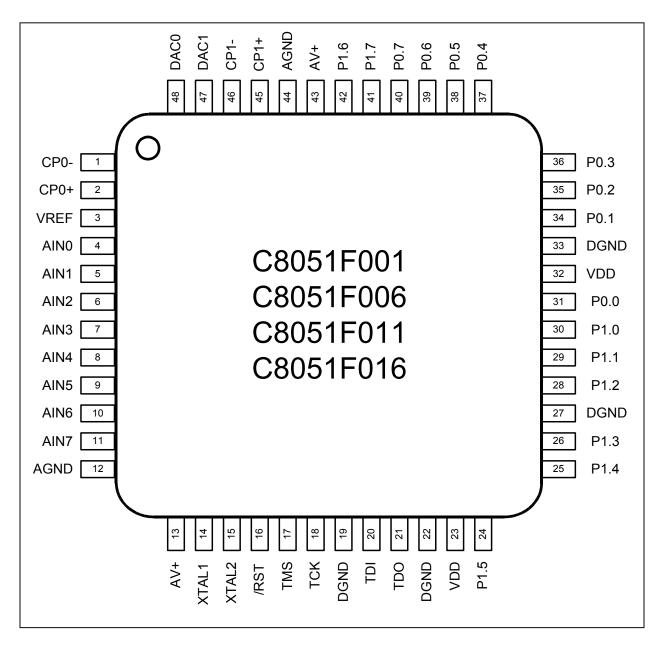




Figure 4.3. TQFP-48 Pinout Diagram





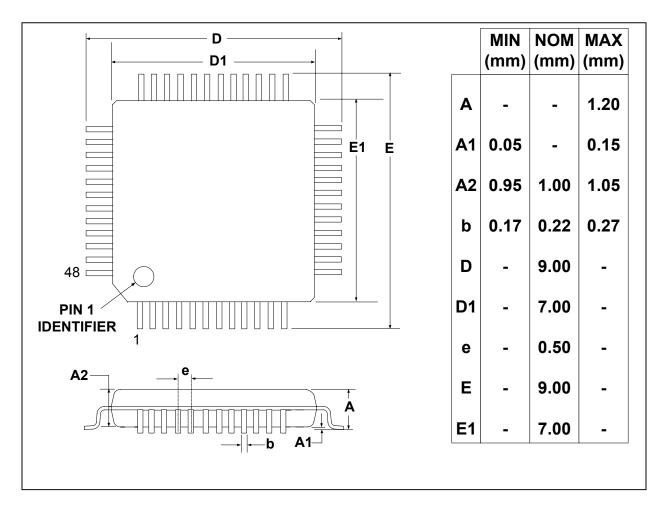
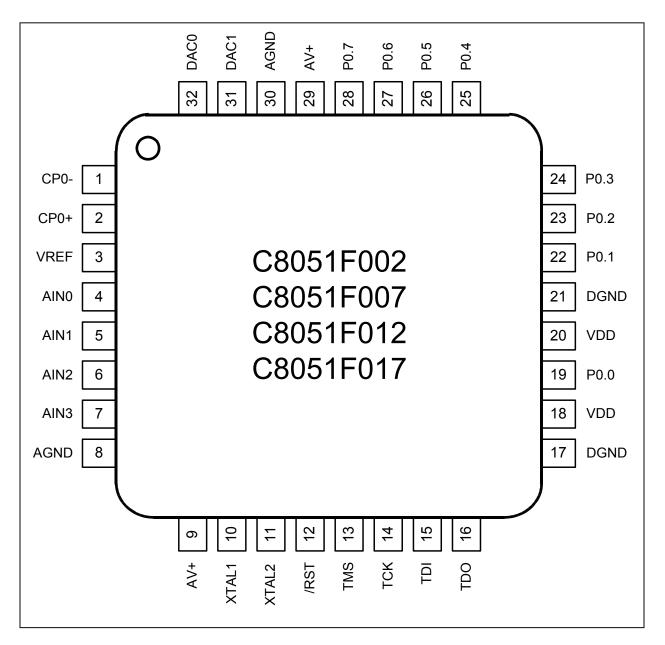


Figure 4.4. TQFP-48 Package Drawing



Figure 4.5. LQFP-32 Pinout Diagram





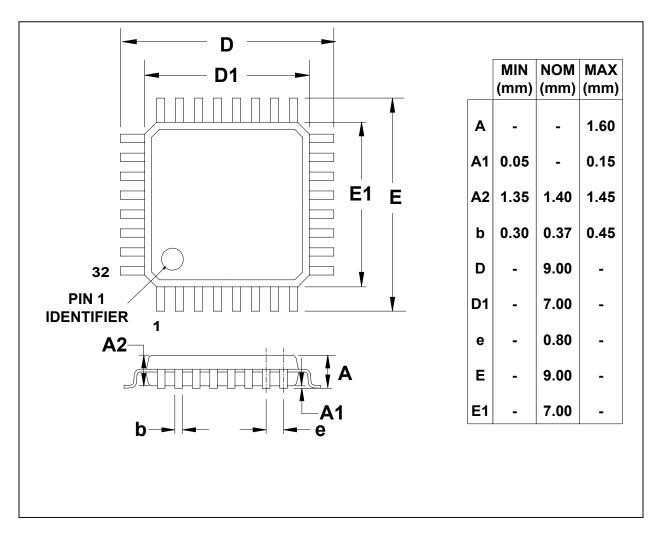
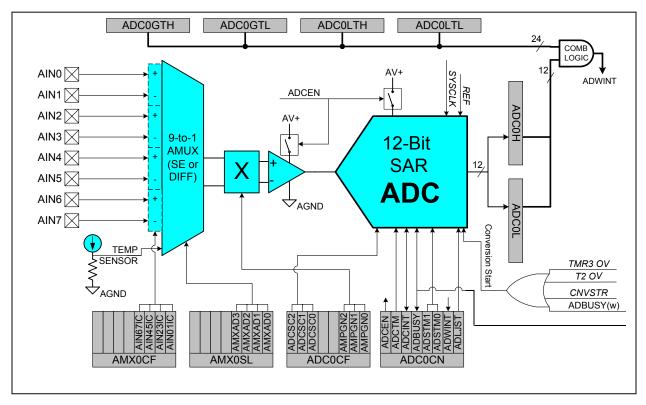


Figure 4.6. LQFP-32 Package Drawing



### 5. ADC (12-Bit, C8051F000/1/2/5/6/7 Only)

The ADC subsystem for the C8051F000/1/2/5/6/7 consists of a 9-channel, configurable analog multiplexer (AMUX), a programmable gain amplifier (PGA), and a 100ksps, 12-bit successive-approximation-register ADC with integrated track-and-hold and programmable window detector (see block diagram in Figure 5.1). The AMUX, PGA, Data Conversion Modes, and Window Detector are all configurable under software control via the Special Function Register's shown in Figure 5.1. The ADC subsystem (ADC, track-and-hold and PGA) is enabled only when the ADCEN bit in the ADC Control register (ADC0CN, Figure 5.7) is set to 1. The ADC subsystem is in low power shutdown when this bit is 0. The Bias Enable bit (BIASE) in the REF0CN register (see Figure 9.2) must be set to 1 in order to supply bias to the ADC.





### 5.1. Analog Multiplexer and PGA

Eight of the AMUX channels are available for external measurements while the ninth channel is internally connected to an on-board temperature sensor (temperature transfer function is shown in Figure 5.3). Note that the PGA gain is applied to the temperature sensor reading. AMUX input pairs can be programmed to operate in either the differential or single-ended mode. This allows the user to select the best measurement technique for each input channel, and even accommodates mode changes "on-the-fly". The AMUX defaults to all single-ended inputs upon reset. There are two registers associated with the AMUX: the Channel Selection register AMX0SL (Figure 5.5), and the Configuration register AMX0CF (Figure 5.4). The table in Figure 5.5 shows AMUX functionality by channel for each possible configuration. The PGA amplifies the AMUX output signal by an amount determined by the AMPGN2-0 bits in the ADC Configuration register, ADC0CF (Figure 5.6). The PGA can be software-programmed for gains of 0.5, 1, 2, 4, 8 or 16. It defaults to unity gain on reset.



#### 5.2. ADC Modes of Operation

The ADC uses VREF to determine its full-scale voltage, thus the reference must be properly configured before performing a conversion (see Section 9). The ADC has a maximum conversion speed of 100ksps. The ADC conversion clock is derived from the system clock. Conversion clock speed can be reduced by a factor of 2, 4, 8 or 16 via the ADCSC bits in the ADC0CF Register. This is useful to adjust conversion speed to accommodate different system clock speeds.

A conversion can be initiated in one of four ways, depending on the programmed states of the ADC Start of Conversion Mode bits (ADSTM1, ADSTM0) in ADC0CN. Conversions may be initiated by:

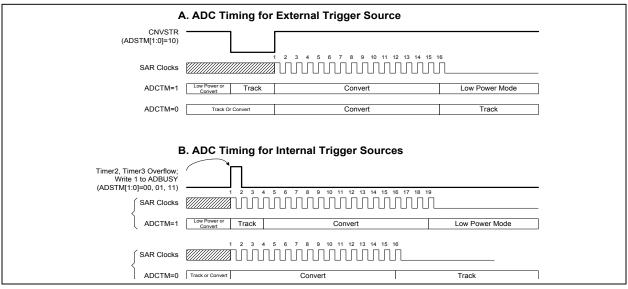
- 1. Writing a 1 to the ADBUSY bit of ADC0CN;
- 2. A Timer 3 overflow (i.e. timed continuous conversions);
- 3. A rising edge detected on the external ADC convert start signal, CNVSTR;
- 4. A Timer 2 overflow (i.e. timed continuous conversions).

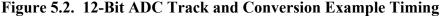
Writing a 1 to ADBUSY provides software control of the ADC whereby conversions are performed "on-demand". During conversion, the ADBUSY bit is set to 1 and restored to 0 when conversion is complete. The falling edge of ADBUSY triggers an interrupt (when enabled) and sets the ADCINT interrupt flag. Note: When conversions are performed "on-demand", the ADCINT flag, not ADBUSY, should be polled to determine when the conversion has completed. Converted data is available in the ADC data word MSB and LSB registers, ADC0H, ADC0L. Converted data can be either left or right justified in the ADC0H:ADC0L register pair (see example in Figure 5.9) depending on the programmed state of the ADLJST bit in the ADC0CN register.

The ADCTM bit in register ADC0CN controls the ADC track-and-hold mode. In its default state, the ADC input is continuously tracked, except when a conversion is in progress. Setting ADCTM to 1 allows one of four different low power track-and-hold modes to be specified by states of the ADSTM1-0 bits (also in ADC0CN):

- 1. Tracking begins with a write of 1 to ADBUSY and lasts for 3 SAR clocks;
- 2. Tracking starts with an overflow of Timer 3 and lasts for 3 SAR clocks;
- 3. Tracking is active only when the CNVSTR input is low;
- 4. Tracking starts with an overflow of Timer 2 and lasts for 3 SAR clocks.

Modes 1, 2 and 4 (above) are useful when the start of conversion is triggered with a software command or when the ADC is operated continuously. Mode 3 is used when the start of conversion is triggered by external hardware. In this case, the track-and-hold is in its low power mode at times when the CNVSTR input is high. Tracking can also be disabled (shutdown) when the entire chip is in low power standby or sleep modes.







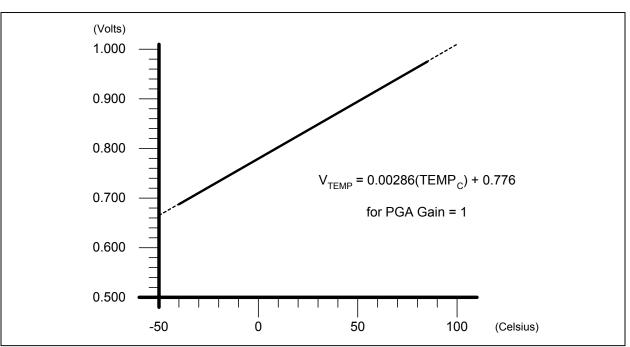


Figure 5.3. Temperature Sensor Transfer Function

Figure 5.4. AMX0CF: AMUX Configuration Register (C8051F00x)

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value			
-	-	-	-	AIN67IC	AIN45IC	AIN23IC	AIN01IC	00000000			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:			
								0xBA			
Bits7-4:	UNUSED. Rea	d = 0000b; W	/rite = don't	care							
Bit3:	AIN67IC: AIN6	6, AIN7 Input	Pair Config	uration Bit							
	0: AIN6 and AI	N7 are indep	endent single	ed-ended inp	uts						
	1: AIN6, AIN7	are (respectiv	vely) +, - difi	ferential inpu	ıt pair						
Bit2:	AIN45IC: AIN4										
	0: AIN4 and AI										
	1: AIN4, AIN5	· -	• /	-	ıt pair						
Bit1:	AIN23IC: AIN2										
	0: AIN2 and AI										
	1: AIN2, AIN3				ıt pair						
Bit0:	AIN01IC: AIN0	· 1	0								
	0: AIN0 and AI	1	U	1							
	1: AIN0, AIN1 are (respectively) +, - differential input pair										
NOTE:	The ADC Data V	Word is in 2's	s complemen	t format for o	channels con	figured as dif	terential.				



### Figure 5.5. AMX0SL: AMUX Channel Select Register (C8051F00x)

W		R/W	R/W	R/W		R/W 1XAD3	R/W AMXAD2	R/W AMXAI		R/W H XAD0 (
it7	]	Bit6	Bit5	Bit4		Bit3	Bit2	Bit1		Bit0 S
-0:	AMXAI	D3-0: AM	UX Addr	Write = dc ess Bits lected per	chart be					
		0000	0001	0010		AMXAD3 0100		0110	0111	1
A M	0000	<b>0000</b> AIN0	AIN1	AIN2	<b>0011</b> AIN3	AIN4	0101 AIN5	<b>0110</b> AIN6	<b>0111</b> AIN7	1xxx TEMP SENSOR
X 0	0001	+(AIN0) -(AIN1)		AIN2	AIN3	AIN4	AIN5	AIN6	AIN7	TEMP SENSOR
C F	0010	AIN0	AIN1	+(AIN2) -(AIN3)		AIN4	AIN5	AIN6	AIN7	TEMP SENSOR
3	0011	+(AIN0) -(AIN1)		+(AIN2) -(AIN3)		AIN4	AIN5	AIN6	AIN7	TEMP SENSOR
I T S	0100	AIN0	AIN1	AIN2	AIN3	+(AIN4) -(AIN5)		AIN6	AIN7	TEMP SENSOR
,	0101	+(AIN0) -(AIN1)		AIN2	AIN3	+(AIN4) -(AIN5)		AIN6	AIN7	TEMP SENSOR
, )	0110	AIN0	AIN1	+(AIN2) -(AIN3)		+(AIN4) -(AIN5)		AIN6	AIN7	TEMP SENSOR
	0111	+(AIN0) -(AIN1)		+(AIN2) -(AIN3)		+(AIN4) -(AIN5)		AIN6	AIN7	TEMP SENSOR
	1000	AIN0	AIN1	AIN2	AIN3	AIN4	AIN5	+(AIN6) -(AIN7)		TEMP SENSOR
	1001	+(AIN0) -(AIN1)		AIN2	AIN3	AIN4	AIN5	+(AIN6) -(AIN7)		TEMP SENSOR
	1010	AIN0	AIN1	+(AIN2) -(AIN3)		AIN4	AIN5	+(AIN6) -(AIN7)		TEMP SENSOR
	1011	+(AIN0) -(AIN1)		+(AIN2) -(AIN3)		AIN4	AIN5	+(AIN6) -(AIN7)		TEMP SENSOR
	1100	AIN0	AIN1	AIN2	AIN3	+(AIN4) -(AIN5)	<u> </u>	+(AIN6) -(AIN7)		TEMP SENSOR
	1101	+(AIN0) -(AIN1)		AIN2	AIN3	+(AIN4) -(AIN5)	<u> </u>	+(AIN6) -(AIN7)		TEMP SENSOR
	1110	AIN0	AIN1	+(AIN2) -(AIN3)		+(AIN4) -(AIN5)		+(AIN6) -(AIN7)		TEMP SENSOR
		+(AIN0)		+(AIN2)		+(AIN4)		+(AIN6)		TEMP



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value			
ADCSC2	ADCSC1	ADCSC0	-	-	AMPGN2	AMPGN1	AMPGN0	01100000			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:			
								0xBC			
0xBC Bits7-5: ADCSC2-0: ADC SAR Conversion Clock Period Bits 000: SAR Conversion Clock = 1 System Clock 001: SAR Conversion Clock = 2 System Clocks 010: SAR Conversion Clock = 4 System Clocks 011: SAR Conversion Clock = 8 System Clocks 1xx: SAR Conversion Clock = 16 Systems Clocks (Note: the SAR Conversion Clock should be ≤ 2MHz) Bits4-3: UNUSED. Read = 00b; Write = don't care Bits2-0: AMPGN2-0: ADC Internal Amplifier Gain 000: Gain = 1 001: Gain = 2 010: Gain = 4 011: Gain = 8 10x: Gain = 16											
	$\operatorname{Gain} = 0.5$										

### Figure 5.6. ADC0CF: ADC Configuration Register (C8051F00x)



Figure 5.7. ADCUCN. ADC COntrol Register (Coustroux)													
R/W		R/W	R/W	R/W	R/W	R/W	R/W	Reset Value					
ADCE	EN ADCTM	ADCINT	ADBUSY	ADSTM1	ADSTM0	ADWINT	ADLJST	00000000					
Bit7	Bit6	Bit5	Bit2	Bit1	Bit0	SFR Address:							
	(bit addressable) $0xE8$												
Bit7:	Bit7: ADCEN: ADC Enable Bit												
	0: ADC Disabled. ADC is in low power shutdown.												
	1: ADC Enabled. ADC is active and ready for data conversions.												
Bit6:	•												
	0: When the ADC is enabled, tracking is always done unless a conversion is in process												
	1: Tracking De						P						
	ADST												
			with the writ	te of 1 to AD	BUSY and la	asts for 3 SAI	R clocks						
						for 3 SAR clo							
				/STR input is									
						for 3 SAR clo	ocks						
Bit5:	ADCINT: ADC	Conversion	Complete In	terrupt Flag									
	(Must be cleare	d by software	e)										
	0: ADC has no	t completed a	data conver	sion since the	e last time thi	is flag was clo	eared						
	1: ADC has con												
Bit4:	ADBUSY: AD	C Busy Bit											
	Read												
	0: ADC Conve	-				since a reset.	The falling						
				upt when ena	bled.								
	1: ADC Busy c	onverting da	ta										
	Write												
	0: No effect	a		0.01									
Diat	1: Starts ADC												
Bits3-2	: ADSTM1-0: Al												
	00: ADC conve												
	01: ADC conve												
	10: ADC conve												
Bit1:	11: ADC conve ADWINT: ADC												
DILI.	(Must be cleare		1	upt riag									
	0: ADC Windo			h has not occ	urred								
	1: ADC Windo				unu								
Bit0:	ADLJST: ADC												
Dit0.		•		right instified									
	<ul> <li>0: Data in ADC0H:ADC0L Registers is right justified</li> <li>1: Data in ADC0H:ADC0L Registers is left justified</li> </ul>												
			ice Biotorio 10	Justinou									

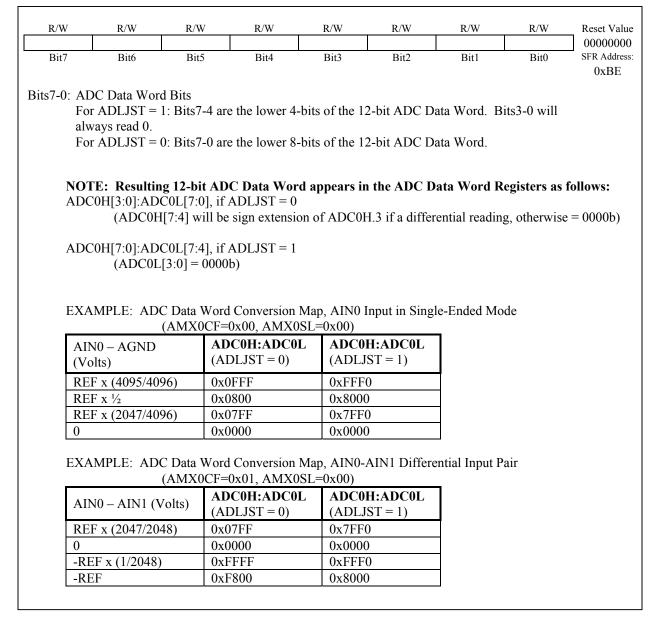
### Figure 5.7. ADC0CN: ADC Control Register (C8051F00x)



	Figure 5.0	b. ADCU	I. ADC D	ala wolu	mod Keg	<u>isici (Cou.</u>	<b>JII UUA</b>			
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value		
								0000000		
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address 0xBF		
Bits7-0: A	DC Data Word	l Bits								
For ADLJST = 1: Upper 8-bits of the 12-bit ADC Data Word.										
Fo	or $ADLJST = 0$	): Bits7-4 ar	e the sign ext	ension of Bi	3. Bits 3-0 a	are the upper	4-bits of the	2		
12	2-bit ADC Dat	a Word.	C			11				

#### Figure 5.8. ADC0H: ADC Data Word MSB Register (C8051F00x)



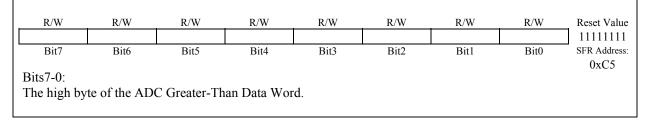




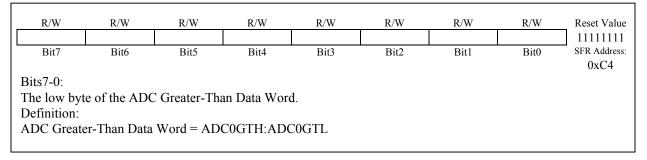
### 5.3. ADC Programmable Window Detector

The ADC programmable window detector is very useful in many applications. It continuously compares the ADC output to user-programmed limits and notifies the system when an out-of-band condition is detected. This is especially effective in an interrupt-driven system, saving code space and CPU bandwidth while delivering faster system response times. The window detector interrupt flag (ADWINT in ADC0CN) can also be used in polled mode. The high and low bytes of the reference words are loaded into the ADC Greater-Than and ADC Less-Than registers (ADC0GTH, ADC0GTL, ADC0LTH, and ADC0LTL). Figure 5.14 and Figure 5.15 show example comparisons for reference. Notice that the window detector flag can be asserted when the measured data is inside or outside the user-programmed limits, depending on the programming of the ADC0GTX and ADC0LTX registers.

### Figure 5.10. ADC0GTH: ADC Greater-Than Data High Byte Register (C8051F00x)



### Figure 5.11. ADC0GTL: ADC Greater-Than Data Low Byte Register (C8051F00x)



#### Figure 5.12. ADC0LTH: ADC Less-Than Data High Byte Register (C8051F00x)

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value	
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xC7	
Bits7-0: The high byte of the ADC Less-Than Data Word.									

#### Figure 5.13. ADC0LTL: ADC Less-Than Data Low Byte Register (C8051F00x)

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value			
								00000000			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:			
								0xC6			
Bits7-0: These bits are the low byte of the ADC Less-Than Data Word. Definition:											
ADC Less-Than Data Word = ADC0LTH:ADC0LTL											



### Figure 5.14. 12-Bit ADC Window Interrupt Examples, Right Justified Data

Input Voltage (AD0 - AGND)	ADC Data Word		Input Voltage (AD0 - AGND)	ADC Data Word	
REF x (4095/4096)	0x0FFF		REF x (4095/4096)	0x0FFF	
		ADWINT not affected			ADWINT=1
	0x0201			0x0201	
REF x (512/4096)	0x0200	ADC0LTH:ADC0LTL	REF x (512/4096)	0x0200	ADC0GTH:ADC0GTL
	0x01FF 0x0101	ADWINT=1		0x01FF 0x0101	ADWINT not affected
REF x (256/4096)	0x0101	ADC0GTH:ADC0GTL	REF x (256/4096)	0x0101	ADC0LTH:ADC0LTL
	0x00FF	ADWINT not affected		0x00FF	ADWINT=1
0	0x0000		. 0	0x0000	
MX0SL = 0x00, A DC0LTH:ADC0LT DC0GTH:ADC0G	TL = 0x0200, $TL = 0x0100$	, I.	AMX0SL = 0x00, AN ADC0LTH:ADC0LT ADC0GTH:ADC0GT	L = 0x0100, L = 0x0200.	
	TL = 0x0200, $TL = 0x0100$ $TL = 0x0100$ $TL = 0x0100$ $TL = 0x0100$ $TL = 0x0$ $TL = 0x0$ $TL = 0x0$ $TL = 0x0$	) l cause an ADC Window l) if the resulting ADC	ADC0LTH:ADC0LT ADC0GTH:ADC0GT An ADC End of Con C Compare Interrupt (, Data Word is < 0x010	TL = 0x0100, TL = 0x0200, version will ADWINT=1 00 or > 0x020 ADC Data	cause an ADC Windo ) if the resulting AD
MX0SL = 0x00, A DC0LTH:ADC0L DC0GTH:ADC0G n ADC End of Co ompare Interrupt ata Word is < 0x02	TL = 0x0200, $TL = 0x0100$ $CONVERSION WII$ $(ADWINT=200 and > 0x0$ $ADC Data$ $Word$	) l cause an ADC Window l) if the resulting ADC	ADC0LTH:ADC0LT ADC0GTH:ADC0GT An ADC End of Con C Compare Interrupt (A Data Word is < 0x010 Input Voltage (AD0 - AD1)	TL = 0x0100, TL = 0x0200, version will ADWINT=1 00 or > 0x020 ADC Data Word	cause an ADC Windo ) if the resulting AD
MX0SL = 0x00, A DC0LTH:ADC0LT DC0GTH:ADC0G n ADC End of Co ompare Interrupt	TL = 0x0200, $TL = 0x0100$ $TL = 0x0100$ $TL = 0x0100$ $TL = 0x0100$ $TL = 0x0$ $TL = 0x0$ $TL = 0x0$ $TL = 0x0$	) l cause an ADC Window l) if the resulting ADC	ADC0LTH:ADC0LT ADC0GTH:ADC0GT An ADC End of Con C Compare Interrupt (, Data Word is < 0x010	TL = 0x0100, TL = 0x0200, version will ADWINT=1 00 or > 0x020 ADC Data	cause an ADC Windo ) if the resulting AD
MX0SL = 0x00, A DC0LTH:ADC0L DC0GTH:ADC0G n ADC End of Co ompare Interrupt ata Word is < 0x02	TL = 0x0200, TL = 0x0100 onversion wil (ADWINT= 200 and > 0x0 ADC Data Word 0x07FF	ADWINT	ADC0LTH:ADC0LT ADC0GTH:ADC0GT An ADC End of Con C Compare Interrupt (A Data Word is < 0x010 Input Voltage (AD0 - AD1)	TL = 0x0100, TL = 0x0200. version will ADWINT=1 00 or > 0x020 ADC Data Word 0x07FF	cause an ADC Windo ) if the resulting AD 00.
MX0SL = 0x00, A DC0LTH:ADC0L DC0GTH:ADC0G n ADC End of Cc ompare Interrupt ata Word is < 0x02 REF x (2047/2048)	TL = 0x0200, TL = 0x0100 onversion wil (ADWINT= 200 and > 0x0 ADC Data Word 0x07FF 0x0101	ADWINT not affected	ADC0LTH:ADC0LT ADC0GTH:ADC0GT ADC0GTH:ADC0GT Compare Interrupt ( Data Word is < 0x010 Input Voltage (AD0 - AD1) REF x (2047/2048)	TL = 0x0100, TL = 0x0200, version will ADWINT=1 00 or > 0x020 ADC Data Word 0x07FF 0x0101	cause an ADC Windo ) if the resulting AD 00. ADWINT=1
MX0SL = 0x00, A DC0LTH:ADC0L DC0GTH:ADC0G n ADC End of Cc ompare Interrupt ata Word is < 0x02 REF x (2047/2048) REF x (256/2048)	TL = 0x0200, TL = 0x0100 onversion wil (ADWINT= 200 and > 0x0 ADC Data Word 0x07FF 0x0101 0x0100	ADWINT not affected	ADC0LTH:ADC0LT ADC0GTH:ADC0GT An ADC End of Con Compare Interrupt ( Data Word is < 0x010 Input Voltage (AD0 - AD1) REF x (2047/2048)	TL = 0x0100, TL = 0x0200. version will ADWINT=1 00 or > 0x020 ADC Data Word 0x07FF 0x0101 0x0100	cause an ADC Windo ) if the resulting AD 00.
MX0SL = 0x00, A DC0LTH:ADC0L DC0GTH:ADC0G n ADC End of Cc ompare Interrupt ata Word is < 0x02 REF x (2047/2048) REF x (256/2048) REF x (-1/2048)	TL = 0x0200, TL = 0x0100 onversion wil (ADWINT= 200 and > 0x0 ADC Data Word 0x07FF 0x0101 0x0100 0x00FF	ADWINT ADWINT ADCOLTH:ADCOLTL ADWINT=1 ADCOGTH:ADCOGTL	ADC0LTH:ADC0LT ADC0GTH:ADC0GT An ADC End of Con Compare Interrupt ( Data Word is < 0x010 Input Voltage (AD0 - AD1) REF x (2047/2048) REF x (256/2048) REF x (-1/2048)	TL = 0x0100, TL = 0x0200. version will ADWINT=1 00 or > 0x020 ADC Data Word 0x07FF 0x0101 0x0100 0x00FF	ADWINT=1 ADCOGTH:ADCOGTL ADWINT ADCOLTH:ADCOLTL
MX0SL = 0x00, A DC0LTH:ADC0L DC0GTH:ADC0G n ADC End of Cc ompare Interrupt ata Word is < 0x02 REF x (2047/2048) REF x (256/2048)	TL = 0x0200, TL = 0x0100 onversion wil (ADWINT= 200 and > 0x0 ADC Data Word 0x07FF 0x0101 0x0100 0x00FF 0x0000	ADWINT ADWINT ADCOLTH:ADCOLTL ADWINT=1	ADC0LTH:ADC0LT ADC0GTH:ADC0GT An ADC End of Con Compare Interrupt ( Data Word is < 0x010 Input Voltage (AD0 - AD1) REF x (2047/2048)	L = 0x0100, TL = 0x0200. version will ADWINT=1 00 or > 0x020 ADC Data Word 0x07FF 0x0101 0x0101 0x00FF 0x0000	ADWINT=1

AMX0SL = 0x00, AMX0CF = 0x01, ADLJST = 0, ADC0LTH:ADC0LTL = 0x0100, ADC0GTH:ADC0GTL = 0xFFFF.

An ADC End of Conversion will cause an ADC Window Compare Interrupt (ADWINT=1) if the resulting ADC Data Word is < 0x0100 and > 0xFFFF. (Two's Complement math, 0xFFFF = -1.)

#### Given:

AMX0SL = 0x00, AMX0CF = 0x01, ADLJST = 0, ADC0LTH:ADC0LTH = 0xFFFF, ADC0GTH:ADC0GTL = 0x0100.

An ADC End of Conversion will cause an ADC Window Compare Interrupt (ADWINT=1) if the resulting ADC Data Word is < 0xFFFF or > 0x0100. (Two's Complement math, 0xFFFF = -1.)



#### Figure 5.15. 12-Bit ADC Window Interrupt Examples, Left Justified Data

Input Voltage (AD0 - AGND)	ADC Data Word	_
REF x (4095/4096)	0xFFF0	
		ADWINT not affected
	0x2010	
REF x (512/4096)	0x2000	ADC0LTH:ADC0LTL
	0x1FF0 0x1010	ADWINT=1
REF x (256/4096)	0x1000	ADC0GTH:ADC0GTL
	0x0FF0	
		ADWINT not affected
0	0x0000	]

#### Given:

AMX0SL = 0x00, AMX0CF = 0x00, ADLJST = 1, ADC0LTH:ADC0LTL = 0x2000, ADC0GTH:ADC0GTL = 0x1000.

An ADC End of Conversion will cause an ADC Window Compare Interrupt (ADWINT=1) if the resulting ADC Data Word is < 0x2000 and > 0x1000.

Compare Interrupt (ADWINT=1) if the resulting ADC Data Word is < 0x1000 and > 0xFFF0. (Two's

Input Voltage (AD0 - AGND)	ADC Data Word	
REF x (4095/4096)	0xFFF0	ADWINT=1
	0x2010	
REF x (512/4096)	0x2000	ADC0GTH:ADC0GTL
	0x1FF0 0x1010	ADWINT not affected
REF x (256/4096)	0x1000	ADC0LTH:ADC0LTL
	0x0FF0	ADWINT=1
0	0x0000	]]

#### Given:

AMX0SL = 0x00, AMX0CF = 0x00, ADLJST = 1,ADC0LTH:ADC0LTL = 0x1000,ADC0GTH:ADC0GTL = 0x2000.

An ADC End of Conversion will cause an ADC Window Compare Interrupt (ADWINT=1) if the resulting ADC Data Word is < 0x1000 or > 0x2000.

Input Voltage (AD0 - AD1)	ADC Data Word		Input Voltage (AD0 - AD1)	ADC Data Word	
REF x (2047/2048)	0x7FF0		REF x (2047/2048)	0x7FF0	
		ADWINT not affected			ADWINT=1
	0x1010			0x1010	
REF x (256/2048)	0x1000	ADC0LTH:ADC0LTL	REF x (256/2048)	0x1000	ADC0GTH:ADC0GTL
	0x0FF0			0x0FF0	ADWINT
	0x0000	ADWINT=1		0x0000	not affected
REF x (-1/2048)	0xFFF0	ADC0GTH:ADC0GTL	REF x (-1/2048)	0xFFF0	ADC0LTH:ADC0LTL
	0xFFE0			0xFFE0	
		ADWINT not affected			ADWINT=1
-REF	0x8000		-REF	0x8000	
diven:			Given:		
MX0SL = 0x00, A DC0LTH:ADC0I DC0GTH:ADC00	LTL = 0x1000		AMX0SL = 0x00, AM ADC0LTH:ADC0LTH ADC0GTH:ADC0GTL	= 0xFFF0,	, ADLJST = 1,
An ADC End of C	onversion will	ll cause an ADC Window	An ADC End of Conv	version will ca	ause an ADC Windo

An ADC End of Conversion will cause an ADC Window Compare Interrupt (ADWINT=1) if the resulting ADC Data Word is < 0xFFF0 or > 0x1000. (Two's Complement math.)



Complement math.)

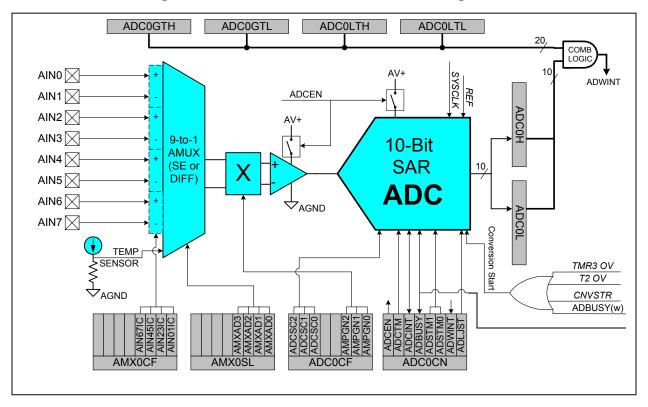
Table 5.1.	<b>12-Bit ADC Electrical Characteristics</b>
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PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
DC ACCURACY					
Resolution			12		bits
Integral Nonlinearity				± 1	LSB
Differential Nonlinearity	Guaranteed Monotonic			± 1	LSB
Offset Error			-3 ± 1		LSB
Full Scale Error	Differential mode		-7 ± 3		LSB
Offset Temperature			± 0.25		ppm/°C
Coefficient					
DYNAMIC PERFORMAN	CE (10kHz sine-wave input, 0 to –1dB of f	full scale, 1	00ksps)		
Signal-to-Noise Plus		66	69		dB
Distortion					
Total Harmonic Distortion	Up to the 5 <sup>th</sup> harmonic		-75		dB
Spurious-Free Dynamic			80		dB
Range					
CONVERSION RATE	1	-	I		
Conversion Time in SAR		16			clocks
Clocks					
SAR Clock Frequency	C8051F000, 'F001, 'F002			2.0	MHz
	C8051F005, 'F006, 'F007			2.5	MHz
Track/Hold Acquisition		1.5			μs
Time The transformed by the second				100	1
Throughput Rate				100	ksps
ANALOG INPUTS		0		VDEE	17
Voltage Conversion Range	Single-ended Mode (AINn – AGND)	0		VREF	V
Input Voltage	Differential Mode  (AINn+) – (AINm-)  Any AINn pin	AGND		- 1LSB AV+	V
Input Voltage		AGND	10	Av+	pF
TEMPERATURE SENSOR			10		рг
Linearity			10.20		°C
Absolute Accuracy			$\pm 0.20$		<u>°C</u>
Gain	PGA Gain = 1		$\pm 3$ 2.86		-
	PGA Gain = 1 $PGA Gain = 1$				mV/°C
$\frac{\text{Gain Error} (\pm 1\sigma)}{\text{Offset}}$			$\pm 33.5$		$\mu V/^{\circ}C$
Offset	PGA Gain = 1, Temp = $0^{\circ}$ C		776		mV
Offset Error $(\pm 1\sigma)$	PGA Gain = 1, Temp = $0^{\circ}$ C		$\pm 8.51$		mV
POWER SPECIFICATION		1	450	000	
Power Supply Current (AV+ supplied to ADC)	Operating Mode, 100ksps		450	900	μA
Power Supply Rejection			$\pm 0.3$		mV/V



### 6. ADC (10-Bit, C8051F010/1/2/5/6/7 Only)

The ADC subsystem for the C8051F010/1/2/5/6/7 consists of a 9-channel, configurable analog multiplexer (AMUX), a programmable gain amplifier (PGA), and a 100ksps, 10-bit successive-approximation-register ADC with integrated track-and-hold and programmable window detector (see block diagram in Figure 6.1). The AMUX, PGA, Data Conversion Modes, and Window Detector are all configurable under software control via the Special Function Register's shown in Figure 6.1. The ADC subsystem (ADC, track-and-hold and PGA) is enabled only when the ADCEN bit in the ADC Control register (ADC0CN, Figure 6.7) is set to 1. The ADC subsystem is in low power shutdown when this bit is 0. The Bias Enable bit (BIASE) in the REF0CN register (see Figure 9.2) must be set to 1 in order to supply bias to the ADC.





#### 6.1. Analog Multiplexer and PGA

Eight of the AMUX channels are available for external measurements while the ninth channel is internally connected to an on-board temperature sensor (temperature transfer function is shown in Figure 6.3). Note that the PGA gain is applied to the temperature sensor reading. AMUX input pairs can be programmed to operate in either the differential or single-ended mode. This allows the user to select the best measurement technique for each input channel, and even accommodates mode changes "on-the-fly". The AMUX defaults to all single-ended inputs upon reset. There are two registers associated with the AMUX: the Channel Selection register AMX0SL (Figure 6.5), and the Configuration register AMX0CF (Figure 6.4). The table in Figure 6.5 shows AMUX functionality by channel for each possible configuration. The PGA amplifies the AMUX output signal by an amount determined by the AMPGN2-0 bits in the ADC Configuration register, ADC0CF (Figure 6.6). The PGA can be software-programmed for gains of 0.5, 1, 2, 4, 8 or 16. It defaults to unity gain on reset.



#### 6.2. ADC Modes of Operation

The ADC uses VREF to determine its full-scale voltage, thus the reference must be properly configured before performing a conversion (see Section 9). The ADC has a maximum conversion speed of 100ksps. The ADC conversion clock is derived from the system clock. Conversion clock speed can be reduced by a factor of 2, 4, 8 or 16 via the ADCSC bits in the ADC0CF Register. This is useful to adjust conversion speed to accommodate different system clock speeds.

A conversion can be initiated in one of four ways, depending on the programmed states of the ADC Start of Conversion Mode bits (ADSTM1, ADSTM0) in ADC0CN. Conversions may be initiated by:

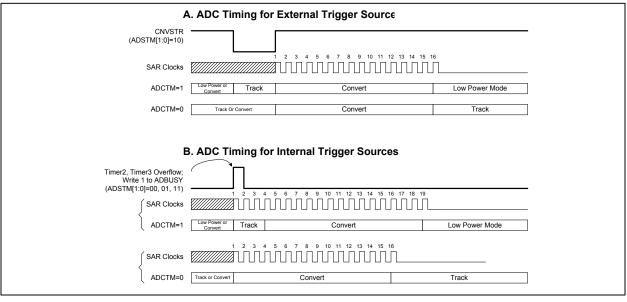
- 1. Writing a 1 to the ADBUSY bit of ADC0CN;
- 2. A Timer 3 overflow (i.e. timed continuous conversions);
- 3. A rising edge detected on the external ADC convert start signal, CNVSTR;
- 4. A Timer 2 overflow (i.e. timed continuous conversions).

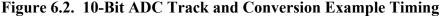
Writing a 1 to ADBUSY provides software control of the ADC whereby conversions are performed "on-demand". During conversion, the ADBUSY bit is set to 1 and restored to 0 when conversion is complete. The falling edge of ADBUSY triggers an interrupt (when enabled) and sets the ADCINT interrupt flag. Note: When conversions are performed "on-demand", the ADCINT flag, not ADBUSY, should be polled to determine when the conversion has completed. Converted data is available in the ADC data word MSB and LSB registers, ADC0H, ADC0L. Converted data can be either left or right justified in the ADC0H:ADC0L register pair (see example in Figure 6.9) depending on the programmed state of the ADLJST bit in the ADC0CN register.

The ADCTM bit in register ADC0CN controls the ADC track-and-hold mode. In its default state, the ADC input is continuously tracked, except when a conversion is in progress. Setting ADCTM to 1 allows one of four different low power track-and-hold modes to be specified by states of the ADSTM1-0 bits (also in ADC0CN):

- 1. Tracking begins with a write of 1 to ADBUSY and lasts for 3 SAR clocks;
- 2. Tracking starts with an overflow of Timer 3 and lasts for 3 SAR clocks;
- 3. Tracking is active only when the CNVSTR input is low;
- 4. Tracking starts with an overflow of Timer 2 and lasts for 3 SAR clocks.

Modes 1, 2 and 4 (above) are useful when the start of conversion is triggered with a software command or when the ADC is operated continuously. Mode 3 is used when the start of conversion is triggered by external hardware. In this case, the track-and-hold is in its low power mode at times when the CNVSTR input is high. Tracking can also be disabled (shutdown) when the entire chip is in low power standby or sleep modes.









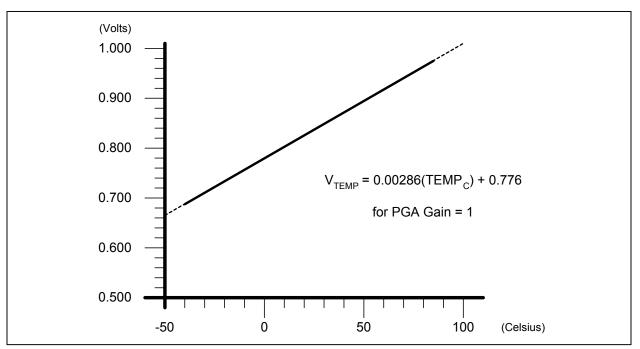


Figure 6.4. AMX0CF: AMUX Configuration Register (C8051F01x)

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-	-	-	-	AIN67IC	AIN45IC	AIN23IC	AIN01IC	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address
								0xBA
Bits7-4:	UNUSED. Rea	d = 0000b; W	rite = don't	care				
Bit3:	AIN67IC: AIN6	, AIN7 Input	Pair Config	uration Bit				
	0: AIN6 and AI	N7 are indep	endent singl	ed-ended inp	uts			
	1: AIN6, AIN7				ıt pair			
Bit2:	AIN45IC: AIN4							
	0: AIN4 and AI							
	1: AIN4, AIN5	are (respectiv	vely) +, - dif	ferential inpu	ıt pair			
Bit1:	AIN23IC: AIN2							
	0: AIN2 and AI							
	1: AIN2, AIN3	· · ·		1	ıt pair			
Bit0:	AIN01IC: AIN0	· 1						
	0: AIN0 and AI	1	U	1				
	1: AIN0, AIN1	are (respectiv	vely) +, - dif	ferential inpu	ıt pair			
NOTE						~ 1 ···	20 . 1	
NOTE:	The ADC Data V	Word is in 2's	s complemen	t format for o	channels con	figured as dif	terential.	



### Figure 6.5. AMX0SL: AMUX Channel Select Register (C8051F01x)

W		R/W	R/W	R/W	A	R/W MXAD3	R/W AMXAD2	R/W AMXAI	1	R/W I IXAD0 (
7	I	Bit6	Bit5	Bit4		Bit3	Bit2	Bit1	]	Bit0 S
0:	AMXAI	D3-0: AM	UX Addr	Write = do ess Bits lected per	chart be	elow	2.0			
	l	0000	0001	0010		AMXAD		0110	0111	1
\	0000	<b>0000</b> AIN0	<b>0001</b> AIN1	<b>0010</b> AIN2	<b>0011</b> AIN3	<b>0100</b> AIN4	<b>0101</b> AIN5	<b>0110</b> AIN6	<b>0111</b> AIN7	1xxx TEMP
1	0001	+(AIN0) -(AIN1)		AIN2	AIN3	AIN4	AIN5	AIN6	AIN7	SENSOR TEMP SENSOR
	0010	AIN0	AIN1	+(AIN2) -(AIN3)		AIN4	AIN5	AIN6	AIN7	TEMP SENSOR
	0011	+(AIN0) -(AIN1)		+(AIN2) -(AIN3)		AIN4	AIN5	AIN6	AIN7	TEMP SENSOR
	0100	AIN0	AIN1	AIN2	AIN3	+(AIN4) -(AIN5)		AIN6	AIN7	TEMP SENSOR
	0101	+(AIN0) -(AIN1)		AIN2	AIN3	+(AIN4) -(AIN5)		AIN6	AIN7	TEMP SENSOR
	0110	AIN0	AIN1	+(AIN2) -(AIN3)		+(AIN4) -(AIN5)		AIN6	AIN7	TEMP SENSOR
	0111	+(AIN0) -(AIN1)		+(AIN2) -(AIN3)		+(AIN4) -(AIN5)		AIN6	AIN7	TEMP SENSOR
	1000	AIN0	AIN1	AIN2	AIN3	AIN4	AIN5	+(AIN6) -(AIN7)		TEMP SENSOR
	1001	+(AIN0) -(AIN1)		AIN2	AIN3	AIN4	AIN5	+(AIN6) -(AIN7)		TEMP SENSOR
	1010	AIN0	AIN1	+(AIN2) -(AIN3)		AIN4	AIN5	+(AIN6) -(AIN7)		TEMP SENSOR
	1011	+(AIN0) -(AIN1)		+(AIN2) -(AIN3)		AIN4	AIN5	+(AIN6) -(AIN7)		TEMP SENSOR
-	1100	AIN0	AIN1	AIN2	AIN3	+(AIN4) -(AIN5)		+(AIN6) -(AIN7)		TEMP SENSOR
	1101	+(AIN0) -(AIN1)		AIN2	AIN3	+(AIN4) -(AIN5)		+(AIN6) -(AIN7)		TEMP SENSOR
	1110	AIN0	AIN1	+(AIN2) -(AIN3)		+(AIN4) -(AIN5)		+(AIN6) -(AIN7)		TEMP SENSOR
	1111	+(AIN0)		+(AIN2)		+(AIN4)		+(AIN6) -(AIN7)		TEMP SENSOR



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
ADCSC2	ADCSC1	ADCSC0	-	-	AMPGN2	AMPGN1	AMPGN0	01100000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
								0xBC
Bits7-5. AF		OC SAR Conv	version Clock	Period Rite				
	0.000 000000	version Clock						
			•					
		version Clock						
		version Clock	•					
		version Clock						
1xx	c: SAR Conv	ersion Clock	= 16 System	ns Clocks				
(No	ote: Convers	ion clock sho	ould be $\leq 2M$	IHz.)				
Bits4-3: UN	USED. Rea	d = 00b; Wri	te = don't car	re				
Bits2-0: AN	4PGN2-0: AI	DC Internal A	Amplifier Gai	in				
	): Gain = 1		1					
001	: Gain = 2							
010	): $Gain = 4$							
011	I: Gain = $8$							
102	c: Gain = 16							
112	c: Gain = $0.5$	5						

### Figure 6.6. ADC0CF: ADC Configuration Register (C8051F01x)



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
ADCEN		ADCINT	ADBUSY	ADSTM1	ADSTM0	ADWINT	ADLJST	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address
							(bit addressable)	0xE8
Bit7:	ADCEN: ADC	Enable Bit						
	0: ADC Disabl	led. ADC is i	n low power	shutdown.				
	1: ADC Enable	ed. ADC is a	ctive and read	dy for data co	onversions.			
Bit6:	ADCTM: ADC	Track Mode	Bit					
	0: When the A	DC is enable	d, tracking is	always done	unless a con-	version is in	process	
	1: Tracking De	fined by AD	STM1-0 bits					
	ADST	M1-0:						
	00: Ti	racking starts	with the writ	e of 1 to AD	BUSY and la	sts for 3 SA	R clocks	
		racking starte				or 3 SAR clo	ocks	
		DC tracks on						
		racking starte			er 2 and last f	or 3 SAR clo	ocks	
Bit5:	ADCINT: ADC			terrupt Flag				
	(Must be cleare							
	0: ADC has no				e last time thi	s flag was cl	eared	
	1: ADC has co		a conversion					
Bit4:	ADBUSY: AD	C Busy Bit						
	Read							
	0: ADC Conve					since a reset.	The falling	
		BUSY genera		ipt when ena	bled.			
	1: ADC Busy of	converting da	ta					
	Write							
	0: No effect	<b>C</b>		- 001				
D:4-2 2.	1: Starts ADC							
Bits3-2:	ADSTM1-0: A							
	00: ADC conv							
	01: ADC conv							
	10: ADC conv 11: ADC conv							
Bit1:								
DILI.	ADWINT: AD (Must be cleare		1	upt riag				
	0: ADC Windo			h has not oco	urrad			
	1: ADC Windo				uiteu			
Bit0:	ADLJST: ADC							
<b>D</b> 110.	0: Data in ADC			ight instified				
	1: Data in ADO							
	1. Data III ADO	LUII.ADCUL	Registers is i	ustilleu				

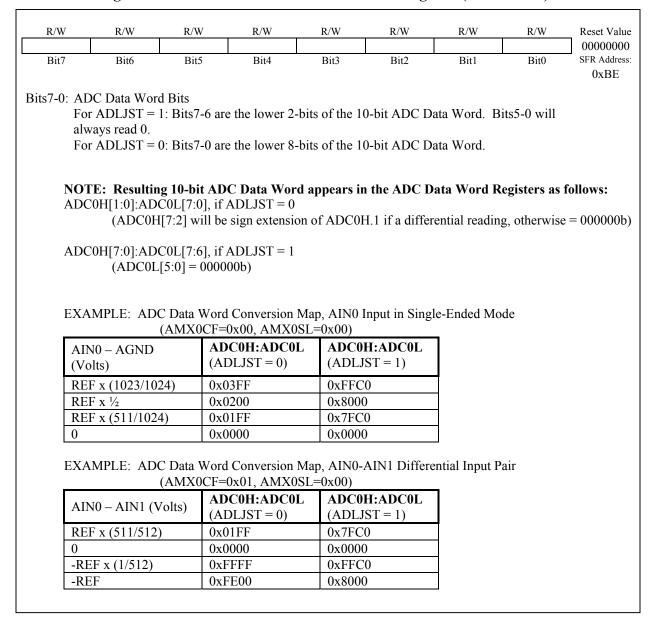
### Figure 6.7. ADC0CN: ADC Control Register (C8051F01x)



Figure 6.8. ADC0H: ADC Data Word MSB Register (C805	(1F01x)
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R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value 00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xBF
Fc Fc	DC Data Word or ADLJST = or ADLJST = 0 -bit ADC Dat	1: Upper 8-b 0: Bits7-2 are				are the upper	2-bits of the	•

#### Figure 6.9. ADC0L: ADC Data Word LSB Register (C8051F01x)

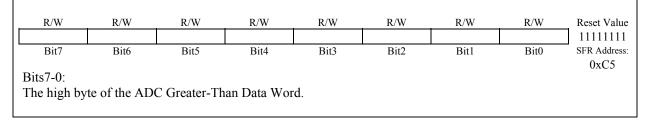




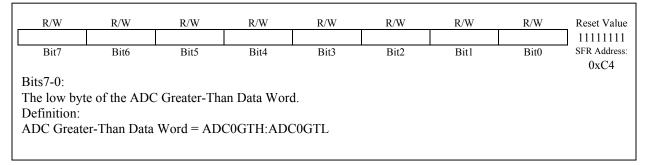
### 6.3. ADC Programmable Window Detector

The ADC programmable window detector is very useful in many applications. It continuously compares the ADC output to user-programmed limits and notifies the system when an out-of-band condition is detected. This is especially effective in an interrupt-driven system, saving code space and CPU bandwidth while delivering faster system response times. The window detector interrupt flag (ADWINT in ADC0CN) can also be used in polled mode. The high and low bytes of the reference words are loaded into the ADC Greater-Than and ADC Less-Than registers (ADC0GTH, ADC0GTL, ADC0LTH, and ADC0LTL). Figure 6.14 and Figure 6.15 show example comparisons for reference. Notice that the window detector flag can be asserted when the measured data is inside or outside the user-programmed limits, depending on the programming of the ADC0GTX and ADC0LTX registers.

### Figure 6.10. ADC0GTH: ADC Greater-Than Data High Byte Register (C8051F01x)



### Figure 6.11. ADC0GTL: ADC Greater-Than Data Low Byte Register (C8051F01x)



#### Figure 6.12. ADC0LTH: ADC Less-Than Data High Byte Register (C8051F01x)

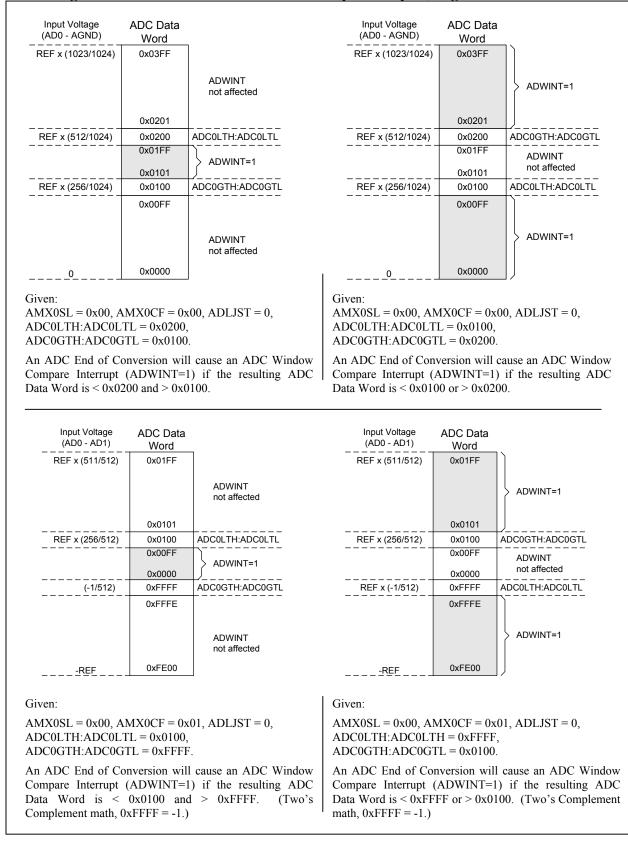
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value 00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xC7
Bits7-0: The high by	te of the AD	C Less-Than	Data Word.					

#### Figure 6.13. ADC0LTL: ADC Less-Than Data Low Byte Register (C8051F01x)

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value 00000000			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xC6			
Bits7-0: These bits are the low byte of the ADC Less-Than Data Word. Definition:											
	ADC Less-Than Data Word = ADC0LTH:ADC0LTL										

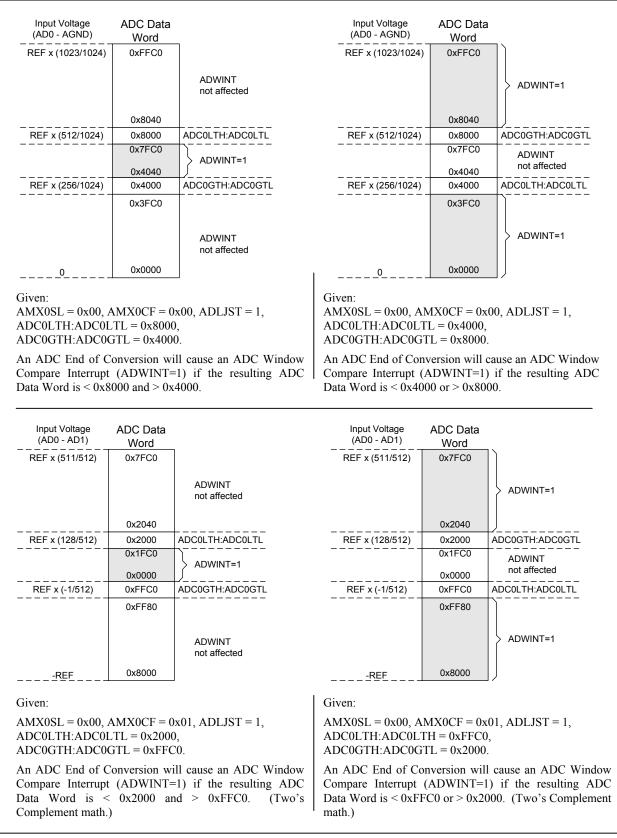


#### Figure 6.14. 10-Bit ADC Window Interrupt Examples, Right Justified Data





### Figure 6.15. 10-Bit ADC Window Interrupt Examples, Left Justified Data





VDD = 3.0V, AV+ = 3.0V, V	REF = 2.40V (REFBE=0), PGA Gain = 1, -	40°C to +8	5°C unles	s otherwise	e specified.
PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
DC ACCURACY					
Resolution			10		bits
Integral Nonlinearity			$\pm \frac{1}{2}$	± 1	LSB
Differential Nonlinearity	Guaranteed Monotonic		$\pm \frac{1}{2}$	± 1	LSB
Offset Error			± 0.5		LSB
Full Scale Error	Differential mode		-1.5 ±		LSB
			0.5		
Offset Temperature			± 0.25		ppm/°C
Coefficient					
DYNAMIC PERFORMAN	CE (10kHz sine-wave input, 0 to –1dB of f	full scale, 1	00ksps)		
Signal-to-Noise Plus		59	61		dB
Distortion					
Total Harmonic Distortion	Up to the 5 <sup>th</sup> harmonic		-70		dB
Spurious-Free Dynamic			80		dB
Range					
CONVERSION RATE		-			
Conversion Time in SAR		16			clocks
Clocks					
SAR Clock Frequency	C8051F000, 'F001, 'F002			2.0	MHz
	C8051F005, 'F006, 'F007			2.5	MHz
Track/Hold Acquisition		1.5			μs
Time					
Throughput Rate				100	ksps
ANALOG INPUTS				1	
Voltage Conversion Range	Single-ended Mode (AINn – AGND)	0		VREF	V
T	Differential Mode  (AINn+) – (AINm-)			- 1LSB	
Input Voltage	Any AINn pin	AGND	10	AV+	V
Input Capacitance			10		pF
TEMPERATURE SENSOR					
Linearity			$\pm 0.20$		°C
Absolute Accuracy			± 3		°C
Gain	PGA Gain = 1		2.86		mV/°C
Gain Error $(\pm 1\sigma)$	PGA Gain = 1		± 33.5		μV/°C
Offset	PGA Gain = 1, Temp = $0^{\circ}$ C		776		mV
Offset Error $(\pm 1\sigma)$	PGA Gain = 1, Temp = $0^{\circ}$ C		± 8.51		mV
POWER SPECIFICATION					
Power Supply Current (AV+ supplied to ADC)	Operating Mode, 100ksps		450	900	μΑ
Power Supply Rejection			± 0.3		mV/V



### 7. DACs, 12 BIT VOLTAGE MODE

The C8051F000 MCU family has two 12-bit voltage-mode Digital to Analog Converters. Each DAC has an output swing of 0V to VREF-1LSB for a corresponding input code range of 0x000 to 0xFFF. Using DAC0 as an example, the 12-bit data word is written to the low byte (DAC0L) and high byte (DAC0H) data registers. Data is latched into DAC0 after a write to the corresponding DAC0H register, **so the write sequence should be DAC0L followed by DAC0H** if the full 12-bit resolution is required. The DAC can be used in 8-bit mode by initializing DAC0L to the desired value (typically 0x00), and writing data to only DAC0H with the data shifted to the left. DAC0 Control Register (DAC0CN) provides a means to enable/disable DAC0 and to modify its input data formatting.

The DAC0 enable/disable function is controlled by the DAC0EN bit (DAC0CN.7). Writing a 1 to DAC0EN enables DAC0 while writing a 0 to DAC0EN disables DAC0. While disabled, the output of DAC0 is maintained in a high-impedance state, and the DAC0 supply current falls to  $1\mu$ A or less. Also, the Bias Enable bit (BIASE) in the REF0CN register (see Figure 9.2) must be set to 1 in order to supply bias to DAC0. The voltage reference for DAC0 must also be set properly (see Section 9).

In some instances, input data should be shifted prior to a DAC0 write operation to properly justify data within the DAC input registers. This action would typically require one or more load and shift operations, adding software overhead and slowing DAC throughput. To alleviate this problem, the data-formatting feature provides a means for the user to program the orientation of the DAC0 data word within data registers DAC0H and DAC0L. The three DAC0DF bits (DAC0CN.[2:0]) allow the user to specify one of five data word orientations as shown in the DAC0CN register definition.

DAC1 is functionally the same as DAC0 described above. The electrical specifications for both DAC0 and DAC1 are given in Table 7.1.

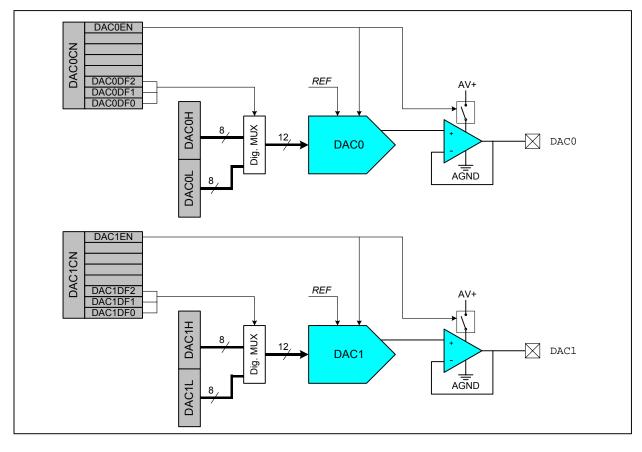


Figure 7.1. DAC Functional Block Diagram



### Figure 7.2. DAC0H: DAC0 High Byte Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value 00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xD3
Bits7-0: DA	ACO Data Wo	rd Most Sigi	nificant Byte.					

### Figure 7.3. DAC0L: DAC0 Low Byte Register

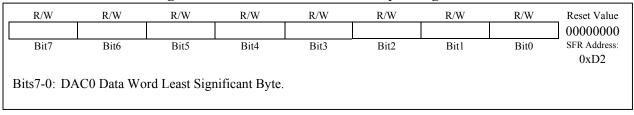


Figure 7.4. DAC0CN: DAC0 Control Register

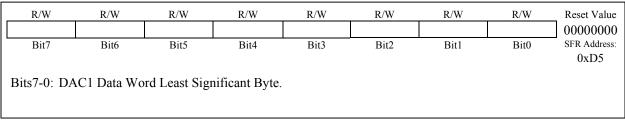
C0 Disat C0 Enab ED. Rez DF2-0: I ne most rte is in ne most	led. DAC0 C ad = 0000b; V DAC0 Data Fo significant ny DAC0L. DAC0H MSB significant 5- n DAC0L[7:1	Output pin is Dutput is pin Vrite = don't ormat Bits ybble of the D	active; DA care DAC0 Data	R/W DAC0DF2 Bit2 DAC0 is in low C0 is operation Word is in DA	al. .C0H[3:0], w DAC0L	hile the least	LSB		
CN: DAC CO Disat CO Enab ED. Rea DF2-0: I ne most rte is in	C0 Enable Bit bled. DAC0 ( led. DAC0 ( ad = 0000b; V DAC0 Data For significant ny DAC0L. DAC0H MSB significant 5- n DAC0L[7:1]	t Output pin is Dutput is pin Vrite = don't ormat Bits ybble of the D -bits of the D	Bit3 disabled; I active; DA care DAC0 Data	Bit2 DAC0 is in low C0 is operation Word is in DA	Bit1 power shutd al. .C0H[3:0], w DAC0L	Bit0 lown mode. /hile the least	SFR Address: 0xD4		
CN: DAC CO Disat CO Enab ED. Rea DF2-0: I ne most rte is in	C0 Enable Bit bled. DAC0 ( led. DAC0 ( ad = 0000b; V DAC0 Data For significant ny DAC0L. DAC0H MSB significant 5- n DAC0L[7:1]	t Output pin is Dutput is pin Vrite = don't ormat Bits ybble of the D -bits of the D	disabled; I active; DA care DAC0 Data	DAC0 is in low C0 is operation Word is in DA	power shutd al. .C0H[3:0], w DAC0L	lown mode. hile the least	0xD4 t significant		
C0 Disat C0 Enab ED. Rez DF2-0: I ne most rte is in ne most	bled. DAC0 ( led. DAC0 ( ad = 0000b; V DAC0 Data Fo significant ny DAC0L. DAC0H MSB significant 5- n DAC0L[7:1	Output pin is Dutput is pin Vrite = don't ormat Bits ybble of the D	active; DA care DAC0 Data	C0 is operation Word is in DA	al. .C0H[3:0], w DAC0L	hile the least	LSB		
C0 Enab ED. Rea DF2-0: I ne most te is in ne most	led. DAC0 C ad = 0000b; V DAC0 Data Fo significant ny DAC0L. DAC0H MSB significant 5- n DAC0L[7:1	Dutput is pin Vrite = don't ormat Bits ybble of the l	active; DA care DAC0 Data	C0 is operation Word is in DA	al. .C0H[3:0], w DAC0L	hile the least	LSB		
ED. Rea DF2-0: In the most the is in the most	ad = 0000b; V DAC0 Data Fo significant ny DAC0L. DAC0H MSB significant 5- n DAC0L[7:1	Vrite = don't ormat Bits ybble of the l	care DAC0 Data	Word is in DA	.C0H[3:0], w DAC0L		LSB		
DF2-0: I ne most te is in ne most	DAC0 Data Fo significant ny DAC0L. DAC0H MSB significant 5- DAC0L[7:1	ormat Bits ybble of the I	DAC0 Data		DAC0L		LSB		
ne most rte is in he most	significant ny DAC0L. DAC0H MSB significant 5- DAC0L[7:1	ybble of the l			DAC0L		LSB		
rte is in	DAC0L. DAC0H significant 5- DAC0L[7:1	bits of the D			DAC0L		LSB		
ne most	DAC0H MSB significant 5- n DAC0L[7:1		AC0 Data	Word is in DA					
	MSB significant 5- n DAC0L[7:1		AC0 Data	Word is in DA					
	significant 5- 1 DAC0L[7:1		AC0 Data '	Word is in DA	C0H[4:0], wł				
	n DAC0L[7:1		ACO Dala	woru is ili DAV	2011[4.0], WI	me the least s			
	<b>D</b> 1 00						"ginneant		
	DAC0H				DAC0L				
	MSB					LSB			
	significant 6- 1 DAC0L[7:2		AC0 Data	Word is in DA	C0H[5:0], wł	nile the least s	significant		
	DAC0H			DAC0L					
MSB						LSB			
			AC0 Data	Word is in DA	C0H[6:0], wł	nile the least s	significant		
bits is ir	1 DAC0L[7:3	B].							
	DAC0H				DAC0L				
SB					LSB				
		yte of the DA	C0 Data W	ord is in DAC	OH, while the	e least signifi	cant nybble		
					DAC0L				
					LSB				
5	bits is ir	bits is in DAC0L[7:3 DAC0H	bits is in DAC0L[7:3]. DAC0H B	bits is in DAC0L[7:3]. DAC0H B B B B B B B B B B B B B B B B B B B	bits is in DAC0L[7:3]. DAC0H B DAC0H ne most significant byte of the DAC0 Data Word is in DAC0 in DAC0L[7:4].	bits is in DAC0L[7:3]. DAC0H DAC0L B LSB he most significant byte of the DAC0 Data Word is in DAC0H, while the in DAC0L[7:4]. DAC0H DAC0L	DAC0H DAC0L B LSB DacoH LSB DacoH DacoD Data Word is in DAC0H, while the least signific DAC0L[7:4]. DAC0H DAC0L		



### Figure 7.5. DAC1H: DAC1 High Byte Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
								00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
								0xD6
Bits7-0: DA	AC1 Data Wo	rd Most Sigr	nificant Byte.					

### Figure 7.6. DAC1L: DAC1 Low Byte Register



#### Figure 7.7. DAC1CN: DAC1 Control Register

						8						
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value				
DAC1EN	-	-	-	-	DAC1DF2	DAC1DF1	DAC1DF0	0000000				
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xD7				
Bit7: DA	C1EN: DAG	C1 Enable Bit	-									
	DAC1 Disat	oled. DAC1	Output pin is	disabled; D	AC1 is in low	power shut	lown mode.					
					1 is operation							
		d = 0000b; V			1							
Bits2-0: DAC1DF2-0: DAC1 Data Format Bits												
000: The most significant nybble of the DAC1 Data Word is in DAC1H[3:0], while the least												
		t byte is in D										
		AC1H			DAG	CIL						
		MSB					LSB					
		t 7-bits is in I AC1H			DAG	C1L	LSB					
01		• •	bits of the D	AC1 Data W	Vord is in DA	C1H[5:0] w						
01		t 6-bits is in I		liei Duu v		0111[0.0], #	line the least					
T	Ŭ	AC1H	- [].	DAC1L								
	MSB					LSB						
011: The most significant 7-bits of the DAC1 Data Word is in DAC1H[6:0], while the least significant 5-bits is in DAC1L[7:3].												
		AC1H			DAG							
MSI	3					LSB						
1x:		significant by t nybble is in			ord is in DAC	1H, while th	e least					
	U	AC1H	[/		DAG	CIL						
MOD				<b>I</b>								
MSB					LSB							



### Table 7.1. DAC Electrical Characteristics

VDD = 3.0V, AV + = 3.0V, R	EF = 2.40V (REFBE=0), No Output Load un	less other	wise speci	fied.	
PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
STATIC PERFORMANCE					
Resolution			12		bits
Integral Nonlinearity	For Data Word Range 0x014 to 0xFEB		±2		LSB
Differential Nonlinearity	Guaranteed Monotonic (codes 0x014 to 0xFEB)			±1	LSB
Output Noise	No Output Filter 100kHz Output Filter 10kHz Output Filter		250 128 41		μVrms
Offset Error	Data Word = $0x014$		±3	±30	mV
Offset Tempco			6		ppm/°C
Full-Scale Error			±20	±60	mV
Full-Scale Error Tempco			10		ppm/°C
VDD Power-Supply Rejection Ratio			-60		dB
Output Impedance in Shutdown Mode	DACnEN=0		100		kΩ
Output Current			±300		μΑ
Output Short Circuit Current	Data Word = 0xFFF		15		mA
DYNAMIC PERFORMANC	ĊE		•		
Voltage Output Slew Rate	Load = 40 pF		0.44		V/µs
Output Settling Time To <sup>1</sup> / <sub>2</sub> LSB	Load = 40pF, Output swing from code 0xFFF to 0x014		10		μs
Output Voltage Swing		0		REF- 1LSB	V
Startup Time	DAC Enable asserted		10		μs
ANALOG OUTPUTS	·		·	•	
Load Regulation	$I_L = 0.01 \text{ mA to } 0.3 \text{ mA at code } 0 \text{xFFF}$		60		ppm
CURRENT CONSUMPTIO					
Power Supply Current (AV+ supplied to DAC)	Data Word = $0x7FF$		110	400	μΑ



### 8. COMPARATORS

The MCU family has two on-chip analog voltage comparators as shown in Figure 8.1. The inputs of each Comparator are available at the package pins. The output of each comparator is optionally available at the package pins via the I/O crossbar (see Section 15.1). When assigned to package pins, each comparator output can be programmed to operate in open drain or push-pull modes (see section 15.3).

The hysteresis of each comparator is software-programmable via its respective Comparator control register (CPT0CN, CPT1CN). The user can program both the amount of hysteresis voltage (referred to the input voltage) and the positive and negative-going symmetry of this hysteresis around the threshold voltage. The output of the comparator can be polled in software, or can be used as an interrupt source. Each comparator can be individually enabled or disabled (shutdown). When disabled, the comparator output (if assigned to a Port I/O pin via the Crossbar) defaults to the logic low state, its interrupt capability is suspended and its supply current falls to less than  $1\mu$ A. Comparator 0 inputs can be externally driven from -0.25V to (AV+) + 0.25V without damage or upset.

The Comparator 0 hysteresis is programmed using bits 3-0 in the Comparator 0 Control Register CPT0CN (shown in Figure 8.3). The amount of *negative* hysteresis voltage is determined by the settings of the CP0HYN bits. As shown in Figure 8.2, settings of 10, 4 or 2mV of negative hysteresis can be programmed, or negative hysteresis can be disabled. In a similar way, the amount of *positive* hysteresis is determined by the setting the CP0HYP bits.

Comparator interrupts can be generated on both rising-edge and falling-edge output transitions. (For Interrupt enable and priority control, see Section 10.4). The CP0FIF flag is set upon a Comparator 0 falling-edge interrupt, and the CP0RIF flag is set upon the Comparator 0 rising-edge interrupt. Once set, these bits remain set until cleared by the CPU. The Output State of Comparator 0 can be obtained at any time by reading the CP0OUT bit. Note the comparator output and interrupt should be ignored until the comparator settles after power-up. Comparator 0 is enabled by setting the CP0EN bit, and is disabled by clearing this bit. Note there is a 20usec settling time for the comparator output to stabilize after setting the CP0EN bit or a power-up. Comparator 0 can also be programmed as a reset source. For details, see Section 13.

The operation of Comparator 1 is identical to that of Comparator 0, except the Comparator 1 is controlled by the CPT1CN Register (Figure 8.4). Comparator 1 can not be programmed as a reset source. Also, the input pins for Comparator 1 are not pinned out on the F002, F007, F012, or F017 devices. The complete electrical specifications for the Comparators are given in Table 8.1.

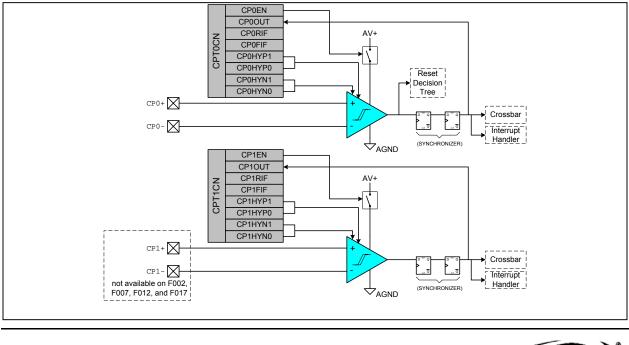
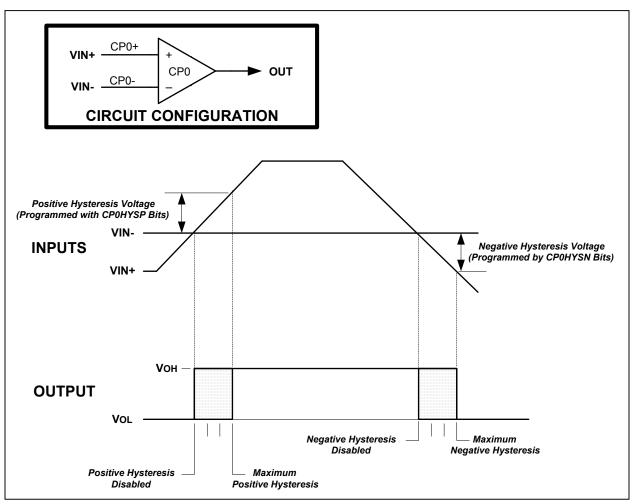


Figure 8.1. Comparator Functional Block Diagram









R/W	R	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value					
CP0EN	CP0OUT	CP0RIF	CP0FIF	CP0HYP1	CP0HYP0	CP0HYN1	CP0HYN0	0000000					
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address					
								0x9E					
Bit7:	CP0EN: Comp												
	0: Comparato												
	<ol> <li>Comparator 0 Enabled.</li> <li>CP0OUT: Comparator 0 Output State Flag</li> <li>0: Voltage on CP0+ &lt; CP0-</li> <li>Voltage on CP0+ &lt; CP0-</li> </ol>												
Bit6:													
	1: Voltage on CP0+>CP0-												
Bit5:		PORIF: Comparator 0 Rising-Edge Interrupt Flag											
		: No Comparator 0 Rising-Edge Interrupt has occurred since this flag was cleared											
DIA	1: Comparator 0 Rising-Edge Interrupt has occurred since this flag was cleared CP0FIF: Comparator 0 Falling-Edge Interrupt Flag												
Bit4:					1 1	·	1						
	0: No Compa												
D:42 0.	1: Comparato					ag was cleare	ed						
Bit3-2:				steresis Con	TOI BITS								
	00: Positive H												
	01: Positive H 10: Positive H												
	11: Positive F												
Rit1_0.	CP0HYN1-0:			Instaracia Co	ntrol Bits								
Dit1-0.	00: Negative			Tysteresis Co	into Dits								
	01: Negative												
	10: Negative	2											
	11: Negative	•											
	iii itegutive	1,50010515	101111										

### Figure 8.3. CPT0CN: Comparator 0 Control Register



R/W	R	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value				
CP1EN	CPIOUT	CP1RIF	CP1FIF	CP1HYP1	CP1HYP0	CP1HYN1	CP1HYN0	00000000				
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:				
								0x9F				
Bit7:	CP1EN: Com	parator 1 Ena	ble Bit									
	0: Comparato	r 1 Disabled.										
	1: Comparato	r 1 Enabled.										
Bit6:	CP1OUT: Cor	CP1OUT: Comparator 1 Output State Flag										
	0: Voltage on	Voltage on CP1+ < CP1-										
	1: Voltage on	Voltage on $CP1+ > CP1-$										
Bit5:	CP1RIF: Com	P1RIF: Comparator 1 Rising-Edge Interrupt Flag										
		No Comparator 1 Rising-Edge Interrupt has occurred since this flag was cleared										
	1: Comparato											
Bit4:	CP1FIF: Com	parator 1 Fal	ling-Edge In	terrupt Flag								
	0: No Compa	rator 1 Fallin	g-Edge Inter	rupt has occu	irred since th	is flag was c	leared					
	1: Comparato	r 1 Falling-E	dge Interrup	t has occurred	d since this fl	ag was clear	ed					
Bit3-2:	CP1HYP1-0:	Comparator	l Positive Hy	ysteresis Cont	trol Bits							
	00: Positive H	Iysteresis Di	sabled									
	01: Positive H	Iysteresis = 2	2mV									
	10: Positive H											
	11: Positive H	Iysteresis = 1	0mV									
Bit1-0:				<b>Iysteresis</b> Co	ntrol Bits							
	00: Negative	2										
	01: Negative											
	10: Negative	2										
	11: Negative	Hysteresis =	10mV									

### Figure 8.4. CPT1CN: Comparator 1 Control Register



### Table 8.1. Comparator Electrical Characteristics

VDD = 3.0V, AV + = 3.0V,  $-40^{\circ}C$  to  $+85^{\circ}C$  unless otherwise specified.

PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
Response Time1	(CP+) - (CP-) = 100mV (Note 1)		4		μs
Response Time2	(CP+) - (CP-) = 10mV (Note 1)		12		μs
Common Mode Rejection			1.5	4	mV/V
Ratio					
Positive Hysteresis1	CPnHYP1-0 = 00		0	1	mV
Positive Hysteresis2	CPnHYP1-0 = 01	2	4.5	7	mV
Positive Hysteresis3	CPnHYP1-0 = 10	4	9	13	mV
Positive Hysteresis4	CPnHYP1-0 = 11	10	17	25	mV
Negative Hysteresis1	CPnHYN1-0 = 00		0	1	mV
Negative Hysteresis2	CPnHYN1-0 = 01	2	4.5	7	mV
Negative Hysteresis3	CPnHYN1-0 = 10	4	9	13	mV
Negative Hysteresis4	CPnHYN1-0 = 11	10	17	25	mV
Inverting or Non-inverting		-0.25		(AV+)	V
Input Voltage Range				+ 0.25	
Input Capacitance			7		pF
Input Bias Current		-5	0.001	+5	nA
Input Offset Voltage		-10		+10	mV
POWER SUPPLY					
Power-up Time	CPnEN from 0 to 1		20		μs
Power Supply Rejection			0.1	1	mV/V
Supply Current	Operating Mode (each comparator) at DC		1.5	10	μΑ

Note 1: CPnHYP1-0 = CPnHYN1-0 = 00.



### 9. VOLTAGE REFERENCE

The voltage reference circuit consists of a 1.2V, 15ppm/°C (typical) bandgap voltage reference generator and a gain-of-two output buffer amplifier. The reference voltage on VREF can be connected to external devices in the system, as long as the maximum load seen by the VREF pin is less than 200µA to AGND (see Figure 9.1).

If a different reference voltage is required, an external reference can be connected to the VREF pin and the internal bandgap and buffer amplifier disabled in software. The external reference voltage must still be less than AV+ - 0.3V. The Reference Control Register, REF0CN (defined in Figure 9.2), provides the means to enable or disable the bandgap and buffer amplifier. The BIASE bit in REF0CN enables the bias circuitry for the ADC and DACs while the REFBE bit enables the bandgap reference and buffer amplifier which drive the VREF pin. When disabled, the supply current drawn by the bandgap and buffer amplifier falls to less than 1uA (typical) and the output of the buffer amplifier enters a high impedance state. If the internal bandgap is used as the reference voltage generator, BIASE and REFBE must both be set to 1. If an external reference is used, REFBE must be set to 0 and BIASE must be set to 1. If neither the ADC nor the DAC are being used, both of these bits can be set to 0 to conserve power. The electrical specifications for the Voltage Reference are given in Table 9.1.

The temperature sensor connects to the highest order input of the A/D converter's input multiplexer (see Figure 5.1 and Figure 5.5 for details). The TEMPE bit within REF0CN enables and disables the temperature sensor. While disabled, the temperature sensor defaults to a high impedance state and any A/D measurements performed on the sensor while disabled result in meaningless data.

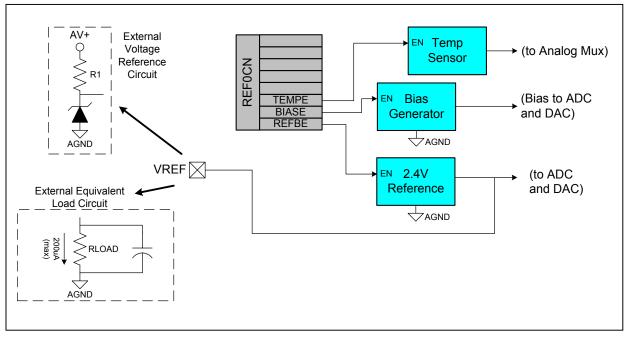


Figure 9.1. Voltage Reference Functional Block Diagram



R/W		R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-	-	-	-	-	TEMPE	BIASE	REFBE	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xD1
Bits7-3	UNUSED. Rea	d = 00000b	Write = don'	t care				
Bit2:	TEMPE: Tempe	,		t ouro				
D1(2).	0: Internal Tem							
	1: Internal Tem	1						
Bit1:	BIASE: Bias Er	1		C's				
DITI.	0: Internal Bias							
	1: Internal Bias		for use of A	DC  or  DAC	's)			
Bit0:	REFBE: Interna	× 1			/			
Dito.	0: Internal Refe	0				from external	l source on	
	VREF pin.	Telice Duffer	OII. System	i ieleielice ca			i source on	
	1: Internal Refe	rence Buffer	On. System	reference pr	ovided by int	ernal voltage	e reference.	
			2		2	C		

### Figure 9.2. REF0CN: Reference Control Register

### **Table 9.1. Reference Electrical Characteristics**

VDD = 3.0V, AV + = 3.0V,  $-40^{\circ}C$  to  $+85^{\circ}C$  unless otherwise specified.

PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
INTERNAL REFERENCE	$(\mathbf{REFBE} = 1)$				
Output Voltage	25°C ambient	2.34	2.43	2.50	V
VREF Short Circuit Current				30	mA
VREF Power Supply			50		μΑ
Current (supplied by AV+)					-
VREF Temperature			15		ppm/°C
Coefficient					
Load Regulation	Load = $(0-to-200\mu A)$ to AGND (Note 1)		0.5		ppm/µA
VREF Turn-on Time1	4.7µF tantalum, 0.1µF ceramic bypass		2		ms
VREF Turn-on Time2	0.1µF ceramic bypass		20		μs
VREF Turn-on Time3	no bypass cap		10		μs
EXTERNAL REFERENCE	$(\mathbf{REFBE} = 0)$				
Input Voltage Range		1.00		(AV+)	V
				-0.3V	
Input Current			0	1	μA

Note 1: The reference can only source current. When driving an external load, it is recommended to add a load resistor to AGND.



### **10. CIP-51 CPU**

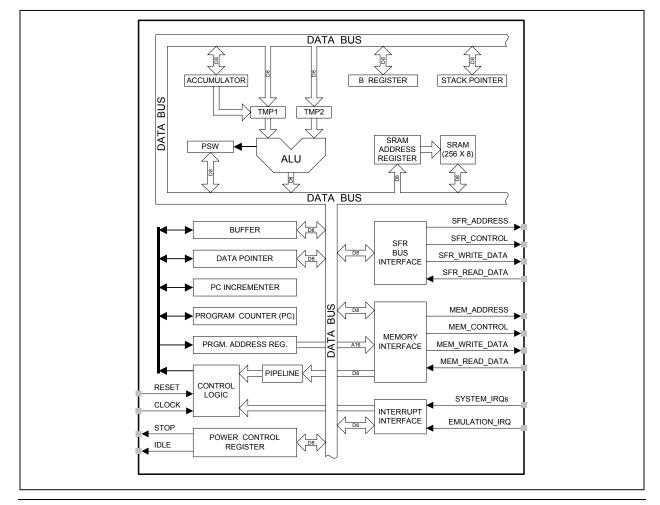
The MCUs' system CPU is the CIP-51. The CIP-51 is fully compatible with the MCS- $51^{\text{TM}}$  instruction set. Standard 803x/805x assemblers and compilers can be used to develop software. The MCU family has a superset of all the peripherals included with a standard 8051. Included are four 16-bit counter/timers (see description in Section 19), a full-duplex UART (see description in Section 18), 256 bytes of internal RAM, 128 byte Special Function Register (SFR) address space (see Section 10.3), and four byte-wide I/O Ports (see description in Section 14). The CIP-51 also includes on-chip debug hardware (see description in Section 21), and interfaces directly with the MCUs' analog and digital subsystems providing a complete data acquisition or control-system solution in a single integrated circuit.

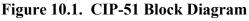
#### Features

The CIP-51 Microcontroller core implements the standard 8051 organization and peripherals as well as additional custom peripherals and functions to extend its capability (see Figure 10.1 for a block diagram). The CIP-51 includes the following features:

- Fully Compatible with MCS-51 Instruction Set
- 25 MIPS Peak Throughput with 25MHz Clock
- 0 to 25MHz Clock Frequency (on 'F0x5/6/7)
- Four Byte-Wide I/O Ports
- Extended Interrupt Handler

- Reset Input
- Power Management Modes
- On-chip Debug Circuitry
- Program and Data Memory Security







#### Performance

The CIP-51 employs a pipelined architecture that greatly increases its instruction throughput over the standard 8051 architecture. In a standard 8051, all instructions except for MUL and DIV take 12 or 24 system clock cycles to execute, and usually have a maximum system clock of 12MHz. By contrast, the CIP-51 core executes 70% of its instructions in one or two system clock cycles, with no instructions taking more than eight system clock cycles.

With the CIP-51's maximum system clock at 25MHz, it has a peak throughput of 25MIPS. The CIP-51 has a total of 109 instructions. The number of instructions versus the system clock cycles required to execute them is as follows:

Instructions	26	50	5	14	7	3	1	2	1
Clocks to Execute	1	2	2/3	3	3/4	4	4/5	5	8

#### **Programming and Debugging Support**

A JTAG-based serial interface is provided for in-system programming of the Flash program memory and communication with on-chip debug support circuitry. The reprogrammable Flash can also be read and changed a single byte at a time by the application software using the MOVC and MOVX instructions. This feature allows program memory to be used for non-volatile data storage as well as updating program code under software control.

The on-chip debug support circuitry facilitates full speed in-circuit debugging, allowing the setting of hardware breakpoints and watch points, starting, stopping and single stepping through program execution (including interrupt service routines), examination of the program's call stack, and reading/writing the contents of registers and memory. This method of on-chip debugging is completely non-intrusive and non-invasive, requiring no RAM, Stack, timers, or other on-chip resources.

The CIP-51 is supported by development tools from Silicon Laboratories and third party vendors. Silicon Labs provides an integrated development environment (IDE) including editor, macro assembler, debugger and programmer. The IDE's debugger and programmer interface to the CIP-51 via its JTAG interface to provide fast and efficient in-system device programming and debugging. Third party macro assemblers and C compilers are also available.

#### **10.1. INSTRUCTION SET**

The instruction set of the CIP-51 System Controller is fully compatible with the standard MCS-51<sup>™</sup> instruction set. Standard 8051 development tools can be used to develop software for the CIP-51. All CIP-51 instructions are the binary and functional equivalent of their MCS-51<sup>™</sup> counterparts, including opcodes, addressing modes and effect on PSW flags. However, instruction timing is different than that of the standard 8051.

#### **10.1.1. Instruction and CPU Timing**

In many 8051 implementations, a distinction is made between machine cycles and clock cycles, with machine cycles varying from 2 to 12 clock cycles in length. However, the CIP-51 implementation is based solely on clock cycle timing. All instruction timings are specified in terms of clock cycles.

Due to the pipelined architecture of the CIP-51, most instructions execute in the same number of clock cycles as there are program bytes in the instruction. Conditional branch instructions take one less clock cycle to complete when the branch is not taken as opposed to when the branch is taken. Table 10.1 is the CIP-51 Instruction Set Summary, which includes the mnemonic, number of bytes, and number of clock cycles for each instruction.

#### 10.1.2. MOVX Instruction and Program Memory

The MOVX instruction is typically used to access external data memory. In the CIP-51, the MOVX instruction can access the on-chip program memory space implemented as reprogrammable Flash memory using the control bits in the PSCTL register (see Figure 11.1). This feature provides a mechanism for the CIP-51 to update program code and use the program memory space for non-volatile data storage. For the products with RAM mapped into external data memory space (C8051F005/06/07/15/16/17), MOVX is still used to read/write this memory with the PSCTL



register configured for accessing the external data memory space. Refer to Section 11 (Flash Memory) for further details.



Mnemonic	Description	Bytes	Clock
			Cycles
	ARITHMETIC OPERATIONS Add register to A	1	1
ADD A,Rn ADD A,direct	Add register to A Add direct byte to A	2	2
ADD A,@Ri	Add indirect BAM to A	1	2
ADD A,@KI ADD A,#data	Add immediate to A	2	2
ADD A,#data ADDC A,Rn		1	1
ADDC A, Kn ADDC A, direct	Add register to A with carry	2	2
	Add direct byte to A with carry	1	2
ADDC A,@Ri	Add indirect RAM to A with carry	2	
ADDC A,#data	Add immediate to A with carry	1	2
SUBB A,Rn	Subtract register from A with borrow		1
SUBB A, direct	Subtract direct byte from A with borrow	2	2
SUBB A,@Ri	Subtract indirect RAM from A with borrow	1	2
SUBB A,#data	Subtract immediate from A with borrow	2	2
INC A	Increment A	1	1
INC Rn	Increment register	1	1
INC direct	Increment direct byte	2	2
INC @Ri	Increment indirect RAM	1	2
DEC A	Decrement A	1	1
DEC Rn	Decrement register	1	1
DEC direct	Decrement direct byte	2	2
DEC @Ri	Decrement indirect RAM	1	2
INC DPTR	Increment Data Pointer	1	1
MUL AB	Multiply A and B	1	4
DIV AB	Divide A by B	1	8
DA A	Decimal Adjust A	1	1
	LOGICAL OPERATIONS		<u>г</u> .
ANL A,Rn	AND Register to A	1	1
ANL A, direct	AND direct byte to A	2	2
ANL A,@Ri	AND indirect RAM to A	1	2
ANL A,#data	AND immediate to A	2	2
ANL direct,A	AND A to direct byte	2	2
ANL direct,#data	AND immediate to direct byte	3	3
ORL A,Rn	OR Register to A	1	1
ORL A, direct	OR direct byte to A	2	2
ORL A,@Ri	OR indirect RAM to A	1	2
ORL A,#data	OR immediate to A	2	2
ORL direct,A	OR A to direct byte	2	2
ORL direct,#data	OR immediate to direct byte	3	3
XRL A,Rn	Exclusive-OR Register to A	1	1
XRL A, direct	Exclusive-OR direct byte to A	2	2
XRL A,@Ri	Exclusive-OR indirect RAM to A	1	2
XRL A,#data	Exclusive-OR immediate to A	2	2
XRL direct,A	Exclusive-OR A to direct byte	2	2
XRL direct,#data	Exclusive-OR immediate to direct byte	3	3
CLR A	Clear A	1	1
CPL A	Complement A	1	1
RL A	Rotate A left	1	1
RLC A	Rotate A left through carry	1	1
RR A	Rotate A right	1	1

Table 10.1. CIP-51 Instruction Set Summary



Mnemonic	Description	Bytes	Clock Cycles
RRC A	Rotate A right through carry	1	1
SWAP A	Swap nibbles of A	1	1
	DATA TRANSFER		
MOV A,Rn	Move register to A	1	1
MOV A, direct	Move direct byte to A	2	2
MOV A,@Ri	Move indirect RAM to A	1	2
MOV A,#data	Move immediate to A	2	2
MOV Rn,A	Move A to register	1	1
MOV Rn,direct	Move direct byte to register	2	2
MOV Rn,#data	Move immediate to register	2	2
MOV direct,A	Move A to direct byte	2	2
MOV direct,Rn	Move register to direct byte	2	2
MOV direct, direct	Move direct byte to direct	3	3
MOV direct,@Ri	Move indirect RAM to direct byte	2	2
MOV direct,#data	Move immediate to direct byte	3	3
MOV @Ri,A	Move A to indirect RAM	1	2
MOV @Ri,direct	Move direct byte to indirect RAM	2	2
MOV @Ri,#data	Move immediate to indirect RAM	2	2
MOV DPTR,#data16	Load data pointer with 16-bit constant	3	3
MOVC A,@A+DPTR	Move code byte relative DPTR to A	1	3
MOVC A,@A+PC	Move code byte relative DLTR to A	1	3
MOVC A,@AHC MOVX A,@Ri	Move external data (8-bit address) to A	1	3
MOVX @Ri,A	Move A to external data (8-bit address) to A	1	3
MOVX @KI,A MOVX A,@DPTR	Move A to external data (8-bit address) Move external data (16-bit address) to A	1	3
MOVX @DPTR,A	Move A to external data (16-bit address) to A	1	3
PUSH direct	Push direct byte onto stack	2	2
POP direct	Pop direct byte from stack	2	2
XCH A,Rn	Exchange register with A	1	1
		2	2
XCH A, direct	Exchange direct byte with A Exchange indirect RAM with A		
XCH A,@Ri		1	2
XCHD A,@Ri	Exchange low nibble of indirect RAM with A	1	2
CL D C	BOOLEAN MANIPULATION	1	1
CLR C	Clear carry	1	1
CLR bit	Clear direct bit	2	2
SETB C	Set carry	1	1
SETB bit	Set direct bit	2	2
CPL C	Complement carry	1	1
CPL bit	Complement direct bit	2	2
ANL C,bit	AND direct bit to carry	2	2
ANL C,/bit	AND complement of direct bit to carry	2	2
ORL C,bit	OR direct bit to carry	2	2
ORL C,/bit	OR complement of direct bit to carry	2	2
MOV C,bit	Move direct bit to carry	2	2
MOV bit,C	Move carry to direct bit	2	2
JC rel	Jump if carry is set	2	2/3
JNC rel	Jump if carry not set	2	2/3
JB bit,rel	Jump if direct bit is set	3	3/4
JNB bit,rel	Jump if direct bit is not set	3	3/4
JBC bit,rel	Jump if direct bit is set and clear bit	3	3/4
	PROGRAM BRANCHING		



Mnemonic	Description	Bytes	Clock Cycles
ACALL addr11	Absolute subroutine call	2	3
LCALL addr16	Long subroutine call	3	4
RET	Return from subroutine	1	5
RETI	Return from interrupt	1	5
AJMP addr11	Absolute jump	2	3
LJMP addr16	Long jump	3	4
SJMP rel	Short jump (relative address)	2	3
JMP @A+DPTR	Jump indirect relative to DPTR	1	3
JZ rel	Jump if A equals zero	2	2/3
JNZ rel	Jump if A does not equal zero	2	2/3
CJNE A, direct, rel	Compare direct byte to A and jump if not equal	3	3/4
CJNE A,#data,rel	Compare immediate to A and jump if not equal	3	3/4
CJNE Rn,#data,rel	Compare immediate to register and jump if not equal	3	3/4
CJNE @Ri,#data,rel	Compare immediate to indirect and jump if not equal	3	4/5
DJNZ Rn,rel	Decrement register and jump if not zero	2	2/3
DJNZ direct,rel	Decrement direct byte and jump if not zero	3	3/4
NOP	No operation	1	1

#### Notes on Registers, Operands and Addressing Modes:

**Rn** - Register R0-R7 of the currently selected register bank.

@Ri - Data RAM location addressed indirectly through register R0-R1

**rel** - 8-bit, signed (two's compliment) offset relative to the first byte of the following instruction. Used by SJMP and all conditional jumps.

**direct** - 8-bit internal data location's address. This could be a direct-access Data RAM location (0x00-0x7F) or an SFR (0x80-0xFF).

#data - 8-bit constant

#data 16 - 16-bit constant

bit - Direct-addressed bit in Data RAM or SFR.

**addr 11** - 11-bit destination address used by ACALL and AJMP. The destination must be within the same 2K-byte page of program memory as the first byte of the following instruction.

**addr 16** - 16-bit destination address used by LCALL and LJMP. The destination may be anywhere within the 64K-byte program memory space.

There is one unused opcode (0xA5) that performs the same function as NOP. All mnemonics copyrighted  $\bigcirc$  Intel Corporation 1980.



#### 10.2. MEMORY ORGANIZATION

The memory organization of the CIP-51 System Controller is similar to that of a standard 8051. There are two separate memory spaces: program memory and data memory. Program and data memory share the same address space but are accessed via different instruction types. There are 256 bytes of internal data memory and 64K bytes of internal program memory address space implemented within the CIP-51. The CIP-51 memory organization is shown in Figure 10.2.

#### 10.2.1. Program Memory

The CIP-51 has a 64K-byte program memory space. The MCU implements 32896 bytes of this program memory space as in-system, reprogrammable Flash memory, organized in a contiguous block from addresses 0x0000 to 0x807F. Note: 512 bytes (0x7E00 - 0x7FFF) of this memory are reserved for factory use and are not available for user program storage.

Program memory is normally assumed to be read-only. However, the CIP-51 can write to program memory by setting the Program Store Write Enable bit (PSCTL.0) and using the MOVX instruction. This feature provides a mechanism for the CIP-51 to update program code and use the program memory space for non-volatile data storage. Refer to Section 11 (Flash Memory) for further details.

#### 10.2.2. Data Memory

The CIP-51 implements 256 bytes of internal RAM mapped into the data memory space from 0x00 through 0xFF. The lower 128 bytes of data memory are used for general purpose registers and scratch pad memory. Either direct or indirect addressing may be used to access the lower 128 bytes of data memory. Locations 0x00 through 0x1F are addressable as four banks of general purpose registers, each bank consisting of eight byte-wide registers. The next 16 bytes, locations 0x20 through 0x2F, may be addressed as bytes or as 128 bit locations accessible with the directbit addressing mode.

The upper 128 bytes of data memory are accessible only by indirect addressing. This region occupies the same address space as the Special Function Registers (SFR) but is physically separate from the SFR space. The addressing mode used by an instruction when accessing locations above 0x7F determines whether the CPU accesses the upper 128 bytes of data memory space or the SFRs. Instructions that use direct addressing will access the SFR space. Instructions using indirect addressing above 0x7F will access the upper 128 bytes of data memory. Figure 10.2 illustrates the data memory organization of the CIP-51.

The C8051F005/06/07/15/16/17 also have 2048 bytes of RAM in the external data memory space of the CIP-51, accessible using the MOVX instruction. Refer to Section 12 (External RAM) for details.

#### 10.2.3. General Purpose Registers

The lower 32 bytes of data memory, locations 0x00 through 0x1F, may be addressed as four banks of generalpurpose registers. Each bank consists of eight byte-wide registers designated R0 through R7. Only one of these banks may be enabled at a time. Two bits in the program status word, RS0 (PSW.3) and RS1 (PSW.4), select the active register bank (see description of the PSW in Figure 10.6). This allows fast context switching when entering subroutines and interrupt service routines. Indirect addressing modes use registers R0 and R1 as index registers.

#### **10.2.4.** Bit Addressable Locations

In addition to direct access to data memory organized as bytes, the sixteen data memory locations at 0x20 through 0x2F are also accessible as 128 individually addressable bits. Each bit has a bit address from 0x00 to 0x7F. Bit 0 of the byte at 0x20 has bit address 0x00 while bit 7 of the byte at 0x20 has bit address 0x07. Bit 7 of the byte at 0x2F has bit address 0x7F. A bit access is distinguished from a full byte access by the type of instruction used (bit source or destination operands as opposed to a byte source or destination).

The MCS-51<sup>™</sup> assembly language allows an alternate notation for bit addressing of the form XX. B where XX is the byte address and B is the bit position within the byte. For example, the instruction: MOV

C, 22h.3

moves the Boolean value at 0x13 (bit 3 of the byte at location 0x22) into the user Carry flag.



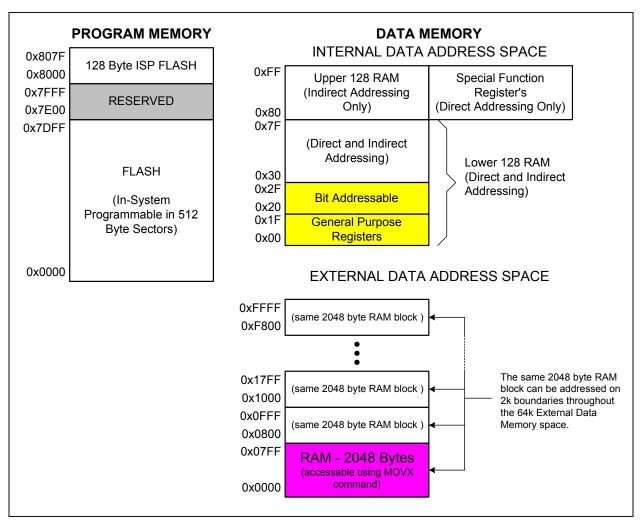


Figure 10.2. Memory Map

#### 10.2.5. Stack

A programmer's stack can be located anywhere in the 256-byte data memory. The stack area is designated using the Stack Pointer (SP, 0x81) SFR. The SP will point to the last location used. The next value pushed on the stack is placed at SP+1 and then SP is incremented. A reset initializes the stack pointer to location 0x07. Therefore, the first value pushed on the stack is placed at location 0x08, which is also the first register (R0) of register bank 1. Thus, if more than one register bank is to be used, the SP should be initialized to a location in the data memory not being used for data storage. The stack depth can extend up to 256 bytes.

The MCUs also have built-in hardware for a stack record. The stack record is a 32-bit shift register, where each Push or increment SP pushes one record bit onto the register, and each Call or interrupt pushes two record bits onto the register. (A Pop or decrement SP pops one record bit, and a Return pops two record bits, also.) The stack record circuitry can also detect an overflow or underflow on the Stack, and can notify the debug software even with the MCU running full-speed debug.



### **10.3. SPECIAL FUNCTION REGISTERS**

The direct-access data memory locations from 0x80 to 0xFF constitute the special function registers (SFRs). The SFRs provide control and data exchange with the CIP-51's resources and peripherals. The CIP-51 duplicates the SFRs found in a typical 8051 implementation as well as implementing additional SFRs used to configure and access the sub-systems unique to the MCU. This allows the addition of new functionality while retaining compatibility with the MCS-51<sup>TM</sup> instruction set. Table 10.3 lists the SFRs implemented in the CIP-51 System Controller.

The SFR registers are accessed any time the direct addressing mode is used to access memory locations from 0x80 to 0xFF. SFRs with addresses ending in 0x0 or 0x8 (e.g. P0, TCON, P1, SCON, IE, etc.) are bit-addressable as well as byte-addressable. All other SFRs are byte-addressable only. Unoccupied addresses in the SFR space are reserved for future use. Accessing these areas will have an indeterminate effect and should be avoided. Refer to the corresponding pages of the datasheet, as indicated in Table 10.3, for a detailed description of each register.

8	SPI0CN	PCA0H	PCA0CPH0	PCA0CPH1	PCA0CPH2	PCA0CPH3	PCA0CPH4	WDTCN
)	В						EIP1	EIP2
3	ADC0CN	PCA0L	PCA0CPL0	PCA0CPL1	PCA0CPL2	PCA0CPL3	PCA0CPL4	RSTSRC
0	ACC	XBR0	XBR1	XBR2			EIE1	EIE2
8	PCA0CN	PCA0MD	PCA0CPM0	PCA0CPM1	PCA0CPM2	PCA0CPM3	PCA0CPM4	
0	PSW	<b>REF0CN</b>	DAC0L	DAC0H	DAC0CN	DAC1L	DAC1H	DAC1CN
8	T2CON		RCAP2L	RCAP2H	TL2	TH2		SMB0CR
0	SMB0CN	SMB0STA	SMB0DAT	SMB0ADR	ADC0GTL	ADC0GTH	ADC0LTL	ADC0LTH
8	IP		AMX0CF	AMX0SL	ADC0CF		ADC0L	ADC0H
0	P3	OSCXCN	OSCICN				FLSCL	FLACL***
8	IE					PRT1IF		EMI0CN**
0	P2				PRT0CF	PRT1CF	PRT2CF	PRT3CF
8	SCON	SBUF	SPI0CFG	SPI0DAT		SPI0CKR	CPT0CN	CPT1CN
)	P1	TMR3CN	TMR3RLL	TMR3RLH	TMR3L	TMR3H		
3	TCON	TMOD	TL0	TL1	TH0	TH1	CKCON	PSCTL
0	P0	SP	DPL	DPH				PCON
	<b>▲</b> 0(8)	1(9)	2(A)	3(B)	4(C)	5(D)	6(E)	7(F)

 Table 10.2.
 Special Function Register Memory Map

Bit Addressable

#### **Table 10.3. Special Function Registers**

SFRs are listed in alphabetical order. All undefined SFR locations are reserved.

- \* Refers to a register in the C8051F000/1/2/5/6/7 only.
- \*\* Refers to a register in the C8051F010/1/2/5/6/7 only.
- \*\*\* Refers to a register in the C8051F005/06/07/15/16/17 only.

Address	Register	Description	Page No.
0xE0	ACC	Accumulator	76
0xBC	ADC0CF	ADC Configuration	33*, 42**
0xE8	ADC0CN	ADC Control	34*, 45**
0xC5	ADC0GTH	ADC Greater-Than Data Word (High Byte)	36*, 47**
0xC4	ADC0GTL	ADC Greater-Than Data Word (Low Byte)	36*, 47**
0xBF	ADC0H	ADC Data Word (High Byte)	35*, 46**
0xBE	ADC0L	ADC Data Word (Low Byte)	35*, 46**



Address	Register	Description	Page No.
0xC7	ADC0LTH	ADC Less-Than Data Word (High Byte)	36*, 47**
0xC6	ADC0LTL	ADC Less-Than Data Word (Low Byte)	36*, 47**
0xBA	AMX0CF	ADC MUX Configuration	31*, 42**
0xBB	AMX0SL	ADC MUX Channel Selection	32*, 43**
0xF0	В	B Register	76
0x8E	CKCON	Clock Control	144
0x9E	CPT0CN	Comparator 0 Control	56
0x9F	CPT1CN	Comparator 1 Control	58
0xD4	DAC0CN	DAC 0 Control	52
0xD3	DAC0H	DAC 0 Data Word (High Byte)	52
0xD2	DAC0L	DAC 0 Data Word (Low Byte)	52
0xD7	DAC1CN	DAC 1 Control	53
0xD6	DAC1H	DAC 1 Data Word (High Byte)	53
0xD5	DAC1L	DAC 1 Data Word (Low Byte)	53
0x83	DPH	Data Pointer (High Byte)	74
0x82	DPL	Data Pointer (Low Byte)	74
0xE6	EIE1	Extended Interrupt Enable 1	81
0xE7	EIE2	Extended Interrupt Enable 2	82
0xF6	EIP1	External Interrupt Priority 1	83
0xF7	EIP2	External Interrupt Priority 2	84
0xAF	EMI0CN	External Memory Interface Control	92***
0xB7	FLACL	Flash Access Limit	90***
0xB6	FLSCL	Flash Memory Timing Prescaler	91
0xA8	IE	Interrupt Enable	79
0xB8	IP	Interrupt Priority Control	80
0xB2	OSCICN	Internal Oscillator Control	100
0xB1	OSCXCN	External Oscillator Control	101
0x80	P0	Port 0 Latch	109
0x90	P1	Port 1 Latch	110
0xA0	P2	Port 2 Latch	111
0xB0	P3	Port 3 Latch	112
0xD8	PCA0CN	Programmable Counter Array 0 Control	160
0xFA	РСА0СРН0	PCA Capture Module 0 Data Word (High Byte)	163
0xFB	PCA0CPH1	PCA Capture Module 1 Data Word (High Byte)	163
0xFC	PCA0CPH2	PCA Capture Module 2 Data Word (High Byte)	163
0xFD	РСА0СРН3	PCA Capture Module 3 Data Word (High Byte)	163
0xFE	PCA0CPH4	PCA Capture Module 4 Data Word (High Byte)	163
0xEA	PCA0CPL0	PCA Capture Module 0 Data Word (Low Byte)	163
0xEB	PCA0CPL1	PCA Capture Module 1 Data Word (Low Byte)	163
0xEC	PCA0CPL2	PCA Capture Module 2 Data Word (Low Byte)	163
0xED	PCA0CPL3	PCA Capture Module 3 Data Word (Low Byte)	163



Address	Register	Description	Page No.
0xEE	PCA0CPL4	PCA Capture Module 4 Data Word (Low Byte)	163
0xDA	PCA0CPM0	Programmable Counter Array 0 Capture/Compare 0	162
0xDB	PCA0CPM1	Programmable Counter Array 0 Capture/Compare 1	162
0xDC	PCA0CPM2	Programmable Counter Array 0 Capture/Compare 2	162
0xDD	PCA0CPM3	Programmable Counter Array 0 Capture/Compare 3	162
0xDE	PCA0CPM4	Programmable Counter Array 0 Capture/Compare 4	162
0xF9	РСА0Н	PCA Counter/Timer Data Word (High Byte)	163
0xE9	PCA0L	PCA Counter/Timer Data Word (Low Byte)	163
0xD9	PCA0MD	Programmable Counter Array 0 Mode	161
0x87	PCON	Power Control	86
0xA4	PRT0CF	Port 0 Configuration	109
0xA5	PRT1CF	Port 1 Configuration	110
0xAD	PRT1IF	Port 1 Interrupt Flags	110
0xA6	PRT2CF	Port 2 Configuration	111
0xA7	PRT3CF	Port 3 Configuration	112
0x8F	PSCTL	Program Store RW Control	88
0xD0	PSW	Program Status Word	75
0xCB	RCAP2H	Counter/Timer 2 Capture (High Byte)	151
0xCA	RCAP2L	Counter/Timer 2 Capture (Low Byte)	151
0xD1	REF0CN	Voltage Reference Control Register	61
0xEF	RSTSRC	Reset Source Register	97
0x99	SBUF	Serial Data Buffer (UART)	136
0x98	SCON	Serial Port Control (UART)	137
0xC3	SMB0ADR	SMBus 0 Address	120
0xC0	SMB0CN	SMBus 0 Control	118
0xCF	SMB0CR	SMBus 0 Clock Rate	119
0xC2	SMB0DAT	SMBus 0 Data	120
0xC1	SMB0STA	SMBus 0 Status	121
0x81	SP	Stack Pointer	74
0x9A	SPI0CFG	Serial Peripheral Interface Configuration	127
0x9D	SPI0CKR	SPI Clock Rate	129
0xF8	SPI0CN	SPI Bus Control	128
0x9B	SPIODAT	SPI Port 1Data	129
0xC8	T2CON	Counter/Timer 2 Control	150
0x88	TCON	Counter/Timer Control	142
0x8C	TH0	Counter/Timer 0 Data Word (High Byte)	145
0x8D	TH1	Counter/Timer 1 Data Word (High Byte)	145
0xCD	TH2	Counter/Timer 2 Data Word (High Byte)	151
0x8A	TL0	Counter/Timer 0 Data Word (Low Byte)	145
0x8B	TL1	Counter/Timer 1 Data Word (Low Byte)	145
0xCC	TL2	Counter/Timer 2 Data Word (Low Byte)	151



Address	Register	Description	Page No.
0x89	TMOD	Counter/Timer Mode	143
0x91	TMR3CN	Timer 3 Control	152
0x95	TMR3H	Timer 3 High	153
0x94	TMR3L	Timer 3 Low	153
0x93	TMR3RLH	Timer 3 Reload High	153
0x92	TMR3RLL	Timer 3 Reload Low	153
0xFF	WDTCN	Watchdog Timer Control	96
0xE1	XBR0	Port I/O Crossbar Configuration 1	105
0xE2	XBR1	Port I/O Crossbar Configuration 2	107
0xE3	XBR2	Port I/O Crossbar Configuration 3	108
	x96-97, 0x9C,		
0xA1-A3,	0xA9-AC,		
0xAE, 0xE	3-B5, 0xB9,	Reserved	
0xBD, 0xC	C9, 0xCE,		
0xDF, 0xE	4-E5, 0xF1-F5		

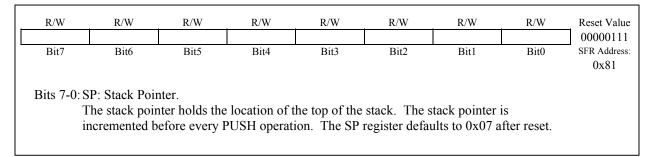
\* Refers to a register in the C8051F000/1/2/5/6/7 only. \*\* Refers to a register in the C8051F010/1/2/5/6/7 only. \*\*\* Refers to a register in the C8051F005/06/07/15/16/17 only.



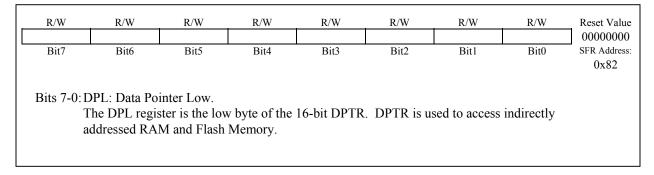
### **10.3.1.** Register Descriptions

Following are descriptions of SFRs related to the operation of the CIP-51 System Controller. Reserved bits should not be set to logic l. Future product versions may use these bits to implement new features in which case the reset value of the bit will be logic 0, selecting the feature's default state. Detailed descriptions of the remaining SFRs are included in the sections of the datasheet associated with their corresponding system function.

### Figure 10.3. SP: Stack Pointer



### Figure 10.4. DPL: Data Pointer Low Byte



### Figure 10.5. DPH: Data Pointer High Byte

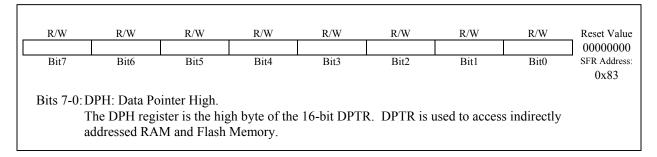


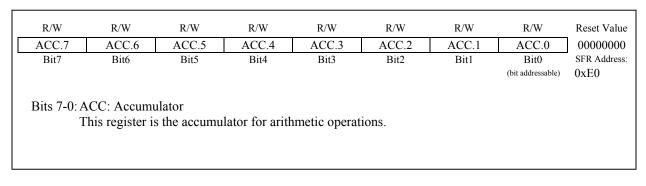


Figure 10.6.	<b>PSW: Program</b>	n Status Word
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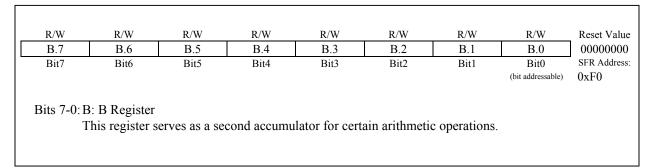
	R/W		R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu
CY	AC		F0	RS1	RS0	OV	F1	PARITY	0000000
Bit7	Bit6	]	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (bit addressable)	SFR Addres 0xD0
Bit7:	CY: Carry		the last	arithmatia	an arction rac	lta in a comm	(addition) a	r a harran	
					operation resu other arithmeti		(addition) o	1 a 00110w	
Bit6:	AC: Auxil			•.•		1		<sup>×</sup>	
					operation resuler nibble. It i				
	operations		action) u	le nigh of	iei illuule. It i	s cleared to 0	by all other	anumetic	
Bit5:	F0: User F	ໄລດ ()							
Dito.			sable, gei	neral purpo	ose flag for us	e under softw	are control.		
Bits4-3	: RS1-RS0:	Register	Bank Se	lect.					
	These bits	select w	hich regis	ster bank is	s used during	register acces	ses.		
	RS1	RS0	Register	Bank	Address				
	0	0	0		0x00-0x07				
	0	1	1		0x08-0x0F				
	1	0	23		)x10-0x17 )x18-0x1F				
Bit2:	by the "Mo OV: Overf This bit is • An A • A MU • A DIV The OV b other case	OV Rn, 2 flow Flag set to 1 u DD, AD JL instru V instruc it is clear s.	A" instruct g. under the DC, or SI ction resu tion caus	following UBB instru ults in an c es a divide	the RS1-RS0 to circumstance action causes overflow (resu by-zero cond D, ADDC, SU	s: a sign-change lt is greater th lition.	overflow. an 255) .		
Bit1:	F1: User F This is a b		sable, gei	neral purpo	ose flag for us	e under softw	are control.		
	PARITY: 1 (Read only		ag.			accumulator is			



### Figure 10.7. ACC: Accumulator



### Figure 10.8. B: B Register





### **10.4. INTERRUPT HANDLER**

The CIP-51 includes an extended interrupt system supporting a total of 22 interrupt sources with two priority levels. The allocation of interrupt sources between on-chip peripherals and external inputs pins varies according to the specific version of the device. Each interrupt source has one or more associated interrupt-pending flag(s) located in an SFR. When a peripheral or external source meets a valid interrupt condition, the associated interrupt-pending flag is set to logic 1.

If interrupts are enabled for the source, an interrupt request is generated when the interrupt-pending flag is set. As soon as execution of the current instruction is complete, the CPU generates an LCALL to a predetermined address to begin execution of an interrupt service routine (ISR). Each ISR must end with an RETI instruction, which returns program execution to the next instruction that would have been executed if the interrupt request had not occurred. If interrupts are not enabled, the interrupt-pending flag is ignored by the hardware and program execution continues as normal. (The interrupt-pending flag is set to logic 1 regardless of the interrupt's enable/disable state.)

Each interrupt source can be individually enabled or disabled through the use of an associated interrupt enable bit in an SFR (IE-EIE2). However, interrupts must first be globally enabled by setting the EA bit (IE.7) to logic 1 before the individual interrupt enables are recognized. Setting the EA bit to logic 0 disables all interrupt sources regardless of the individual interrupt-enable settings.

Some interrupt-pending flags are automatically cleared by the hardware when the CPU vectors to the ISR. However, most are not cleared by the hardware and must be cleared by software before returning from the ISR. If an interrupt-pending flag remains set after the CPU completes the return-from-interrupt (RETI) instruction, a new interrupt request will be generated immediately and the CPU will re-enter the ISR after the completion of the next instruction.

#### 10.4.1. MCU Interrupt Sources and Vectors

The MCUs allocate 12 interrupt sources to on-chip peripherals. Up to 10 additional external interrupt sources are available depending on the I/O pin configuration of the device. Software can simulate an interrupt by setting any interrupt-pending flag to logic 1. If interrupts are enabled for the flag, an interrupt request will be generated and the CPU will vector to the ISR address associated with the interrupt-pending flag. MCU interrupt sources, associated vector addresses, priority order and control bits are summarized in Table 10.4. Refer to the datasheet section associated with a particular on-chip peripheral for information regarding valid interrupt conditions for the peripheral and the behavior of its interrupt-pending flag(s).

#### **10.4.2.** External Interrupts

Two of the external interrupt sources (/INT0 and /INT1) are configurable as active-low level-sensitive or active-low edge-sensitive inputs depending on the setting of IT0 (TCON.0) and IT1 (TCON.2). IE0 (TCON.1) and IE1 (TCON.3) serve as the interrupt-pending flag for the /INT0 and /INT1 external interrupts, respectively. If an /INT0 or /INT1 external interrupt is configured as edge-sensitive, the corresponding interrupt-pending flag is automatically cleared by the hardware when the CPU vectors to the ISR. When configured as level sensitive, the interrupt-pending flag follows the state of the external interrupt's input pin. The external interrupt source must hold the input active until the interrupt request is recognized. It must then deactivate the interrupt request before execution of the ISR completes or another interrupt request will be generated.

The remaining four external interrupts (External Interrupts 4-7) are active-low, edge-sensitive inputs. The interruptpending flags for these interrupts are in the Port 1 Interrupt Flag Register shown in Figure 15.10.



Interrupt Source	Interrupt Vector	Priority Order	Interrupt-Pending Flag	Enable
Reset	0x0000	Тор	None	Always enabled
External Interrupt 0 (/INT0)	0x0003	0	IE0 (TCON.1)	EX0 (IE.0)
Timer 0 Overflow	0x000B	1	TF0 (TCON.5)	ET0 (IE.1)
External Interrupt 1 (/INT1)	0x0013	2	IE1 (TCON.3)	EX1 (IE.2)
Timer 1 Overflow	0x001B	3	TF1 (TCON.7)	ET1 (IE.3)
Serial Port (UART)	0x0023	4	RI (SCON.0)	ES (IE.4)
			TI (SCON.1)	
Timer 2 Overflow (or EXF2)	0x002B	5	TF2 (T2CON.7)	ET2 (IE.5)
Serial Peripheral Interface	0x0033	6	SPIF (SPI0CN.7)	ESPI0 (EIE1.0)
			WCOL (SPI0CN.6)	
			MODF (SPI0CN.5)	
			RXOVRN (SPI0CN.4)	
SMBus Interface	0x003B	7	SI (SMB0CN.3)	ESMB0 (EIE1.1)
ADC0 Window Comparison	0x0043	8	ADWINT (ADC0CN.2)	EWADC0 (EIE1.2)
Programmable Counter Array 0	0x004B	9	CF (PCA0CN.7)	EPCA0 (EIE1.3)
			CCFn (PCA0CN.n)	
Comparator 0 Falling Edge	0x0053	10	CP0FIF (CPT0CN.4)	ECP0F (EIE1.4)
Comparator 0 Rising Edge	0x005B	11	CPORIF (CPT0CN.5)	ECPOR (EIE1.5)
Comparator 1 Falling Edge	0x0063	12	CP1FIF (CPT1CN.4)	ECP1F (EIE1.6)
Comparator 1 Rising Edge	0x006B	13	CP1RIF (CPT1CN.5)	ECP1R (EIE1.7)
Timer 3 Overflow	0x0073	14	TF3 (TMR3CN.7)	ET3 (EIE2.0)
ADC0 End of Conversion	0x007B	15	ADCINT (ADC0CN.5)	EADC0 (EIE2.1)
External Interrupt 4	0x0083	16	IE4 (PRT1IF.4)	EX4 (EIE2.2)
External Interrupt 5	0x008B	17	IE5 (PRT1IF.5)	EX5 (EIE2.3)
External Interrupt 6	0x0093	18	IE6 (PRT1IF.6)	EX6 (EIE2.4)
External Interrupt 7	0x009B	19	IE7 (PRT1IF.7)	EX7 (EIE2.5)
Unused Interrupt Location	0x00A3	20	None	Reserved (EIE2.6)
External Crystal OSC Ready	0x00AB	21	XTLVLD (OSCXCN.7)	EXVLD (EIE2.7)

### Table 10.4. Interrupt Summary

#### **10.4.3.** Interrupt Priorities

Each interrupt source can be individually programmed to one of two priority levels: low or high. A low priority interrupt service routine can be preempted by a high priority interrupt. A high priority interrupt cannot be preempted. Each interrupt has an associated interrupt priority bit in an SFR (IP-EIP2) used to configure its priority level. Low priority is the default. If two interrupts are recognized simultaneously, the interrupt with the higher priority is serviced first. If both interrupts have the same priority level, a fixed priority order is used to arbitrate.

#### 10.4.4. Interrupt Latency

Interrupt response time depends on the state of the CPU when the interrupt occurs. Pending interrupts are sampled and priority decoded each system clock cycle. Therefore, the fastest possible response time is 5 system clock cycles: 1 clock cycle to detect the interrupt and 4 clock cycles to complete the LCALL to the ISR. If an interrupt is pending when a RETI is executed, a single instruction is executed before an LCALL is made to service the pending interrupt. Therefore, the maximum response time for an interrupt (when no other interrupt is currently being serviced or the new interrupt is of greater priority) occurs when the CPU is performing an RETI instruction followed by a DIV as the next instruction. In this case, the response time is 18 system clock cycles: 1 clock cycle to detect the interrupt, 5 clock cycles to execute the RETI, 8 clock cycles to complete the DIV instruction and 4 clock cycles to execute the LCALL to the ISR. If the CPU is executing an ISR for an interrupt with equal or higher priority, the new interrupt will not be serviced until the current ISR completes, including the RETI and following instruction.



#### 10.4.5. Interrupt Register Descriptions

The SFRs used to enable the interrupt sources and set their priority level are described below. Refer to the datasheet section associated with a particular on-chip peripheral for information regarding valid interrupt conditions for the peripheral and the behavior of its interrupt-pending flag(s).

### Figure 10.9. IE: Interrupt Enable

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu
EA	IEGF0	ET2	ES	ET1	EX1	ET0	EX0	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (bit addressable)	SFR Addres 0xA8
							(bit addressable)	UXAð
D'/7		1						
Bit7:	EA: Enable Al			· • •	.1 .1 .	1 1 . 1 .	1	
	This bit global	ly enables/d	isables all int	terrupts. It o	verrides the ii	ndividual in	terrupt mask	
	settings.							
	0: Disable all i 1: Enable each							
	1. Enable each	interrupt ac	cording to he	s marviauar i	nask setting.			
Bit6:	IEGF0: Genera	al Purpose F	lag 0.					
	This is a gener			nder software	e control.			
	C	1 1	C					
Bit5:	ET2: Enable T							
	This bit sets th			l interrupt.				
	0: Disable all							
	1: Enable inter	rrupt reques	ts generated	by the TF2 f	lag (T2CON.7	7)		
Bit4:	EQ: Enchla Qar	rial Dart (II)	ADT) Intormu	at				
DIL4.	ES: Enable Ser This bit sets th				interrunt			
	0: Disable all			UII (UAKI)	interrupt.			
	1: Enable inter			by the R1 fla	$\sigma$ (SCON 0)	vr T1 flag (S	CON 1)	
	1. Endote inter	inupt reques	to generated	by the R1 Hd	(BCOI1.0) (	Ji I I IIug (c		
Bit3:	ET1: Enable T	imer 1 Inter	rupt.					
	This bit sets th			interrupt.				
	0: Disable all			-				
	1: Enable inter	rrupt reques	ts generated	by the TF1 f	lag (TCON.7)			
D'/0		1 T 4	. 1					
Bit2:	EX1: Enable E							
	This bit sets th			errupt 1.				
	0: Disable extended 1: Enable inter			by the /INIT1	nin			
	1. Endore inter	inupt reques	is generated		pin.			
Bit1:	ET0: Enable T	imer 0 Inter	rupt.					
	This bit sets th			) interrupt.				
	0: Disable all			1				
	1: Enable inter	rrupt reques	ts generated	by the TF0 f	lag (TCON.5)			
D:40	EV0. E1.1 E							
Bit0:	EX0: Enable E			orrupt 0				
	This bit sets th 0: Disable exte			errupt 0.				
	1: Enable inter			hy the /INITO	nin			
		ruptieques	is generated	by the / IIN I U	Pm.			



# Figure 10.10. IP: Interrupt Priority

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu
-	-	PT2	PS	PT1	PX1	PT0	PX0	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (bit addressable)	SFR Addres 0xB8
Bits7-6:	UNUSED. Re	ead = 11b, W	rite = don't o	care.				
Bit5:	PT2 Timer 2 If This bit sets th 0: Timer 2 int 1: Timer 2 int	e priority of errupts set to	the Timer 2 low priority	level.				
Bit4:	PS: Serial Port This bit sets th 0: UART inte 1: UART inte	e priority of rrupts set to	the Serial Polon low priority 1	ort (UART) i level.	nterrupts.			
Bit3:	PT1: Timer 1 1 This bit sets th 0: Timer 1 int 1: Timer 1 int	e priority of errupts set to	the Timer 1 low priority	interrupts. level.				
Bit2:	PX1: External This bit sets th 0: External In 1: External In	e priority of terrupt 1 set	the External to low priori	Interrupt 1 i ty level.	nterrupts.			
Bit1:	PT0: Timer 0 1 This bit sets th 0: Timer 0 int 1: Timer 0 int	e priority of errupt set to	the Timer 0 low priority	interrupts. level.				
Bit0:	PX0: External This bit sets th	e priority of		Interrupt 0 i	nterrupts.			



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
ECP1R	ECP1F	ECPOR	ECP0F	EPCA0	EWADC0	ESMB0	ESPIO	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
								0xE6
Bit7:	ECP1R: Enab	le Comparato	or 1 (CP1) R	ising Edge Ir	terrupt.			
	This bit sets the			errupt.				
	0: Disable CI							
	1: Enable inte	errupt request	ts generated	by the CP1R	IF flag (CPT1	CN.5).		
D'//			1 (CD1) E	11' T I T				
Bit6:	ECP1F: Enab				iterrupt.			
	This bit sets the			errupt.				
	0: Disable CF 1: Enable inte			by the CD1E	E flog (CDT1	CN(4)		
	1. Enable inte	errupt request	is generated	by the CFIF	IF flag (CFTT	CIN.4).		
Bit5:	ECP0R: Enab	le Comparato	or 0 (CP0) R	ising Edge Ir	terrupt			
Dite.	This bit sets th				upt.			
	0: Disable CI							
	1: Enable inte			by the CP0R	IF flag (CPT)	)CN.5).		
		1 1	C	2	U X	,		
Bit4:	ECP0F: Enab				nterrupt.			
	This bit sets the			errupt.				
	0: Disable CI	0	0 1					
	1: Enable inte	errupt request	ts generated	by the CP0F	IF flag (CPT0	CN.4).		
Bit3:	EPCA0: Enab	le Programm	able Counte	r Arrav (PCA	0) Interrupt.			
21101	This bit sets th							
	0: Disable all			I				
	1: Enable inte	errupt request	ts generated	by PCA0.				
Bit2:	EWADC0: Er	nable Window	v Compariso	n ADCO Inte	orrunt			
DIL2.	This bit sets th					t		
	0: Disable AI				ison menup			
	1: Enable Inte		1	1	indow Compa	arisons.		
Bit1:	ESMB0: Enat	ble SMBus 0	Interrupt.					
	This bit sets the	he masking o	f the SMBus	interrupt.				
	0: Disable all							
	1: Enable inte	errupt request	ts generated	by the SI flag	g (SMB0CN.3	3).		
Bit0:	ESPI0: Enable	e Serial Perin	heral Interfa	ce () Interrun	t			
Ditt.	This bit sets th							
	0: Disable all			~P*.				
	1: Enable Inte			by SPI0.				
		1 . 1	0	<b>,</b>				

# Figure 10.11. EIE1: Extended Interrupt Enable 1



EXVLD Bit7		R/W EX7	R/W EX6	R/W EX5	R/W EX4	R/W	R/W ET3	Reset Value 00000000
Ditt	Bit6	Bit5	Bit4	Bit3	Bit2	EADC0 Bit1	Bit0	SFR Address 0xE7
Bit7:	EXVLD: Enab This bit sets th 0: Disable all 1: Enable inte	e masking o XTLVLD ir	f the XTLVL nterrupts.	D interrupt.		-		
Bit6:	Reserved. Mu	st Write 0.	Reads 0.					
Bit5:	EX7: Enable E This bit sets th 0: Disable Ext 1: Enable inte	e masking o ternal Interro	f External In 1pt 7.		al Interrupt	7 input pin.		
Bit4:	EX6: Enable E This bit sets th 0: Disable Ext 1: Enable inte	e masking o ternal Interro	f External In 1pt 6.		al Interrupt	6 input pin.		
Bit3:	EX5: Enable E This bit sets th 0: Disable Ext 1: Enable inte	e masking o ternal Interro	f External In 1pt 5.		al Interrupt	5 input pin.		
Bit2:	EX4: Enable E This bit sets th 0: Disable Ext 1: Enable inte	e masking o ternal Interro	f External In 1pt 4.		al Interrupt	4 input pin.		
Bit1:	EADC0: Enab This bit sets th 0: Disable AD 1: Enable inte	e masking o OC0 Convers	f the ADC0 I sion Interrupt	End of Conve	ersion Interr	-		
Bit0:	ET3: Enable T This bit sets th 0: Disable all	e masking o Timer 3 inte	f the Timer 3 errupts.	-	ag (TMR3C	N.7)		

# Figure 10.12. EIE2: Extended Interrupt Enable 2



<b>D</b> (11)	D (11)	D (11)	D (11)	<b>D</b> (11)	D (11)	D (11)	D MI	D
R/W PCP1R	R/W PCP1F	R/W PCP0R	R/W PCP0F	R/W PPCA0	R/W PWADC0	R/W PSMB0	R/W PSPI0	Reset Value 00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
								0xF6
Bit7:	PCP1R: Com	parator 1 (CP	1) Rising In	terrupt Priori	ty Control.			
	This bit sets the				2			
	0: CP1 rising	interrupt set	to low prior	ity level.				
	1: CP1 rising	interrupt set	to high prior	rity level.				
Dive								
Bit6:	PCP1F: Comp				ty Control.			
	This bit sets th 0: CP1 falling	1 2		1				
	1: CP1 falling		1	2				
	1. CI I Iaiiii	g interrupt set	. to high pite					
Bit5:	PCP0R: Com	parator 0 (CP	0) Rising In	terrupt Priori	ty Control.			
	This bit sets th				5			
	0: CP0 rising							
	1: CP0 rising	interrupt set	to high prior	rity level.				
5.4	D (2D ) 2							
Bit4:	PCP0F: Comp				ty Control.			
	This bit sets th 0: CP0 falling	1 2		1				
	1: CP0 falling							
	1. Cronanna	s interrupt set	. to high pite	nity level.				
Bit3:	PPCA0: Progr	rammable Co	unter Array	(PCA0) Inter	rupt Priority	Control.		
	This bit sets the	ne priority of	the PCA0 in	terrupt.				
	0: PCA0 inter							
	1: PCA0 inter	rrupt set to hi	gh priority l	evel.				
Bit2:		DC0 Window	Comporato	r Intormunt Dr	iarity Control	1		
DILZ.	PWADC0: AI This bit sets th					1.		
	0: ADC0 Wit							
	1: ADC0 Win	1		1 2				
			0	r - J				
Bit1:	PSMB0: SME							
	This bit sets the	ne priority of	the SMBus	interrupt.				
	0: SMBus int							
	1: SMBus int	errupt set to l	nigh priority	level.				
Bit0:	PSPI0: Serial	Perinheral In	terface () Int	errunt Priorit	v Control			
Ditto.	This bit sets th				y control.			
	0: SPI0 interr							
	1: SPI0 interr							
		-	-					

# Figure 10.13. EIP1: Extended Interrupt Priority 1



PXVLD	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu
	-	PX7	PX6	PX5	PX4	PADC0	PT3	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Addres 0xF7
Bit7:	PXVLD: Exte This bit sets th 0: XTLVLD i 1: XTLVLD i	ne priority of interrupt set	the XTLVL	D interrupt. ty level.	nterrupt Pric	ority Control.		
Bit6:	Reserved: Mu	st write 0. R	eads 0.					
Bit5:	PX7: External This bit sets th 0: External In 1: External In	ne priority of terrupt 7 set	the External to low priori	Interrupt 7. ty level.				
Bit4:	PX6: External This bit sets th 0: External In 1: External In	ne priority of terrupt 6 set	the External to low priori	Interrupt 6. ty level.				
Bit3:	PX5: External This bit sets th 0: External In 1: External In	ne priority of terrupt 5 set	the External to low priori	Interrupt 5. ty level.				
Bit2:	PX4: External This bit sets th 0: External In 1: External In	ne priority of terrupt 4 set	the External to low priori	Interrupt 4. ty level.				
Bit1:	PADC0: ADC This bit sets th 0: ADC0 End 1: ADC0 End	ne priority of of Conversi	the ADC0 E on interrupt	and of Conversion of Conversio	rsion Interru ority level.	pt.		
Bit0:	PT3: Timer 3 This bit sets th	ne priority of		interrupts.				

# Figure 10.14. EIP2: Extended Interrupt Priority 2



### 10.5. Power Management Modes

The CIP-51 core has two software programmable power management modes: Idle and Stop. Idle mode halts the CPU while leaving the external peripherals and internal clocks active. In Stop mode, the CPU is halted, all interrupts and timers (except the Missing Clock Detector) are inactive, and the system clock is stopped. Since clocks are running in Idle mode, power consumption is dependent upon the system clock frequency and the number of peripherals left in active mode before entering Idle. Stop mode consumes the least power. Figure 10.15 describes the Power Control Register (PCON) used to control the CIP-51's power management modes.

Although the CIP-51 has Idle and Stop modes built in (as with any standard 8051 architecture), power management of the entire MCU is better accomplished by enabling/disabling individual peripherals as needed. Each analog peripheral can be disabled when not in use and put into low power mode. Digital peripherals, such as timers or serial buses, draw little power whenever they are not in use. Turning off the oscillator saves even more power, but requires a reset to restart the MCU.

#### 10.5.1. Idle Mode

Setting the Idle Mode Select bit (PCON.0) causes the CIP-51 to halt the CPU and enter Idle mode as soon as the instruction that sets the bit completes. All internal registers and memory maintain their original data. All analog and digital peripherals can remain active during Idle mode.

Idle mode is terminated when an enabled interrupt or /RST is asserted. The assertion of an enabled interrupt will cause the Idle Mode Selection bit (PCON.0) to be cleared and the CPU will resume operation. The pending interrupt will be serviced and the next instruction to be executed after the return from interrupt (RETI) will be the instruction immediately following the one that set the Idle Mode Select bit. If Idle mode is terminated by an internal or external reset, the CIP-51 performs a normal reset sequence and begins program execution at address 0x0000.

Note: If the instruction following the write of the IDLE bit is a single-byte instruction and an interrupt occurs during the execution phase of the instruction that sets the IDLE bit, the CPU may not wake from Idle mode when a future interrupt occurs. Any instructions that set the IDLE bit should be followed by an instruction that has 2 or more opcode bytes, for example:

// in 'C': PCON  = 0x01; PCON = PCON;	<pre>// set IDLE bit // followed by a 3-cycle dummy instruction</pre>
; in assembly: ORL PCON, #01h MOV PCON, PCON	; set IDLE bit ; followed by a 3-cycle dummy instruction

If enabled, the WDT will eventually cause an internal watchdog reset and thereby terminate the Idle mode. This feature protects the system from an unintended permanent shutdown in the event of an inadvertent write to the PCON register. If this behavior is not desired, the WDT may be disabled by software prior to entering the Idle mode if the WDT was initially configured to allow this operation. This provides the opportunity for additional power savings, allowing the system to remain in the Idle mode indefinitely, waiting for an external stimulus to wake up the system. Refer to Section 13.8 Watchdog Timer for more information on the use and configuration of the WDT.

#### 10.5.2. Stop Mode

Setting the Stop Mode Select bit (PCON.1) causes the CIP-51 to enter Stop mode as soon as the instruction that sets the bit completes. In Stop mode, the CPU and oscillators are stopped, effectively shutting down all digital peripherals. Each analog peripheral must be shut down individually prior to entering Stop Mode. Stop mode can only be terminated by an internal or external reset. On reset, the CIP-51 performs the normal reset sequence and begins program execution at address 0x0000.



If enabled, the Missing Clock Detector will cause an internal reset and thereby terminate the Stop mode. The Missing Clock Detector should be disabled if the CPU is to be put to sleep for longer than the MCD timeout of 100µsec.

### Figure 10.15. PCON: Power Control Register

SMOD Bit7	GF4 Bit6	GF3 Bit5	GF2	GF1	GF0	CTOD	ID I D	
Bit7	Bit6	Rit5			010	STOP	IDLE	00000000
		Dits	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address 0x87
0:	MOD: Serial : Serial Port b : Serial Port b	aud rate is the	hat defined b	y Serial Port				
	F4-GF0: Gen hese are gene			under softwa	re control.			
S	TOP: Stop M etting this bit : Goes into p	will place th				always be rea	d as 0.	
S	DLE: Idle Mo etting this bit : Goes into ic Ports, and A	will place the mode. (S		k to CPU, bu		•		



## **11. FLASH MEMORY**

These devices include 32k + 128 bytes of on-chip, reprogrammable Flash memory for program code and nonvolatile data storage. The Flash memory can be programmed in-system, a single byte at a time, through the JTAG interface or by software using the MOVX instruction. Once cleared to 0, a Flash bit must be erased to set it back to 1. The bytes would typically be erased (set to 0xFF) before being reprogrammed. The write and erase operations are automatically timed by hardware for proper execution. Data polling to determine the end of the write/erase operation is not required. The Flash memory is designed to withstand at least 20,000 write/erase cycles. Refer to Table 11.1 for the electrical characteristics of the Flash memory.

### 11.1. Programming The Flash Memory

The simplest means of programming the Flash memory is through the JTAG interface using programming tools provided by Silicon Labs or a third party vendor. This is the only means for programming a non-initialized device. For details on the JTAG commands to program Flash memory, see Section 21.2.

The Flash memory can be programmed by software using the MOVX instruction with the address and data byte to be programmed provided as normal operands. Before writing to Flash memory using MOVX, Flash write operations must be enabled by setting the PSWE Program Store Write Enable bit (PSCTL.0) to logic 1. Writing to Flash remains enabled until the PSWE bit is cleared by software.

Writes to Flash memory can clear bits but cannot set them. Only an erase operation can set bits in Flash. Therefore, the byte location to be programmed must be erased before a new value can be written. The 32kbyte Flash memory is organized in 512-byte sectors. The erase operation applies to an entire sector (setting all bytes in the sector to 0xFF). Setting the PSEE Program Store Erase Enable bit (PSCTL.1) and PSWE (PSCTL.0) bit to logic 1 and then using the MOVX command to write a data byte to any byte location within the sector will erase an entire 512-byte sector. The data byte written can be of any value because it is not actually written to the Flash. Flash erasure remains enabled until the PSEE bit is cleared by software. The following sequence illustrates the algorithm for programming the Flash memory by software:

- 1. Enable Flash Memory write/erase in FLSCL Register using FLASCL bits.
- 2. Set PSEE (PSCTL.1) to enable Flash sector erase.
- 3. Set PSWE (PSCTL.0) to enable Flash writes.
- 4. Use MOVX to write a data byte to any location within the 512-byte sector to be erased.
- 5. Clear PSEE to disable Flash sector erase.
- 6. Use MOVX to write a data byte to the desired byte location within the erased 512-byte sector. Repeat until finished. (Any number of bytes can be written from a single byte to and entire sector.)
- 7. Clear the PSWE bit to disable Flash writes.

Write/Erase timing is automatically controlled by hardware based on the prescaler value held in the Flash Memory Timing Prescaler register (FLSCL). The 4-bit prescaler value FLASCL determines the time interval for write/erase operations. The FLASCL value required for a given system clock is shown in Figure 11.4, along with the formula used to derive the FLASCL values. When FLASCL is set to 1111b, the write/erase operations are disabled. Note that code execution in the 8051 is stalled while the Flash is being programmed or erased.

### Table 11.1. FLASH Memory Electrical Characteristics

VDD = 2.7 to 3.6V,  $-40^{\circ}C$  to  $+85^{\circ}C$  unless otherwise specified.

PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
Endurance		20k	100k		Erase/Wr
Erase Cycle Time		10			ms
Write Cycle Time		40			μs



### **11.2.** Non-volatile Data Storage

The Flash memory can be used for non-volatile data storage as well as program code. This allows data such as calibration coefficients to be calculated and stored at run time. Data is written using the MOVX instruction and read using the MOVC instruction.

The MCU incorporates an additional 128-byte sector of Flash memory located at 0x8000 – 0x807F. This sector can be used for program code or data storage. However, its smaller sector size makes it particularly well suited as general purpose, non-volatile scratchpad memory. Even though Flash memory can be written a single byte at a time, an entire sector must be erased first. In order to change a single byte of a multi-byte data set, the data must be moved to temporary storage. Next, the sector is erased, the data set updated and the data set returned to the original sector. The 128-byte sector-size facilitates updating data without wasting program memory space by allowing the use of internal data RAM for temporary storage. (A normal 512-byte sector is too large to be stored in the 256-byte internal data memory.)

#### 11.3. Security Options

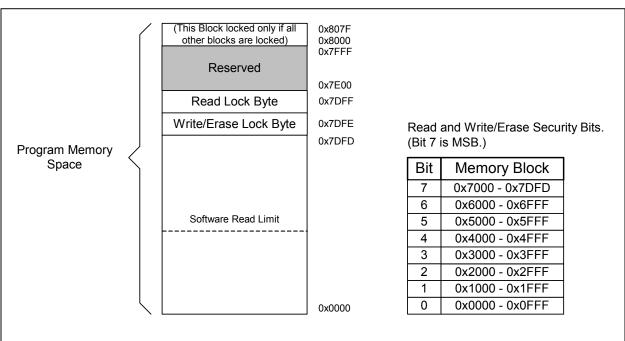
The CIP-51 provides security options to protect the Flash memory from inadvertent modification by software as well as prevent the viewing of proprietary program code and constants. The Program Store Write Enable (PSCTL.0) and the Program Store Erase Enable (PSCTL.1) bits protect the Flash memory from accidental modification by software. These bits must be explicitly set to logic 1 before software can modify the Flash memory. Additional security features prevent proprietary program code and data constants from being read or altered across the JTAG interface or by software running on the system controller.

A set of security lock bytes stored at 0x7DFE and 0x7DFF protect the Flash program memory from being read or altered across the JTAG interface. Each bit in a security lock-byte protects one 4kbyte block of memory. Clearing a bit to logic 0 in a Read lock byte prevents the corresponding block of Flash memory from being read across the JTAG interface. Clearing a bit in the Write/Erase lock byte protects the block from JTAG erasures and/or writes. The Read lock byte is at location 0x7DFF. The Write/Erase lock byte is located at 0x7DFE. Figure 11.2 shows the location and bit definitions of the security bytes. The 512-byte sector containing the lock bytes can be written to, but not erased by software. Writing to the reserved area should not be performed.

Figure 11.1.	<b>PSCTL:</b>	Program	Store	RW	Control
1 15 al 0 11010		11051000			Control

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value			
-	-	-	-	-	-	PSEE	PSWE	00000000			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address			
								0x8F			
Bits7-2	: UNUSED. Re	ad = 000000	b, Write = d	on't care.							
D'.1	DODE D	<b>a</b> . <b>b</b>	F 11								
Bit1:	PSEE: Program										
	Setting this bit										
	the PSWE bit i										
	instruction wil					dressed by the	e MOVX				
	instruction. Th				not matter.						
	0: Flash progra	-									
	1: Flash progra	am memory	erasure enabl	ed.							
Bit0:	PSWE: Progra	m Store Wri	ite Enable								
	0			data to the Fl	ash program	memory usin	og the				
21101	Setting this bit allows writing a byte of data to the Flash program memory using the MOVX instruction. The location must be erased before writing data.										
5110.		tion The la	negtion must l	he eraced het	ore writing	ata					
21001	MOVX instruc				ore writing d	lata.					
21001	MOVX instruction 0: Write to Fla	sh program	memory disa	bled.	ore writing d	lata.					
2	MOVX instruc	sh program	memory disa	bled.	ore writing d	lata.					
	MOVX instruction 0: Write to Fla	sh program	memory disa	bled.	ore writing d	lata.					





### Figure 11.2. Flash Program Memory Security Bytes

### FLASH Read Lock Byte

Bits7-0: Each bit locks a corresponding block of memory. (Bit 7 is MSB.)

0: Read operations are locked (disabled) for corresponding block across the JTAG interface.

1: Read operations are unlocked (enabled) for corresponding block across the JTAG interface.

#### FLASH Write/Erase Lock Byte

Bits7-0: Each bit locks a corresponding block of memory.

0: Write/Erase operations are locked (disabled) for corresponding block across the JTAG interface. 1: Write/Erase operations are unlocked (enabled) for corresponding block across the JTAG interface.

#### FLASH Access Limit Register (FLACL)

The content of this register is used as the high byte of the 16-bit software read limit address. The 16bit read limit address value is calculated as 0xNN00 where NN is replaced by the contents of this register. Software running at or above this address is prohibited from using the MOVX or MOVC instructions to read, write, or erase, locations below this address. Any attempts to read locations below this limit will return the value 0x00.

The lock bits can always be read and cleared to logic 0 regardless of the security setting applied to the block containing the security bytes. This allows additional blocks to be protected after the block containing the security bytes has been locked. However, the only means of removing a lock once set is to erase the entire program memory space by performing a JTAG erase operation (i.e. cannot be done in user firmware). NOTE: Addressing either security byte while performing a JTAG erase operation will automatically initiate erasure of the entire program memory space (except for the reserved area). This erasure can only be performed via JTAG. If a non-security byte in the 0x7C00-0x7DFF page is addressed during erasure, only that page (including the security bytes) will be erased.

The Flash Access Limit security feature (see Figure 11.3) protects proprietary program code and data from being read by software running on the C8051F005/06/07/15/16/17 MCUs. This feature provides support for OEMs that wish to program the MCU with proprietary value-added firmware before distribution. The value-added firmware can be protected while allowing additional code to be programmed in remaining program memory space later.



The Software Read Limit (SRL) is a 16-bit address that establishes two logical partitions in the program memory space. The first is an upper partition consisting of all the program memory locations at or above the SRL address, and the second is a lower partition consisting of all the program memory locations starting at 0x0000 up to (but excluding) the SRL address. Software in the upper partition can execute code in the lower partition, but is prohibited from reading locations in the lower partition using the MOVC instruction. (Executing a MOVC instruction from the upper partition with a source address in the lower partition will always return a data value of 0x00.) Software running in the lower partition can access locations in both the upper and lower partition without restriction.

The Value-added firmware should be placed in the lower partition. On reset, control is passed to the value-added firmware via the reset vector. Once the value-added firmware completes its initial execution, it branches to a predetermined location in the upper partition. If entry points are published, software running in the upper partition may execute program code in the lower partition, but it cannot read the contents of the lower partition. Parameters may be passed to the program code running in the lower partition either through the typical method of placing them on the stack or in registers before the call or by placing them in prescribed memory locations in the upper partition.

The SRL address is specified using the contents of the Flash Access Register. The 16-bit SRL address is calculated as 0xNN00, where NN is the contents of the SRL Security Register. Thus, the SRL can be located on 256-byte boundaries anywhere in program memory space. However, the 512-byte erase sector size essentially requires that a 512 boundary be used. The contents of a non-initialized SRL security byte is 0x00, thereby setting the SRL address to 0x0000 and allowing read access to all locations in program memory space by default.

Figure 11.3	. FLACL: Flash Access	Limit (C8051F005/06/07/15/16/1	17 only)
-------------	-----------------------	--------------------------------	----------

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	D:41	Bit0	00000000 SFR Address:			
BII/	Bit7 Bit6 Bit5 Bit4 Bit3 Bit2 Bit1 Bit0 SFR Address: 0xB7										
T a r r	LACL: Flash This register h ddress. The c eplaced by co egister can o until the next	olds the high entire 16-bit ntents of FL. <b>nly be writt</b>	byte of the access limit a ACL. A write	address value te to this regi	is calculated ster sets the F	as 0xNN00 Flash Access	where NN i Limit. <b>Thi</b>	S			



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu
FOSE	FRAE	-	-		FLA	SCL		1000111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Addres 0xB6
Bit7:	FOSE: Flash C	ne-Shot Tir	ner Enable					
	0: Flash One-s							
	1: Flash One-s							
	FRAE: Flash R							
	0: Flash reads							
	1: Flash alway							
	UNUSED. Re							
	FLASCL: Flas					• • •		
	This register sp							
	correct timing			ations. If th	e prescaler is	set to 1111b	, Flash	
	write/erase ope							
	0000: System (							
	0001: 50kHz ≤	-						
	0010: 100kHz	•						
	0011: 200kHz	2						
	0100: 400kHz	•						
	0101: 800kHz	2						
	0110: 1.6MHz	•						
	0111: 3.2MHz							
	1000: 6.4MHz	•						
	1001: 12.8MH							
	1010: 25.6MH							
	1011, 1100, 11							
	1111: Flash M	emory Write	e/Erase Disab	led				
	The prescaler v				ne following	equation:		
]	FLASCL > log	22(System C	lock / 50kHz)					
:	* For test purp	oses. The C	C8051F000 fai	nily is not g	uaranteed for	operation or	ver 25MHz.	

# Figure 11.4. FLSCL: Flash Memory Timing Prescaler



## 12. EXTERNAL RAM (C8051F005/06/07/15/16/17)

The C8051F005/06/07/15/16/17 MCUs include 2048 bytes of RAM mapped into the external data memory space. All of these address locations may be accessed using the external move instruction (MOVX) and the data pointer (DPTR), or using MOVX indirect addressing mode. If the MOVX instruction is used with an 8-bit address operand (such as @R1), then the high byte of the 16-bit address is provided by the External Memory Interface Control Register (EMI0CN as shown in Figure 12.1). Note: the MOVX instruction is also used for writes to the Flash memory. See Section 11 for details. The MOVX instruction accesses XRAM by default (i.e. PSTCL.0 = 0).

For any of the addressing modes the upper 5-bits of the 16-bit external data memory address word are "don't cares". As a result, the 2048-byte RAM is mapped modulo style over the entire 64k external data memory address range. For example, the XRAM byte at address 0x0000 is also at address 0x0800, 0x1000, 0x1800, 0x2000, etc. This is a useful feature when doing a linear memory fill, as the address pointer doesn't have to be reset when reaching the RAM block boundary.

R	R	R	R	R	R/W	R/W	R/W	Reset Value
-	-	-	-	-	PGSEL2	PGSEL1	PGSEL0	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
								0xAF
Bits 2-0:]	Not Used – rea PGSEL[2:0]: 7 The XRAM P address when RAM. The up over the entire 000: xxxxx00 001: xxxxx00 001: xxxxx01 011: xxxxx10 100: xxxxx10 101: xxxxx10 110: xxxxx11	XRAM Page age Select Bi using an 8-b oper 5-bits are 64k externa 0b 1b 0b 1b 0b 1b 0b	its provide th it MOVX cou e "don't care	mmand, effec s", so the 2k	tively selecti address bloc	ing a 256-byt	e page of	

### Figure 12.1. EMI0CN: External Memory Interface Control



## **13. RESET SOURCES**

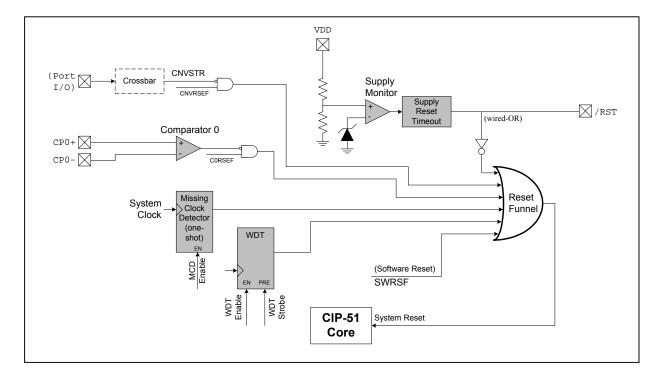
The reset circuitry of the MCUs allows the controller to be easily placed in a predefined default condition. On entry to this reset state, the CIP-51 halts program execution, forces the external port pins to a known state and initializes the SFRs to their defined reset values. Interrupts and timers are disabled. On exit, the program counter (PC) is reset, and program execution starts at location 0x0000.

All of the SFRs are reset to predefined values. The reset values of the SFR bits are defined in the SFR detailed descriptions. The contents of internal data memory are not changed during a reset and any previously stored data is preserved. However, since the stack pointer SFR is reset, the stack is effectively lost even though the data on the stack are not altered.

The I/O port latches are reset to 0xFF (all logic ones), activating internal weak pull-ups which take the external I/O pins to a high state. The weak pull-ups are enabled during and after the reset. If the source of reset is from the VDD Monitor or writing a 1 to PORSF, the /RST pin is driven low until the end of the VDD reset timeout.

On exit from the reset state, the MCU uses the internal oscillator running at 2MHz as the system clock by default. Refer to Section 14 for information on selecting and configuring the system clock source. The Watchdog Timer is enabled using its longest timeout interval. (Section 13.8 details the use of the Watchdog Timer.)

There are seven sources for putting the MCU into the reset state: power-on/power-fail, external /RST pin, external CNVSTR signal, software commanded, Comparator 0, Missing Clock Detector, and Watchdog Timer. Each reset source is described below:







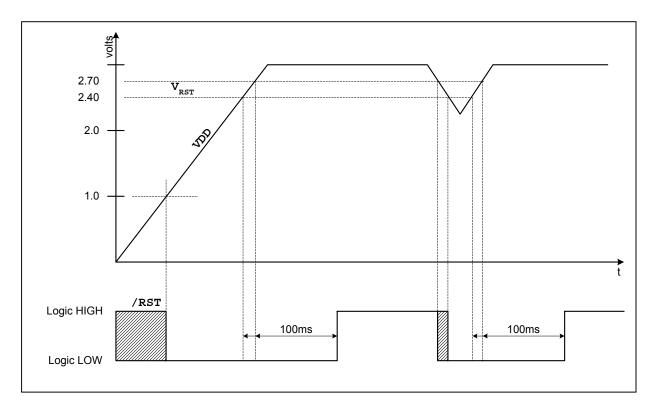
### 13.1. Power-on Reset

The C8051F000 family incorporates a power supply monitor that holds the MCU in the reset state until VDD rises above the  $V_{RST}$  level during power-up. (See Figure 13.2 for timing diagram, and refer to Table 13.1 for the Electrical Characteristics of the power supply monitor circuit.) The /RST pin is asserted (low) until the end of the 100ms VDD Monitor timeout in order to allow the VDD supply to become stable.

On exit from a power-on reset, the PORSF flag (RSTSRC.1) is set by hardware to logic 1. All of the other reset flags in the RSTSRC Register are indeterminate. PORSF is cleared by a reset from any other source. Since all resets cause program execution to begin at the same location (0x0000), software can read the PORSF flag to determine if a power-up was the cause of reset. The content of internal data memory should be assumed to be undefined after a power-on reset.

### **13.2.** Software Forced Reset

Writing a 1 to the PORSF bit forces a Power-On Reset as described in Section 13.1.



## Figure 13.2. VDD Monitor Timing Diagram

### 13.3. Power-fail Reset

When a power-down transition or power irregularity causes VDD to drop below  $V_{RST}$ , the power supply monitor will drive the /RST pin low and return the CIP-51 to the reset state (see Figure 13.2). When VDD returns to a level above  $V_{RST}$ , the CIP-51 will leave the reset state in the same manner as that for the power-on reset. Note that even though internal data memory contents are not altered by the power-fail reset, it is impossible to determine if VDD dropped below the level required for data retention. If the PORSF flag is set, the data may no longer be valid.



### 13.4. External Reset

The external /RST pin provides a means for external circuitry to force the MCU into a reset state. Asserting an active-low signal on the /RST pin will cause the MCU to enter the reset state. Although there is a weak internal pullup, it may be desirable to provide an external pull-up and/or decoupling of the /RST pin to avoid erroneous noise-induced resets. The MCU will remain in reset until at least 12 clock cycles after the active-low /RST signal is removed. The PINRSF flag (RSTSRC.0) is set on exit from an external reset. The /RST pin is also 5V tolerant.

### 13.5. Missing Clock Detector Reset

The Missing Clock Detector is essentially a one-shot circuit that is triggered by the MCU system clock. If the system clock goes away for more than  $100\mu$ s, the one-shot will time out and generate a reset. After a Missing Clock Detector reset, the MCDRSF flag (RSTSRC.2) will be set, signifying the MSD as the reset source; otherwise, this bit reads 0. The state of the /RST pin is unaffected by this reset. Setting the MSCLKE bit in the OSCICN register (see Figure 14.2) enables the Missing Clock Detector.

#### 13.6. Comparator 0 Reset

Comparator 0 can be configured as an active-low reset input by writing a 1 to the CORSEF flag (RSTSRC.5). Comparator 0 should be enabled using CPT0CN.7 (see Figure 8.3) at least 20µs prior to writing to CORSEF to prevent any turn-on chatter on the output from generating an unwanted reset. When configured as a reset, if the non-inverting input voltage (on CP0+) is less than the inverting input voltage (on CP0-), the MCU is put into the reset state. After a Comparator 0 Reset, the CORSEF flag (RSTSRC.5) will read 1 signifying Comparator 0 as the reset source; otherwise, this bit reads 0. The state of the /RST pin is unaffected by this reset. Also, Comparator 0 can generate a reset with or without the system clock.

### 13.7. External CNVSTR Pin Reset

The external CNVSTR signal can be configured as an active-low reset input by writing a 1 to the CNVRSEF flag (RSTSRC.6). The CNVSTR signal can appear on any of the P0, P1, or P2 I/O pins as described in Section 15.1. (Note that the Crossbar must be configured for the CNVSTR signal to be routed to the appropriate Port I/O.) The Crossbar should be configured and enabled before the CNVRSEF is set to configure CNVSTR as a reset source. When configured as a reset, CNVSTR is active-low and level sensitive. After a CNVSTR reset, the CNVRSEF flag (RSTSRC.6) will read 1 signifying CNVSTR as the reset source; otherwise, this bit reads 0. The state of the /RST pin is unaffected by this reset.

#### 13.8. Watchdog Timer Reset

The MCU includes a programmable Watchdog Timer (WDT) running off the system clock. The WDT will force the MCU into the reset state when the watchdog timer overflows. To prevent the reset, the WDT must be restarted by application software before the overflow occurs. If the system experiences a software/hardware malfunction preventing the software from restarting the WDT, the WDT will overflow and cause a reset. This should prevent the system from running out of control.

The WDT is automatically enabled and started with the default maximum time interval on exit from all resets. If desired the WDT can be disabled by system software or locked on to prevent accidental disabling. Once locked, the WDT cannot be disabled until the next system reset. The state of the /RST pin is unaffected by this reset.



#### 13.8.1. Watchdog Usage

The WDT consists of a 21-bit timer running from the programmed system clock. The timer measures the period between specific writes to its control register. If this period exceeds the programmed limit, a WDT reset is generated. The WDT can be enabled and disabled as needed in software, or can be permanently enabled if desired. Watchdog features are controlled via the Watchdog Timer Control Register (WDTCN) shown in Figure 13.3.

#### Enable/Reset WDT

The watchdog timer is both enabled and the countdown restarted by writing 0xA5 to the WDTCN register. The user's application software should include periodic writes of 0xA5 to WDTCN as needed to prevent a watchdog timer overflow. The WDT is enabled and restarted as a result of any system reset.

#### **Disable WDT**

Writing 0xDE followed by 0xAD to the WDTCN register disables the WDT. The following code segment illustrates disabling the WDT.

CLR EA ; disable all interrupts MOV WDTCN,#0DEh ; disable software MOV WDTCN,#0ADh ; watchdog timer SETB EA ; re-enable interrupts

The writes of 0xDE and 0xAD must occur within 4 clock cycles of each other, or the disable operation is ignored. Interrupts should be disabled during this procedure to avoid delay between the two writes.

#### **Disable WDT Lockout**

Writing 0xFF to WDTCN locks out the disable feature. Once locked out, the disable operation is ignored until the next system reset. Writing 0xFF does not enable or reset the watchdog timer. Applications always intending to use the watchdog should write 0xFF to WDTCN in their initialization code.

#### Setting WDT Interval

WDTCN.[2:0] control the watchdog timeout interval. The interval is given by the following equation:

 $4^{3+WDTCN[2:0]} \times T_{SYSCLK}$ , (where  $T_{SYSCLK}$  is the system clock period).

For a 2MHz system clock, this provides an interval range of 0.032msec to 524msec. WDTCN.7 must be a 0 when setting this interval. Reading WDTCN returns the programmed interval. WDTCN.[2:0] is 111b after a system reset.

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
								0xFF
Bits7-0	: WDT Control							
	Writing 0xA5	both enables	and reloads	the WDT.				
	Writing 0xDE	followed with	thin 4 clocks	by 0xAD dis	ables the WI	DT.		
	Writing 0xFF			2				
Bit4:	Watchdog Sta							
2.00	Reading the W	· · · · · · · · · · · · · · · · · · ·	/	he Watchdog	Timer Status	2		
	0: WDT is ina		it indicates th	ne watendog	Timer Status			
	1: WDT is act							
D:4-2.0			1 D:4a					
Bits2-0	: Watchdog Tin			<b>T</b> ' <b>I</b>	. 1 1171	•.• .1		
	The WDTCN.			og Timeout In	terval. When	n writing the	se bits,	
	WDTCN.7 mt	ist be set to 0						

Figure 13.3. WDTCN: Watchdog Timer Control Register



R	R/W	R/W	R/W	R	R	R/W	R	Reset Value				
JTAGRS		CORSEF	SWRSEF	WDTRSF	MCDRSF	PORSF	PINRSF	XXXXXXXX				
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xEF				
								UXEF				
	-											
(Note:	Do not use read	-modify-wri	te operations	on this regis	ter.)							
D												
Bit7:	JTAGRST. JT											
	0: JTAG is no		n reset state.									
D:46	1: JTAG is in		Dagat Carros	Enchle and i	Flag							
Bit6:	CNVRSEF: Convert Start Reset Source Enable and Flag Write											
	0: CNVSTR i	a mot a react										
				)								
	1: CNVSTR i Read	s a reset sou	ice (active to	w)								
	0: Source of p	rior reset wa	s not from (	NVSTR								
	1: Source of p											
Bit5:	CORSEF: Con											
Dito.	Write	ipulutor o R		na i nag								
	0: Comparato	r 0 is not a re	eset source									
	1: Comparato			ve low)								
	Read											
	Note: The valu	e read from	CORSEF is 1	not defined if	Comparator	0 has not bee	en enabled as					
	a reset source.				I							
	0: Source of p	prior reset wa	is not from C	Comparator 0								
	1: Source of p											
Bit4:	SWRSF: Softw			-								
	Write			-								
	0: No Effect											
	1: Forces an i	nternal reset.	/RST pin is	not effected								
	Read											
	0: Prior reset											
	1: Prior reset				oit.							
Bit3:	WDTRSF: Wa											
	0: Source of p											
D'/0	1: Source of p											
Bit2:	MCDRSF: Mi	•		0	Detector							
	0: Source of p			U								
Bit1:	1: Source of p PORSF: Powe				lector timeou	ι.						
DIUI.	Write	I-OII Keset I	force and Fia	ıg								
	0: No effect											
	1: Forces a Po	wer-On Res	et /RST is a	lriven low								
	Read											
	0: Source of p	rior reset wa	is not from P	OR								
	1: Source of p											
Bit0:	PINRSF: HW			-								
	0: Source of p			RST pin.								
	1: Source of p											
	Г		-									

# Figure 13.4. RSTSRC: Reset Source Register



-40°C to +85°C unless otherw	-40°C to +85°C unless otherwise specified.									
PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS					
/RST Output Low Voltage	$I_{OL} = 8.5 \text{mA}, \text{VDD} = 2.7 \text{ to } 3.6 \text{V}$			0.6	V					
/RST Input High Voltage		0.7 x			V					
		VDD								
/RST Input Low Voltage				0.3 x	V					
				VDD						
/RST Input Leakage Current	/RST = 0.0V		20		μΑ					
VDD for /RST Output Valid		1.0			V					
AV+ for /RST Output Valid		1.0			V					
VDD POR Threshold ( $V_{RST}$ )		2.40	2.55	2.70	V					
Reset Time Delay	/RST rising edge after crossing reset	80	100	120	ms					
	threshold									
Missing Clock Detector	Time from last system clock to reset	100	220	500	μs					
Timeout	generation									

## Table 13.1. Reset Electrical Characteristics



## 14. OSCILLATOR

Each MCU includes an internal oscillator and an external oscillator drive circuit, either of which can generate the system clock. The MCUs boot from the internal oscillator after any reset. The internal oscillator starts up instantly. It can be enabled/disabled and its frequency can be changed using the Internal Oscillator Control Register (OSCICN) as shown in Figure 14.2. The internal oscillator's electrical specifications are given in Table 14.1.

Both oscillators are disabled when the /RST pin is held low. The MCUs can run from the internal oscillator or external oscillator, and switch between the two at will using the CLKSL bit in the OSCICN Register. The external oscillator requires an external resonator, parallel-mode crystal, capacitor, or RC network connected to the XTAL1/XTAL2 pins (see Figure 14.1). The oscillator circuit must be configured for one of these sources in the OSCXCN register. An external CMOS clock can also provide the system clock via overdriving the XTAL1 pin. The XTAL1 and XTAL2 pins are 3.6V (not 5V) tolerant. The external oscillator can be left enabled and running even when the MCU has switched to using the internal oscillator.

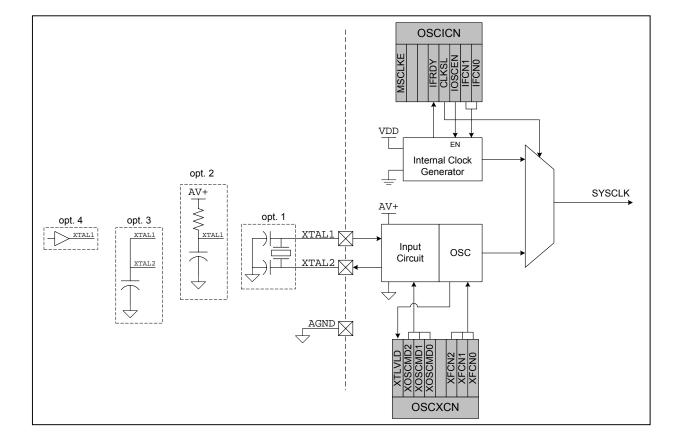


Figure 14.1. Oscillator Diagram



R/W MSCLKE	R/W	R/W	R IFRDY	R/W CLKSL	R/W IOSCEN	R/W IFCN1	R/W IFCN0	Reset Value 00000100				
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:				
								0xB2				
Bit7: M	SCLKE: Miss	sing Clock E	nable Bit									
0: Missing Clock Detector Disabled												
1: Missing Clock Detector Enabled; triggers a reset if a missing clock is detected												
Bits6-5: U	Bits6-5: UNUSED. Read = 00b, Write = don't care											
Bit4: IF												
	0: Internal Oscillator Frequency not running at speed specified by the IFCN bits.											
	Internal Osci				cified by the I	FCN bits.						
	LKSL: Systen											
	Uses Interna											
	Uses Externa		2	ock.								
	OSCEN: Interr											
•••	Internal Osci											
	Internal Osci											
	CN1-0: Intern		1 2									
	): Internal Os											
	1: Internal Os											
	): Internal Os											
1	1: Internal Os	cinator typic	a frequency	IS TOWINZ.								

# Figure 14.2. OSCICN: Internal Oscillator Control Register

-40°C to +85°C unless otherwise specified.								
PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS			
Internal Oscillator	OSCICN.[1:0] = 00	1.5	2	2.4	MHz			
Frequency	OSCICN.[1:0] = 01	3.1	4	4.8				
	OSCICN.[1:0] = 10	6.2	8	9.6				
	OSCICN.[1:0] = 11	12.3	16	19.2				
Internal Oscillator Current	OSCICN.2 = 1		200		μA			
Consumption (from VDD)					-			
Internal Oscillator			4		ppm/°C			
Temperature Stability								
Internal Oscillator Power			6.4		%/V			
Supply (VDD) Stability								



Figure 14.3.	OSCXCN:	External	Oscillator	Control	Register
--------------	---------	----------	------------	---------	----------

	R/	W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
XTLVL	D XOSC	CMD2	XOSCMD1	XOSCMD0	-	XFCN2	XFCN1	XFCN0	00110000
Bit7	Bi	t6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address
									0xB1
Bit7:	XTLVLD	: Cryst	tal Oscillator	Valid Flag					
			en XOSCMI						
				ed or not yet					
					e (should rea	d 1ms after (	Crystal Oscilla	ator is	
			oid transien						
Bits6-4:				llator Mode I					
				unded internation		TALL			
				ternal CMOS ternal CMOS			wided by 2		
				with divide b		TALT pin u	vided by 2.		
			cillator Mode		y 2 stage.				
				e with divide	hv 2 stage				
Bit3:				ned, Write $=$					
				or Frequency		5			
	000-111:			-1					
	XFCN	Crys	tal (XOSCM	D = R	C (XOSCM	D = 10x)	C (XOSCMI	O = 10x	
		11x)							
	000	$f \le 12$	2.5kHz	f	≤ 25kHz		K Factor $= 0$		
	001	12.51	$Hz < f \le 30$	).3kHz 2	$5 \text{kHz} < f \le$	50kHz	K Factor = 1		
	010	$30.35 \text{kHz} < f \le 93.8 \text{kHz}$		93.8kHz 5	$50 \text{kHz} \le f \le 100 \text{kHz}$		K Factor $= 4.4$		
	011	$93.8 \text{kHz} < f \le 267 \text{kHz}$		7kHz 1	$100 \text{kHz} < f \le 200 \text{kHz}$		K Factor $= 1$		
	100	267k	$Hz < f \le 72$	2kHz 2	$00 \text{kHz} < \text{f} \le$	400kHz	K Factor = 38		
	101	722k	$Hz < f \le 2.2$	23MHz 4	$00 \text{kHz} < \text{f} \le$	800kHz	K Factor $= 1$	00	
	110	2.231	$MHz < f \le 6$	.74MHz 8	$00 \text{kHz} < \text{f} \le$	1.6MHz	K Factor $= 4$	20	
		f > 6	.74MHz	1	$.6MHz < f \le$	3.2MHz	K Factor = 1	400	
	111								
	111	I							
CRYST	AL MOD	E (Cire		gure 14.1, Op					
CRYST	AL MOD	E (Cire		gure 14.1, Op h the crystal					
	AL MOD Choose X	E (Ciro FCN v	value to mate	h the crystal	or ceramic r	esonator freq			
	CAL MOD Choose X DDE (Circu	E (Ciro FCN v iit from	ralue to mate	h the crystal o	or ceramic r	esonator freq			
	Choose X DDE (Circu Choose os	E (Ciro FCN v it from	ralue to matc n Figure 14.1 on frequency	h the crystal , Option 2; X range where	or ceramic r	esonator freq			
	<b>CAL MOD</b> Choose X <b>DE</b> (Circu Choose of f = 1.23(1)	E (Ciro FCN v it from scillatio 0 <sup>3</sup> ) / (1	ralue to mate n Figure 14.1 on frequency <b>R * C)</b> , wher	h the crystal o , Option 2; X range where e	or ceramic r	esonator freq			
	<b>CAL MOD</b> Choose X <b>DE</b> (Circu Choose of f = 1.23(1) f = freque	E (Ciro FCN v it from scillatio <b>0<sup>3</sup>) / (1</b> ncy of	ralue to matc n Figure 14.1 on frequency <b>R * C)</b> , wher r oscillation i	h the crystal o , Option 2; X range where e	or ceramic r	esonator freq			
	<b>AL MOD</b> Choose X <b>DE</b> (Circu Choose or f = 1.23(1) f = freque C = capac	E (Ciro FCN v it from scillatio 0 <sup>3</sup> ) / (I ncy of itor va	ralue to matc n Figure 14.1 on frequency <b>R * C)</b> , wher oscillation i lue in pF	h the crystal o , Option 2; X v range where e n MHz	or ceramic r	esonator freq			
	<b>AL MOD</b> Choose X <b>DE</b> (Circu Choose or f = 1.23(1) f = freque C = capac	E (Ciro FCN v it from scillatio 0 <sup>3</sup> ) / (I ncy of itor va	ralue to matc n Figure 14.1 on frequency <b>R * C)</b> , wher r oscillation i	h the crystal o , Option 2; X v range where e n MHz	or ceramic r	esonator freq			
RC MO	<b>AL MOD</b> Choose X <b>DE</b> (Circu Choose of f = 1.23(1 f = freque C = capac R = Pull-t	E (Ciro FCN v it from scillatio <b>0<sup>3</sup>) / (I</b> ncy of itor va up resis	ralue to matc a Figure 14.1 on frequency <b>R * C)</b> , wher oscillation i lue in pF stor value in	h the crystal o , Option 2; X range where e n MHz kΩ	or ceramic r COSCMD =	esonator freq			
RC MO	<b>AL MOD</b> Choose X <b>DE</b> (Circu Choose or $\mathbf{f} = 1.23(1$ $\mathbf{f} = \text{freque}$ $\mathbf{C} = \text{capac}$ $\mathbf{R} = \text{Pull-tr}$ <b>E</b> (Circuit	E (Circ FCN v it from scillatio <b>0<sup>3</sup>) / (I</b> ncy of itor va ıp resis from I	ralue to matc a Figure 14.1 on frequency <b>R</b> * <b>C</b> ), wher oscillation i lue in pF stor value in Figure 14.1,	h the crystal o , Option 2; X y range where e n MHz kΩ Option 3; XO	or ceramic r COSCMD = :: PSCMD = 10	esonator freq 10x) 0x)			
RC MO	<b>AL MOD</b> Choose X <b>DE</b> (Circu Choose or $\mathbf{f} = 1.23(1$ $\mathbf{f} = \text{freque}$ $\mathbf{C} = \text{capac}$ $\mathbf{R} = \text{Pull} \cdot 1$ <b>DE</b> (Circuit Choose K	E (Cira FCN v iit from scillatio <b>0<sup>3</sup>) / (I</b> ncy of itor va ip resis from I Factor	ralue to matc a Figure 14.1 on frequency <b>R</b> * <b>C</b> ), wher oscillation i lue in pF stor value in Figure 14.1, r (KF) for th	h the crystal o , Option 2; X range where e n MHz kΩ	or ceramic r COSCMD = :: PSCMD = 10	esonator freq 10x) 0x)			
RC MO	<b>CAL MOD</b> Choose X <b>DE</b> (Circu Choose or $\mathbf{f} = 1.23(1$ $\mathbf{f} = \text{freque}$ $\mathbf{C} = \text{capac}$ $\mathbf{R} = \text{Pull-t}$ <b>DE</b> (Circuit Choose K $\mathbf{f} = \mathbf{KF} / (\mathbf{C} + \mathbf{KF})$	E (Cire FCN v iit from scillatio 0 <sup>3</sup> ) / (I ncy of itor va ip resis from I Factor C * A	ralue to matc a Figure 14.1 on frequency <b>R</b> * <b>C</b> ), wher coscillation i lue in pF stor value in Figure 14.1, r (KF) for th <b>V+</b> ), where	h the crystal o , Option 2; X range where e n MHz kΩ Option 3; XO e oscillation f	or ceramic r COSCMD = :: PSCMD = 10	esonator freq 10x) 0x)			
RC MO	<b>AL MOD</b> Choose X <b>DE</b> (Circu Choose or f = 1.23(1) f = freque C = capac R = Pull-toE (CircuitChoose K $f = KF / (f = freque$	E (Cire FCN v iit from scillation 0 <sup>3</sup> ) / (I ney of itor va ip resist from I Factor C * A ney of	alue to matc a Figure 14.1 on frequency <b>R</b> * <b>C</b> ), wher oscillation i lue in pF stor value in Figure 14.1, r (KF) for th V+), where oscillation i	h the crystal o , Option 2; X range where e n MHz kΩ Option 3; XO e oscillation f n MHz	or ceramic r COSCMD = :: DSCMD = 10 frequency de	esonator freq 10x) 0x)			
RC MO	<b>AL MOD</b> Choose X <b>DE</b> (Circu Choose or $\mathbf{f} = 1.23(1$ $\mathbf{f} = \mathbf{f}$ reque $\mathbf{C} = \mathbf{c}$ apac $\mathbf{R} = \mathbf{Pull} + \mathbf{r}$ <b>E</b> (Circuit Choose K $\mathbf{f} = \mathbf{K} \mathbf{F} / (\mathbf{f}$ $\mathbf{f} = \mathbf{f}$ reque $\mathbf{C} = \mathbf{c}$ apac	E (Circ FCN v iit from scillation $0^3$ ) / (1 ncy of iitor va up resist from I Factor C * AV ncy of iitor va	ralue to match n Figure 14.1 on frequency <b>R * C)</b> , wher oscillation i lue in pF stor value in Figure 14.1, f r (KF) for th V+), where oscillation i lue on XTA	h the crystal o , Option 2; X v range where e n MHz kΩ Option 3; XO e oscillation f n MHz L1, XTAL2 p	or ceramic r COSCMD = :: OSCMD = 10 frequency do pins in pF	esonator freq 10x) 0x)			
RC MO	<b>AL MOD</b> Choose X <b>DE</b> (Circu Choose or $\mathbf{f} = 1.23(1$ $\mathbf{f} = \mathbf{f}$ reque $\mathbf{C} = \mathbf{c}$ apac $\mathbf{R} = \mathbf{Pull} + \mathbf{r}$ <b>E</b> (Circuit Choose K $\mathbf{f} = \mathbf{K} \mathbf{F} / (\mathbf{f}$ $\mathbf{f} = \mathbf{f}$ reque $\mathbf{C} = \mathbf{c}$ apac	E (Circ FCN v iit from scillation $0^3$ ) / (1 ncy of iitor va up resist from I Factor C * AV ncy of iitor va	ralue to match n Figure 14.1 on frequency <b>R * C)</b> , wher oscillation i lue in pF stor value in Figure 14.1, f r (KF) for th V+), where oscillation i lue on XTA	h the crystal o , Option 2; X range where e n MHz kΩ Option 3; XO e oscillation f n MHz	or ceramic r COSCMD = :: OSCMD = 10 frequency do pins in pF	esonator freq 10x) 0x)			



### 14.1. External Crystal Example

If a crystal or ceramic resonator were used to generate the system clock for the MCU, the circuit would be as shown in Figure 14.1, Option 1. For an ECS-110.5-20-4 crystal, the resonate frequency is 11.0592MHz, the intrinsic capacitance is 7pF, and the ESR is  $60\Omega$ . The compensation capacitors should be 33pF each, and the PWB parasitic capacitance is estimated to be 2pF. The appropriate External Oscillator Frequency Control value (XFCN) from the Crystal column in the table in Figure 14.3 (OSCXCN Register) should be 111b.

Because the oscillator detect circuitry needs time to settle after the crystal oscillator is enabled, software should wait at least 1ms between enabling the crystal oscillator and polling the XTLVLD bit. The recommend procedure is:

- 1. Enable the external oscillator
- 2. Wait at least 1 ms
- 3. Poll for XTLVLD '0' ==> '1'
- 4. Switch to the external oscillator

Switching to the external oscillator before the crystal oscillator has stabilized could result in unpredictable behavior.

NOTE: Crystal oscillator circuits are quite sensitive to PCB layout. The crystal should be placed as close as possible to the XTAL pins on the device, keeping the traces as short as possible and shielded with ground plane from any other traces which could introduce noise or interference.

### 14.2. External RC Example

If an external RC network were used to generate the system clock for the MCU, the circuit would be as shown in Figure 14.1, Option 2. The capacitor must be no greater than 100pF, but using a very small capacitor will increase the frequency drift due to the PWB parasitic capacitance. To determine the required External Oscillator Frequency Control value (XFCN) in the OSCXCN Register, first select the RC network value to produce the desired frequency of oscillation. If the frequency desired is 100kHz, let R = 246k $\Omega$  and C = 50pF:

 $f = 1.23(10^3)/RC = 1.23(10^3) / [246 * 50] = 0.1MHz = 100kHz$ 

$$\begin{split} & XFCN \geq \log_2(f/25kHz) \\ & XFCN \geq \log_2(100kHz/25kHz) = \log_2(4) \\ & XFCN \geq 2, \text{ or code } 010 \end{split}$$

#### 14.3. External Capacitor Example

If an external capacitor were used to generate the system clock for the MCU, the circuit would be as shown in Figure 14.1, Option 3. The capacitor must be no greater than 100pF, but using a very small capacitor will increase the frequency inaccuracy due to the PWB parasitic capacitance. To determine the required External Oscillator Frequency Control value (XFCN) in the OSCXCN Register, select the capacitor to be used and find the frequency of oscillation from the equations below. Assume AV + = 3.0V and C = 50pF:

f = KF / (C \* VDD) = KF / (50 \* 3)f = KF / 150

If a frequency of roughly 90kHz is desired, select the K Factor from the table in Figure 14.3 as KF = 13:

f = 13 / 150 = 0.087 MHz, or 87 kHz

Therefore, the XFCN value to use in this example is 011.



## **15. PORT INPUT/OUTPUT**

The MCUs have a wide array of digital resources, which are available through four digital I/O ports, P0, P1, P2 and P3. Each of the pins on Ports 0, 1, and 2 can be defined as either its corresponding port I/O or one of the internal digital resources assigned as shown in Figure 15.1. The designer has complete control over which functions are assigned, limited only by the number of physical I/O pins available on the selected package (the C8051F000/05/10/15 have all four ports pinned out, the F001/06/11/16 have P0 and P1, and the F002/07/12/17 have P0). This resource assignment flexibility is achieved through the use of a Priority CrossBar Decoder. (Note that the state of a Port I/O pin can always be read in the corresponding Port latch regardless of the Crossbar settings).

The CrossBar assigns the selected internal digital resources to the I/O pins based on the Priority Decode Table 15.1. The registers XBR0, XBR1, and XBR2, defined in Figure 15.3, Figure 15.4, and Figure 15.5 are used to select an internal digital function or let an I/O pin default to being a Port I/O. The crossbar functions identically for each MCU, with the caveat that P2 is not pinned out on the F001/06/11/16, and both P1 and P2 are not pinned out on the F002/07/12/17. Digital resources assigned to port pins that are not pinned out cannot be accessed.

All Port I/Os are 5V tolerant (Refer to Figure 15.2 for the port cell circuit.) The Port I/O cells are configured as either push-pull or open-drain in the Port Configuration Registers (PRT0CF, PRT1CF, PRT2CF, PRT3CF). Complete Electrical Specifications for Port I/O are given in Table 15.2.

### 15.1. Priority Cross Bar Decoder

One of the design goals of this MCU family was to make the entire palette of digital resources available to the designer even on reduced pin count packages. The Priority CrossBar Decoder provides an elegant solution to the problem of connecting the internal digital resources to the physical I/O pins.

The Priority CrossBar Decode (Table 15.1) assigns a priority to each I/O function, starting at the top with the SMBus. As the table illustrates, when selected, its two signals will be assigned to Pin 0 and 1 of I/O Port 0. The decoder always fills I/O bits from LSB to MSB starting with Port 0, then Port 1, finishing if necessary with Port 2. If you choose not to use a resource, the next function down on the table will fill the priority slot. In this way it is possible to choose only the functions required by the design, making full use of the available I/O pins. Also, any extra Port I/O are grouped together for more convenient use in application code.

Registers XBR0, XBR1 and XBR2 are used to assign the digital I/O resources to the physical I/O Port pins. It is important to understand that when the SMBus, SPI Bus, or UART is selected, the crossbar assigns all pins associated with the selected bus. It would be impossible for instance to assign the RX pin from the UART function without also assigning the TX function. Standard Port I/Os appear contiguously after the prioritized functions have been assigned. For example, if you choose functions that take the first 14 Port I/O (P0.[7:0], P1.[5:0]), you would have 18 Port I/O left unused by the crossbar (P1.[7:6], P2 and P3).

#### **15.2.** Port I/O Initialization

Port I/O initialization is straightforward. Registers XBR0, XBR1 and XBR2 must be loaded with the appropriate values to select the digital I/O functions required by the design. Setting the XBARE bit in XBR2 to 1 enables the CrossBar. **Until the Crossbar is enabled, the external pins remain as standard Ports in input mode regardless of the XBRn Register settings.** For given XBRn Register settings, one can determine the I/O pin-out using the Priority Decode Table; as an alternative, the Code Configuration Wizard function of the IDE software will determine the Port I/O pin-assignments based on the XBRn Register settings.

The output driver characteristics of the I/O pins are defined using the Port Configuration Registers PRT0CF, PRT1CF, PRT2CF and PRT3CF (see Figure 15.7, Figure 15.9, Figure 15.12, and Figure 15.14). Each Port Output driver can be configured as either Open Drain or Push-Pull. This is required even for the digital resources selected in the XBRn registers and is not automatic. The only exception to this is the SMBus (SDA, SCL) and UART Receive (RX, when in mode 0) pins which are Open-drain regardless of the PRTnCF settings. When the WEAKPUD bit in XBR2 is 0, a weak pullup is enabled for all Port I/O configured as open-drain. WEAKPUD does



not affect the push-pull Port I/O. Furthermore, the weak pullup is turned off on an open-drain output that is driving a 0 to avoid unnecessary power dissipation.

The third and final step is to initialize the individual resources selected using the appropriate setup registers. Initialization procedures for the various digital resources may be found in the detailed explanation of each available function. The reset state of each register is shown in the figures that describe each individual register.

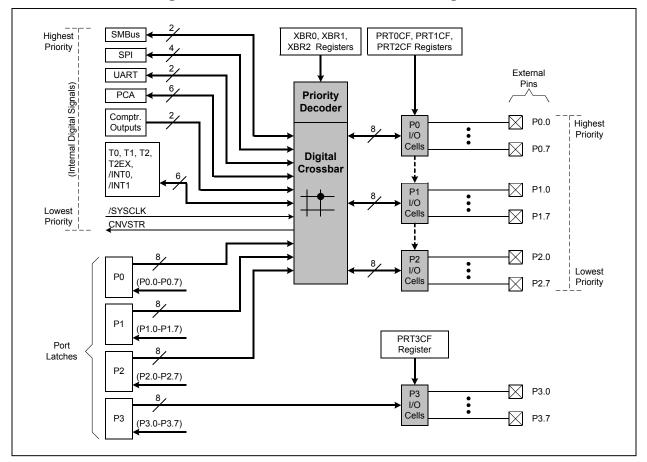
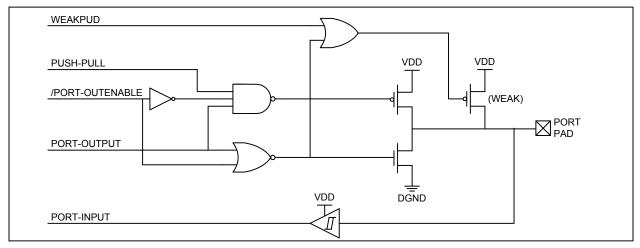




Figure 15.2. Port I/O Cell Block Diagram





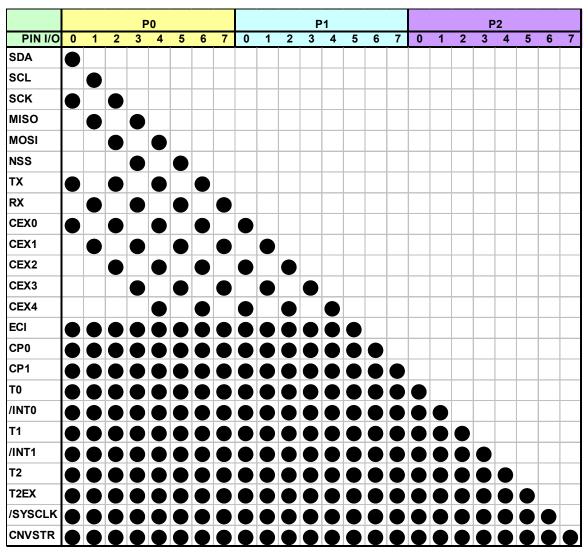


 Table 15.1. Crossbar Priority Decode

In the Priority Decode Table, a dot ( $\bullet$ ) is used to show the external Port I/O pin (column) to which each signal (row) can be assigned by the user application code via programming registers XBR2, XBR1, and XBR0.



DAV	D/IV	DAV	D /IV	D /IV	D /IV	D /IV	D/W	D (1/1
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value 0000000
CP0OEN Bit7	ECIE Bit6	D:45	PCA0ME Bit4	Bit3	UARTEN Bit2	SPI0OEN Bit1	SMB0OEN Bit0	SFR Address:
Bit/	Bilo	Bit5	B114	BIG	BIIZ	BILI	Bito	0xE1
								UALI
D:47.	CDOOEN: Cor		Destaurst Excepted	D:4				
Bit7:		-	Dutput Enable	ы				
	0: CP0 unava		1					
D'16	1: CP0 routed							
Bit6:	ECIE: PCA0 (	1						
	0: ECI unavai		1					
D'4 2 5	1: ECI routed							
Bits3-5:	PCA0ME: PC							
			able at Port pi	ns.				
	001: CEX0 rc							
			to 2 Port Pins					
	,	· · · ·	2 routed to 3 Po		<b>.</b> .			
			2, CEX3 routed					
		,	2, CEX3, CEX	4 routed to	5 Port Pins.			
	110: RESERV							
D:40	111: RESERV		1.1. D'4					
Bit2:	UARTEN: UA							
	0: UART I/O		1					
D'(1	1: RX, TX ro							
Bit1:	SPIOOEN: SP							
	0: SPI I/O una		1	( ( D ( D				
<b>D</b> .	· · · ·		nd NSS routed	to 4 Port P	ins.			
Bit0:	SMB0OEN: S							
			e at P0.0, P0.1.					
	1: SDA route	d to P0.0, S	CL routed to P	0.1.				

# Figure 15.3. XBR0: Port I/O CrossBar Register 0



<b>D</b> (11)	5 (1)	D (11)	D (11)	D (11)	D (11)	D (11)	D (11)	D
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
SYSCKE		T2E	INT1E	T1E	INT0E	TOE	CP10EN	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xE2
								UXE2
Bit7:	SYSCKE: SYS							
	0: SYSCLK u							
	1: SYSCLK of	1						
Bit6:	T2EXE: T2EX							
	0: T2EX unav		1					
	1: T2EX route		n.					
Bit5:	T2E: T2 Enabl							
	0: T2 unavaila		oin.					
	1: T2 routed to							
Bit4:	INT1E: /INT1							
	0: /INT1 unav		1					
	1: /INT1 route		n.					
Bit3:	T1E: T1 Enabl							
	0: T1 unavaila		oin.					
	1: T1 routed to							
Bit2:	INT0E: /INT0							
	0: /INT0 unav		1					
	1: /INT0 route		n.					
Bit1:	T0E: T0 Enabl							
	0: T0 unavaila		oin.					
	1: T0 routed to							
Bit0:	CP1OEN: Con			Bit				
	0: CP1 unavai		1					
	1: CP1 routed	to Port Pin.						

# Figure 15.4. XBR1: Port I/O CrossBar Register 1



R/W WEAKPUD Bit7	R/W XBARE Bit6	R/W - Bit5	R/W - Bit4	R/W - Bit3	R/W - Bit2	R/W - Bit1	R/W CNVSTE Bit0	Reset Value 00000000 SFR Address:
0 Bit6: X 0 1 Bits5-1: U Bit0: C	VEAKPUD: F : Weak Pull- : Weak Pull- : Crossbar D : Crossbar E : Crossbar E : NUSED. Re : NVSTE: AD	ups Enabled ups Disablec sbar Enable isabled nabled ad = 00000t C Convert S	(except for F d Bit o, Write = dor tart Input End	Ports whose I n't care.	/O are confi	gured as pusl	n-pull)	0xE3
1 <u>Example U</u> When sele Table 15. through P	: CNVSTR u : CNVSTR re <u>Usage of XBR</u> ected, the dig 1) starting w 2.7. If the dig internal Port F	outed to Por <u>(0, XBR1, X</u> ital resource ith P0.0 thr gital resource	t Pin. BR2: s fill the Por ough P0.7, a ses are not m	and then P1	.0 through	P1.7, and fin	nally P2.0	
P0.0=SDA Example2	: If XBR0 = 0 A, P0.1=SCL, : If XBR0 = 0 , P0.1=/INT0,	P0.2=CEX0 0x80, XBR1	P = 0x04, and	$1, P0.4 \dots P2$ XBR2 = 0x4	.7 map to cc 1:			

# Figure 15.5. XBR2: Port I/O CrossBar Register 2



### 15.3. General Purpose Port I/O

Each MCU has four byte-wide, bi-directional parallel ports that can be used general purpose I/O. Each port is accessed through a corresponding special function register (SFR) that is both byte addressable and bit addressable. When writing to a port, the value written to the SFR is latched to maintain the output data value at each pin. When reading, the logic levels of the port's input pins are returned regardless of the XBRn settings (i.e. even when the pin is assigned to another signal by the Crossbar, the Port Register can always still read its corresponding Port I/O pin). The exception to this is the execution of the *read-modify-write* instructions. The *read-modify-write* instructions when operating on a port SFR are the following: ANL, ORL, XRL, JBC, CPL, INC, DEC, DJNZ and MOV, CLR or SET, when the destination is an individual bit in a port SFR. For these instructions, the value of the port register (not the pin) is read, modified, and written back to the SFR.

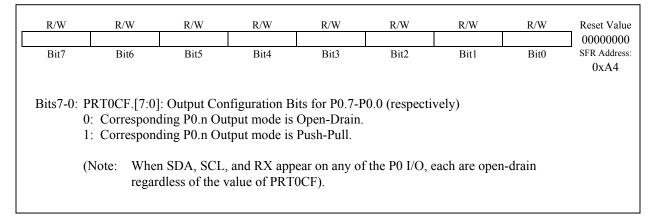
### 15.4. Configuring Ports Which are not Pinned Out

P2 and P3 are not pinned out on the F001/06/11/16. P1, P2, and P3 are not pinned out on the F002/07/12/17. These port registers (and corresponding interrupts, where applicable) are still available for software use in these reduced pin count MCUs. Whether used or not in software, it is recommended not to let these port drivers go to high impedance state. This is prevented after reset by having the weak pull-ups enabled as described in the XBR2 register. It is recommended that each output driver for ports not pinned out should be configured as push-pull using the corresponding PRTnCF register. This will inhibit a high impedance state even if the weak pull-up is disabled.

R/W P0.7	R/W P0.6	R/W P0.5	R/W P0.4	R/W P0.3	R/W P0.2	R/W P0.1	R/W P0.0	Reset Value 11111111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (bit addressable)	SFR Address: 0x80
	Write – Output : Logic Low : Logic High	Output. Output (hig dless of XBI logic low.	h-impedance	if correspon	R1, and XBR2 ding PRT0CI gister settings	F.n bit = $0$ )		

### Figure 15.6. P0: Port0 Register



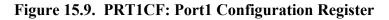


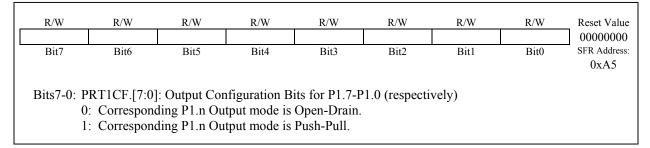


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R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
P1.7	P1.6	P1.5	P1.4	P1.3	P1.2	P1.1	P1.0	11111111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
							(bit addressable)	0x90
0 1 (. 0	Write – Outpu : Logic Low : Logic High Read – Regar : P1.n pin is : P1.n pin is	Output. Output (hig dless of XBI logic low.	h-impedance	if correspon	ding PRT1CI	F.n  bit = 0)		

### Figure 15.8. P1: Port1 Register





### Figure 15.10. PRT1IF: Port1 Interrupt Flag Register

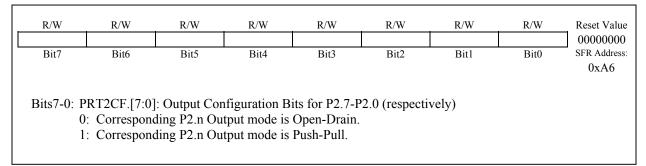
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
IE7	IE6	IE5	IE4	-	-	-	-	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xAD
Bit7:	IE7: External 1 0: No falling of 1: This flag is	edge detected	l on P1.7.	falling edge o	on P1.7 is det	ected.		
Bit6:	IE6: External 1 0: No falling of 1: This flag is	edge detected	l on P1.6.	alling edge o	on P1.6 is det	ected.		
Bit5:	IE5: External 1 0: No falling of 1: This flag is	edge detected	l on P1.5.	falling edge o	on P1.5 is det	ected.		
Bit4:	IE4: External 1 0: No falling o 1: This flag is	edge detected	l on P1.4.	falling edge o	on P1.4 is det	ected.		
Bits3-0	: UNUSED. Re	ead = 0000b,	Write = don <sup>3</sup>	't care.				



R/W P2.7 Bit7	R/W P2.6 Bit6	R/W P2.5 Bit	R/W P2.4 Bit4	R/W P2.3 Bit3	R/W P2.2 Bit2	R/W P2.1 Bit1	R/W P2.0 Bit0 (bit addressable)	Reset Value 11111111 SFR Address: 0xA0
0 1 (. 0	2.[7:0] Write – Outpo : Logic Low : Logic High Read – Regar : P2.n is logi : P2.n is logi	Output. Output (high dless of XBF ic low.	h-impedance	if correspond	ding PRT2CI	F.n bit = $0$ )		

Figure 15.11. P2: Port2 Register



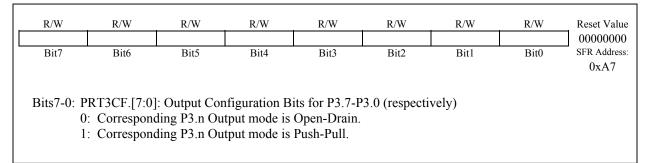




R/W P3.7	R/W P3.6	R/W P3.5	R/W P3.4	R/W P3.3	R/W P3.2	R/W P3.1	R/W P3.0	Reset Value 11111111
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
							(bit addressable)	0xB0
	P3.[7:0] Write) E Logic Low Logic High Read) P3.n is logi P3.n is logi	Output (hig	h-impedance	if correspond	ding PRT3CI	F.n bit = 0)		

### Figure 15.13. P3: Port3 Register





### Table 15.2. Port I/O DC Electrical Characteristics

VDD = 2.7 to 3.6V, -40°C to +85°C unless otherwise specified.

PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
Output High Voltage	$I_{OH} = -10uA$ , Port I/O push-pull	VDD –			V
		0.1			
	$I_{OH}$ = -3mA, Port I/O push-pull	VDD –			
		0.7			
	$I_{OH} = -10 mA$ , Port I/O push-pull		VDD –		
			0.8		
Output Low Voltage	$I_{OL} = 10uA$			0.1	V
	$I_{OL} = 8.5 \text{mA}$			0.6	
	$I_{OL} = 25 \text{mA}$		1.0		
Input High Voltage		0.7 x			V
		VDD			
Input Low Voltage				0.3 x	V
				VDD	
Input Leakage Current	DGND < Port Pin < VDD, Pin Tri-state				μA
	Weak Pull-up Off			±1	
	Weak Pull-up On		30		
Capacitive Loading			5		pF



### 16. SMBus / I2C Bus

The SMBus serial I/O interface is compliant with the System Management Bus Specification, version 1.1. It is a two-wire, bi-directional serial bus, which is also compatible with the  $I^2C$  serial bus. Reads and writes to the interface by the system controller are byte oriented with the SMBus interface autonomously controlling the serial transfer of the data. Data can be transferred at up to  $1/8^{th}$  of the system clock if desired (this can be faster than allowed by the SMBus specification, depending on the system clock used). A method of extending the clock-low duration is used to accommodate devices with different speed capabilities on the same bus.

Two types of data transfers are possible: data transfers from a master transmitter to an addressed slave receiver, and data transfers from an addressed slave transmitter to a master receiver. The master device initiates both types of data transfers and provides the serial clock pulses. The SMBus interface may operate as a master or a slave. Multiple master devices on the same bus are also supported. If two or more masters attempt to initiate a data transfer simultaneously, an arbitration scheme is employed with a single master always winning the arbitration.

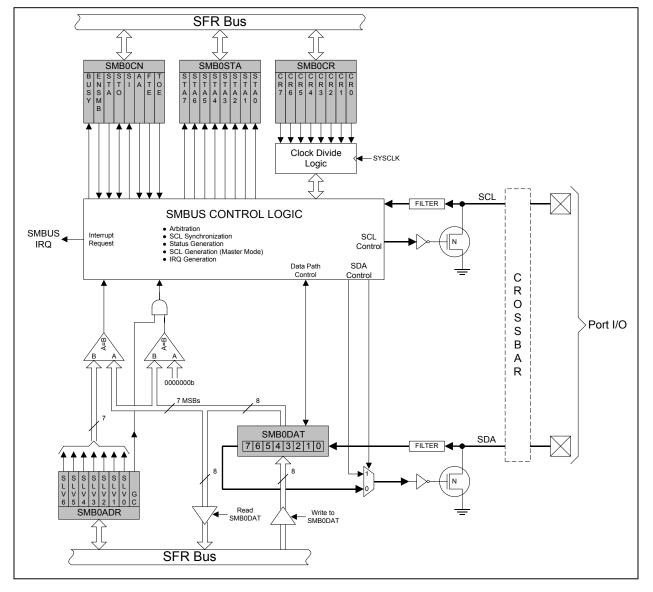
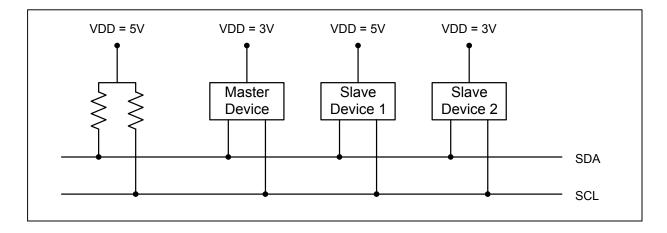


Figure 16.1. SMBus Block Diagram



Figure 16.2 shows a typical SMBus configuration. The SMBus interface will work at any voltage between 3.0V and 5.0V and different devices on the bus may operate at different voltage levels. The SCL (serial clock) and SDA (serial data) lines are bi-directional. They must be connected to a positive power supply voltage through a pull-up resistor or similar circuit. When the bus is free, both lines are pulled high. Every device connected to the bus must have an open-drain or open-collector output for both the SCL and SDA lines. The maximum number of devices on the bus is limited only by the requirement that the rise and fall times on the bus will not exceed 300ns and 1000ns, respectively.





### 16.1. Supporting Documents

It is assumed the reader is familiar with or has access to the following supporting documents:

- 1. The  $l^2C$ -bus and how to use it (including specifications), Philips Semiconductor.
- 2. *The I<sup>2</sup>C-Bus Specification -- Version 2.0*, Philips Semiconductor.
- 3. System Management Bus Specification -- Version 1.1, SBS Implementers Forum.



### 16.2. Operation

A typical SMBus transaction consists of a START condition, followed by an address byte, one or more bytes of data, and a STOP condition. The address byte and each of the data bytes are followed by an ACKNOWLEDGE bit from the receiver. The address byte consists of a 7-bit address plus a direction bit. The direction bit (R/W) occupies the least-significant bit position of the address. The direction bit is set to logic 1 to indicate a "READ" operation and cleared to logic 0 to indicate a "WRITE" operation. A general call address (0x00 +R/W) is recognized by all slave devices allowing a master to address multiple slave devices simultaneously.

All transactions are initiated by the master, with one or more addressed slave devices as the target. The master generates the START condition and then transmits the address and direction bit. If the transaction is a WRITE operation from the master to the slave, the master transmits the data a byte at a time waiting for an ACKNOWLEDGE from the slave at the end of each byte. If it is a READ operation, the slave transmits the data waiting for an ACKNOWLEDGE from the master at the end of each byte. At the end of the data transfer, the master generates a STOP condition to terminate the transaction and free the bus. Figure 16.3 illustrates a typical SMBus transaction.

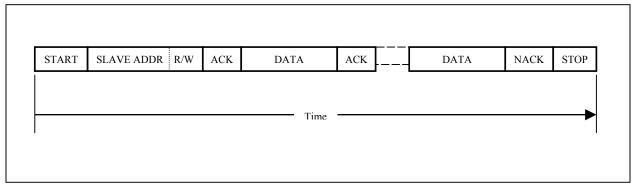


Figure 16.3. SMBus Transaction

The SMBus interface may be configured to operate as either a master or a slave. At any particular time, it will be operating in one of the following four modes:

#### 16.2.1. Master Transmitter Mode

Serial data is transmitted on SDA while the serial clock is output on SCL. The first byte transmitted contains the address of the target slave device and the data direction bit. In this case the data direction bit (R/W) will be logic 0 to indicate a "WRITE" operation. The master then transmits one or more bytes of serial data. After each byte is transmitted, an acknowledge bit is generated by the slave. To indicate the beginning and the end of the serial transfer, the master device outputs START and STOP conditions.

#### 16.2.2. Master Receiver Mode

Serial data is received on SDA while the serial clock is output on SCL. The first byte is transmitted by the master and contains the address of the target slave and the data direction bit. In this case the data direction bit (R/W) will be logic 1 to indicate a "READ" operation. Serial data is then received from the slave on SDA while the master outputs the serial clock. The slave transmits one or more bytes of serial data. After each byte is received, an acknowledge bit is transmitted by the master. The master outputs START and STOP conditions to indicate the beginning and end of the serial transfer.

#### 16.2.3. Slave Transmitter Mode

Serial data is transmitted on SDA while the serial clock is received on SCL. First, a byte is received that contains an address and data direction bit. In this case the data direction bit (R/W) will be logic 1 to indicate a "READ" operation. If the received address matches the slave's assigned address (or a general call address is received) one or more bytes of serial data are transmitted to the master. After each byte is received, an acknowledge bit is transmitted by the master. The master outputs START and STOP conditions to indicate the beginning and end of the serial transfer.



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#### 16.2.4. Slave Receiver Mode

Serial data is received on SDA while the serial clock is received on SCL. First, a byte is received that contains an address and data direction bit. In this case the data direction bit (R/W) will be logic 0 to indicate a "WRITE" operation. If the received address matches the slave's assigned address (or a general call address is received) one or more bytes of serial data are received from the master. After each byte is received, an acknowledge bit is transmitted by the slave. The master outputs START and STOP conditions to indicate the beginning and end of the serial transfer.

#### 16.3. Arbitration

A master may start a transfer only if the bus is free. The bus is free after a STOP condition or after the SCL and SDA lines remains high for a specified time. Two or more master devices may attempt to generate a START condition at the same time. Since the devices that generated the START condition may not be aware that other masters are contending for the bus, an arbitration scheme is employed. The master devices continue to transmit until one of the masters transmits a HIGH level, while the other(s) master transmits a LOW level on SDA. The first master(s) transmitting the HIGH level on SDA looses the arbitration and is required to give up the bus.

#### 16.4. Clock Low Extension

SMBus provides a clock synchronization mechanism, similar to I2C, which allows devices with different speed capabilities to coexist on the bus. A clock-low extension is used during a transfer in order to allow slower slave devices to communicate with faster masters. The slave can hold the SCL line LOW to extend the clock low period, effectively decreasing the serial clock frequency.

#### 16.5. Timeouts

#### 16.5.1. SCL Low Timeout

If the SCL line is held low by a slave device on the bus, no further communication is possible. Furthermore, the master cannot force the SCL line high to correct the error condition. To solve this problem, the SMBus protocol specifies that devices participating in a transfer must detect any clock cycle held low longer than 25ms as a "timeout" condition. Devices that have detected the timeout condition must reset the communication no later than 10ms after detecting the timeout condition.

One of the MCU's general-purpose timers, operating in 16-bit auto-reload mode, can be used to monitor the SCL line for this timeout condition. Timer 3 is specifically designed for this purpose. (Refer to the Timer 3 Section 19.3. for detailed information on Timer 3 operation.)

#### 16.5.2. SCL High (SMBus Free) Timeout

The SMBus specification stipulates that if a device holds the SCL and SDA lines high for more that 50usec, the bus is designated as free. The SMB0CR register is used to detect this condition when the FTE bit in SMB0CN is set.

#### 16.6. SMBus Special Function Registers

The SMBus serial interface is accessed and controlled through five SFRs: SMB0CN Control Register, SMB0CR Clock Rate Register, SMB0ADR Address Register, SMB0DAT Data Register and SMB0STA Status Register. The system device may have one or more SMBus serial interfaces implemented. The five special function registers related to the operation of the SMBus interface are described in the following section.



#### 16.6.1. Control Register

The SMBus Control register SMB0CN is used to configure and control the SMBus interface. All of the bits in the register can be read or written by software. Two of the control bits are also affected by the SMBus hardware. The Serial Interrupt flag (SI, SMB0CN.3) is set to logic 1 by the hardware when a valid serial interrupt condition occurs. It can only be cleared by software. The Stop flag (STO, SMB0CN.4) is cleared to logic 0 by hardware when a STOP condition is present on the bus.

Setting the ENSMB flag to logic 1 enables the SMBus interface. Clearing the ENSMB flag to logic 0 disables the SMBus interface and removes it from the bus. Momentarily clearing the ENSMB flag and then resetting it to logic 1 will reset a SMBus communication. However, ENSMB should not be used to temporarily remove a device from the bus since the bus state information will be lost. Instead, the Assert Acknowledge (AA) flag should be used to temporarily remove the device from the bus (see description of AA flag below).

Setting the Start flag (STA, SMB0CN.5) to logic 1 will put the SMBus in a master mode. If the bus is free, the SMBus hardware will generate a START condition. If the bus is not free, the SMBus hardware waits for a STOP condition to free the bus and then generates a START condition after a 5 $\mu$ s delay per the SMB0CR value. (In accordance with the SMBus protocol, the SMBus interface also considers the bus free if the bus is idle for 50 $\mu$ s and no STOP condition was recognized.) If STA is set to logic 1 while the SMBus is in master mode and one or more bytes have been transferred, a repeated START condition will be generated. To ensure proper operation, the STO flag should be explicitly cleared before setting STA to a logic 1.

When the Stop flag (STO, SMB0CN.4) is set to logic 1 while the SMBus interface is in master mode, the hardware generates a STOP condition on the SMBus. In a slave mode, the STO flag may be used to recover from an error condition. In this case, a STOP condition is not generated on the SMBus, but the SMBus hardware behaves as if a STOP condition has been received and enters the "not addressed" slave receiver mode. The SMBus hardware automatically clears the STO flag to logic 0 when a STOP condition is detected on the bus.

The Serial Interrupt flag (SI, SMB0CN.3) is set to logic 1 by hardware when the SMBus interface enters one of 27 possible states. If interrupts are enabled for the SMBus interface, an interrupt request is generated when the SI flag is set. The SI flag must be cleared by software. While SI is set to logic 1, the clock-low period of the serial clock will be stretched and the serial transfer is suspended.

The Assert Acknowledge flag (AA, SMB0CN.2) is used to set the level of the SDA line during the acknowledge clock cycle on the SCL line. Setting the AA flag to logic 1 will cause an ACKNOWLEDGE (low level on SDA) to be sent during the acknowledge cycle if the device has been addressed. Setting the AA flag to logic 0 will cause a NOT ACKNOWLEDGE (high level on SDA) to be sent during acknowledge cycle. After the transmission of a byte in slave mode, the slave can be temporarily removed from the bus by clearing the AA flag. The slave's own address and general call address will be ignored. To resume operation on the bus, the AA flag must be reset to logic 1 to allow the slave's address to be recognized.

Setting the SMBus Free Timer Enable bit (FTE, SMB0CN.1) to logic 1 enables the SMBus Free Timeout feature. If SCL and SDA remain high for the SMBus Free Timeout given in the SMBus Clock Rate Register (Figure 16.5), the bus will be considered free and a Start will be generated if pending. The bus free period should be greater than 50µs.

Setting the SMBus timeout enable bit (TOE, SMB0CN.0) to logic 1 enables Timer 3 to count up when the SCL line is low and Timer 3 is enabled. If Timer 3 overflows, a Timer 3 interrupt will be generated, which will alert the CPU that a SMBus SCL low timeout has occurred.



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R	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu
BUSY	ENSMB	STA	STO	SI	AA	FTE	TOE	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (bit addressable)	SFR Address 0xC0
Bit7:	BUSY: Busy S 0: SMBus is fro							
	1: SMBus is bu							
Bit6:	ENSMB: SMB							
	This bit enable	s/disables th	ne SMBus sei	rial interface.				
	0: SMBus disa							
	1: SMBus enab							
Bit5:	STA: SMBus S							
	0: No START 1: When operation			T condition	is transmitted	l if the bus is	free (If the	
	bus is not free,							
	or more bytes h							
	START condit							
	logic 1.						C	
Bit4:	STO: SMBus S	1 0						
	0: No STOP co							
	1: Setting STO							
	condition is rec							
	STOP conditio STO flag cause						ue, setting the	
Bit3:	SI: SMBus Ser				untion was re	ccivcu.		
BR5.	This bit is set b			27 possible	SMBus states	s is entered.	(Status code	
	0xF8 does not							
	the CPU to vec							
	cleared by hard	lware and m	nust be cleare	d by softwar	e.		-	
Bit2:	AA: SMBus A							
	This bit defines	s the type of	f acknowledg	e returned du	uring the ack	nowledge cy	cle on the	
	SCL line.	1 1 2 4						
	0: A "not ackne							
Bit1:	1: An "acknow FTE: SMBus F	•		A) is returne	a during the a	acknowledge	e cycle.	
DILI.	0: No timeout							
	1: Timeout wh			ds limit snec	ified by the S	MB0CR val	ue	
Bit0:	TOE: SMBus T			us mint spee				
	0: No timeout							



### 16.6.2. Clock Rate Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address 0xCF
, 1 , ,	SMB0CR.[7:0 The SMB0CR node. The 8 The timer cour The SMB0CR unsigned 8-bit Hz:	Clock Rate -bit word sto nts up, and w setting shou value in reg	register cont bred in the S when it rolls o ld be bounde ister SMB0C	rols the frequ MB0CR Reg over to 0x00, ed by the follo	ister preload the SCL logic owing equation <i>LK</i> is the system	s a dedicated c state toggle on, where <i>SM</i> tem clock fre	d 8-bit timer es. <i>1B0CR</i> is the	
	The resulting	•	-	times are give SMB0CR) / S	-	owing equati	ions:	
		$T_{HIGH} \cong$	(258 – SMB)	OCR) / SYSCI	LK + 625  ns			
	Using the sam following equation		MB0CR from	n above, the E	Bus Free Time	eout period is	s given in th	e
		$T_{BFT} \cong l$	0 * [(256 – S	SMB0CR) + 1	] / SYSCLK			

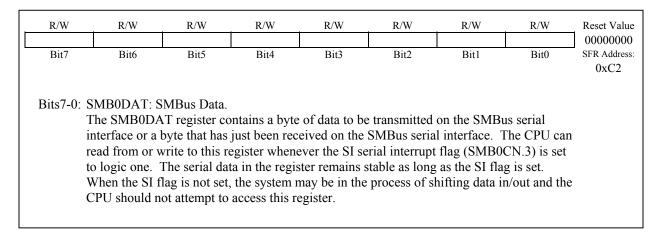


#### 16.6.3. Data Register

The SMBus Data register SMB0DAT holds a byte of serial data to be transmitted or one that has just been received. Data remains stable in the register as long as SI is set to logic 1. Software can safely read or write to the data register when the SI flag is set. Software should not attempt to access the SMB0DAT register when the SMBus is enabled and the SI flag is cleared to logic 0 since the hardware may be in the process of shifting a byte of data in or out of the register.

Data in SMB0DAT is always shifted out MSB first. After a byte has been received, the first bit of received data is located at the MSB of SMB0DAT. While data is being shifted out, data on the bus is simultaneously being shifted in. Therefore, SMB0DAT always contains the last data byte present on the bus. Thus, in the event of lost arbitration, the transition from master transmitter to slave receiver is made with the correct data in SMB0DAT.

#### Figure 16.6. SMB0DAT: SMBus Data Register



#### 16.6.4. Address Register

The SMB0ADR Address register holds the slave address for the SMBus interface. In slave mode, the seven mostsignificant bits hold the 7-bit slave address. The least significant bit, bit 0, is used to enable the recognition of the general call address (0x00). If bit 0 is set to logic 1, the general call address will be recognized. Otherwise, the general call address is ignored. The contents of this register are ignored when the SMBus hardware is operating in master mode.

R/W SLV6	R/W SLV5	R/W SLV4	R/W SLV3	R/W SLV2	R/W SLV1	R/W SLV0	R/W GC	Reset Value 00000000		
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xC3		
Bits7-1	Bits7-1: SLV6-SLV0: SMBus Slave Address. These bits are loaded with the 7-bit slave address to which the SMBus will respond when operating as a slave transmitter or slave receiver. SLV6 is the most significant bit of the address and corresponds to the first bit of the address byte received on the SMBus.									
Bit0:	GC: General C This bit is used 0: General cal 1: General cal	d to enable g l address is ig	eneral call ac gnored.	ldress (0x00)	recognition.					

Figure 16.7.	<b>SMB0ADR:</b>	SMBus /	Address	Register
Figure 10.7.	SWIDUADK.	SIMDUS /	<b>Auu</b> (35	Register



### 16.6.5. Status Register

The SMB0STA Status register holds an 8-bit status code indicating the current state of the SMBus. There are 28 possible SMBus states, each with a corresponding unique status code. The five most significant bits of the status code vary while the three least-significant bits of a valid status code are fixed at zero when SI = 1. Therefore, all possible status codes are multiples of eight. This facilitates the use of status codes in software as an index used to branch to appropriate service routines (allowing 8 bytes of code to service the state or jump to a more extensive service routine).

For the purposes of user software, the contents of the SMB0STA register is only defined when the SI flag is logic 1. Software should never write to the SMB0STA register. Doing so will yield indeterminate results. The 28 SMBus states, along with their corresponding status codes, are given in Table 16.1.

STA7STA6STA5STA4STA3STA2STA1STA011111000Bit7Bit6Bit5Bit4Bit3Bit2Bit1Bit0SFR Address: 0xC1Bits7-3:STA7-STA3:SMBus Status Code.These bits contain the SMBus Status Code.There are 28 possible status codes.Each status code corresponds to a single SMBus state.A valid status code is present in SMB0STA when the SI flag (SMB0CN.3) is set.The content of SMB0STA is not defined when the SI flag is logic 0.
Bits7-3: STA7-STA3: SMBus Status Code.       0xC1         Bits7-3: STA7-STA3: SMBus Status Code.       There are 28 possible status codes. Each status code corresponds to a single SMBus state. A valid status code is present in SMB0STA when the SI flag (SMB0CN.3) is set. The content of SMB0STA is not defined
<ul> <li>Bits7-3: STA7-STA3: SMBus Status Code.</li> <li>These bits contain the SMBus Status Code. There are 28 possible status codes. Each status code corresponds to a single SMBus state. A valid status code is present in SMB0STA when the SI flag (SMB0CN.3) is set. The content of SMB0STA is not defined</li> </ul>
indeterminate results.

#### Figure 16.8. SMB0STA: SMBus Status Register



		.1. SMBus Status Codes
Status Code (SMB0STA)	Mode	SMBus State
0x00	All	Bus Error (i.e. illegal START, illegal STOP,)
0x08	Master Transmitter/Receiver	START condition transmitted.
0x10	Master Transmitter/Receiver	Repeated START condition transmitted.
0x18	Master Transmitter	Slave address + W transmitted. ACK received.
0x20	Master Transmitter	Slave address + W transmitted. NACK received.
0x28	Master Transmitter	Data byte transmitted. ACK received.
0x30	Master Transmitter	Data byte transmitted. NACK received.
0x38	Master Transmitter	Arbitration lost
0x40	Master Receiver	Slave address + R transmitted. ACK received.
0x48	Master Receiver	Slave address + R transmitted. NACK received
0x50	Master Receiver	Data byte received. ACK transmitted.
0x58	Master Receiver	Data byte received. NACK transmitted.
0x60	Slave Receiver	SMB0's own slave address + W received. ACK transmitted.
0x68	Slave Receiver	Arbitration lost in transmitting slave address + R/W as master. Own slave address + W received. ACK transmitted.
0x70	Slave Receiver	General call address (0x00) received. ACK returned.
0x78	Slave Receiver	Arbitration lost in transmitting slave address + R/W as master. General call address received. ACK transmitted.
0x80	Slave Receiver	SMB0's own slave address + W received. Data byte received. ACK transmitted.
0x88	Slave Receiver	SMB0's own slave address + W received. Data byte received. NACK transmitted.
0x90	Slave Receiver	General call address (0x00) received. Data byte received. ACK transmitted.
0x98	Slave Receiver	General call address (0x00) received. Data byte received. NACK transmitted.
0xA0	Slave Receiver	A STOP or repeated START received while addressed as a slave.
0xA8	Slave Transmitter	SMB0's own slave address + R received. ACK transmitted.
0xB0	Slave Transmitter	Arbitration lost in transmitting slave address + R/W as master. Own slave address + R received. ACK transmitted.
0xB8	Slave Transmitter	Data byte transmitted. ACK received.
0xC0	Slave Transmitter	Data byte transmitted. NACK received.
0xC8	Slave Transmitter	Last data byte transmitted (AA=0). ACK received.
0xD0	Slave Transmitter/Receiver	SCL Clock High Timer per SMB0CR timed out (FTE=1)
0xF8	All	Idle

### Table 16.1. SMBus Status Codes



## **17. SERIAL PERIPHERAL INTERFACE BUS**

The Serial Peripheral Interface (SPI) provides access to a four-wire, full-duplex, serial bus. SPI supports the connection of multiple slave devices to a master device on the same bus. A separate slave-select signal (NSS) is used to select a slave device and enable a data transfer between the master and the selected slave. Multiple masters on the same bus are also supported. Collision detection is provided when two or more masters attempt a data transfer at the same time. The SPI can operate as either a master or a slave. When the SPI is configured as a master, the maximum data transfer rate (bits/sec) is one-half the system clock frequency.

When the SPI is configured as a slave, the maximum data transfer rate (bits/sec) for full-duplex operation is 1/10 the system clock frequency, provided that the master issues SCK, NSS, and the serial input data synchronously with the system clock. If the master issues SCK, NSS, and the serial input data asynchronously, the maximum data transfer rate (bits/sec) must be less that 1/10 the system clock frequency. In the special case where the master only wants to transmit data to the slave and does not need to receive data from the slave (i.e. half-duplex operation), the SPI slave can receive data at a maximum data transfer rate (bits/sec) of <sup>1</sup>/<sub>4</sub> the system clock frequency. This is provided that the master issues SCK, NSS, and the serial input data synchronously with the system clock.

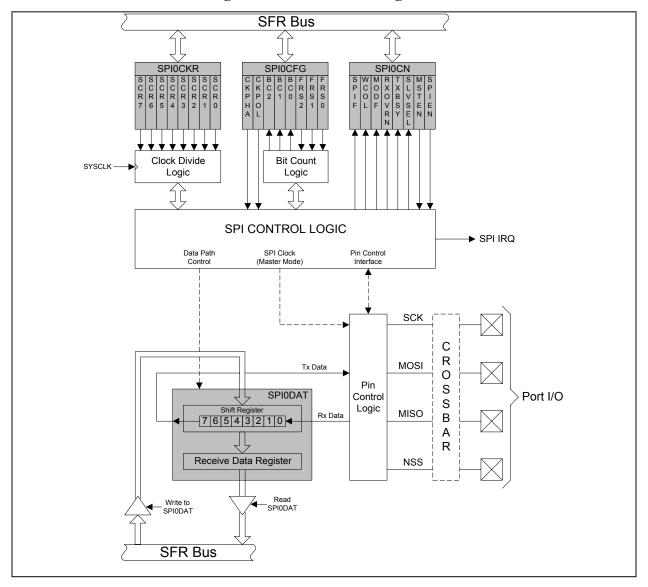
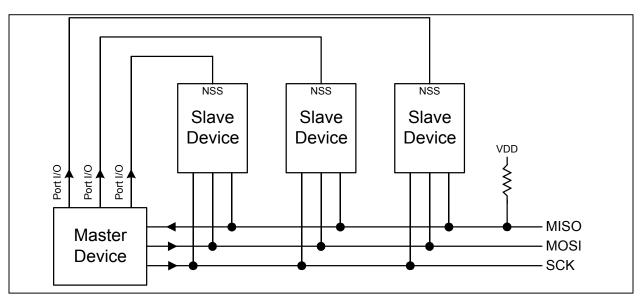


Figure 17.1. SPI Block Diagram



Figure 17.2. Typical SPI Interconnection



### **17.1.** Signal Descriptions

The four signals used by the SPI (MOSI, MISO, SCK, NSS) are described below.

#### 17.1.1. Master Out, Slave In

The master-out, slave-in (MOSI) signal is an output from a master device and an input to slave devices. It is used to serially transfer data from the master to the slave. Data is transferred most-significant bit first.

#### 17.1.2. Master In, Slave Out

The master-in, slave-out (MISO) signal is an output from a slave device and an input to the master device. It is used to serially transfer data from the slave to the master. Data is transferred most-significant bit first. A SPI slave places the MISO pin in a high-impedance state when the slave is not selected.

#### 17.1.3. Serial Clock

The serial clock (SCK) signal is an output from the master device and an input to slave devices. It is used to synchronize the transfer of data between the master and slave on the MOSI and MISO lines.

#### 17.1.4. Slave Select

The slave select (NSS) signal is an input used to select the SPI module when in slave mode by a master, or to disable the SPI module when in master mode. When in slave mode, it is pulled low to initiate a data transfer and remains low for the duration of the transfer.



### 17.2. Operation

Only a SPI master device can initiate a data transfer. The SPI is placed in master mode by setting the Master Enable flag (MSTEN, SPI0CN.1). Writing a byte of data to the SPI data register (SPI0DAT) when in Master Mode starts a data transfer. The SPI master immediately shifts out the data serially on the MOSI line while providing the serial clock on SCK. The SPIF (SPI0CN.7) flag is set to logic 1 at the end of the transfer. If interrupts are enabled, an interrupt request is generated when the SPIF flag is set. The SPI master can be configured to shift in/out from one to eight bits in a transfer operation in order to accommodate slave devices with different word lengths. The SPIFRS bits in the SPI Configuration Register (SPI0CFG.[2:0]) are used to select the number of bits to shift in/out in a transfer operation.

While the SPI master transfers data to a slave on the MOSI line, the addressed SPI slave device simultaneously transfers the contents of its shift register to the SPI master on the MISO line in a full-duplex operation. The data byte received from the slave replaces the data in the master's data register. Therefore, the SPIF flag serves as both a transmit-complete and receive-data-ready flag. The data transfer in both directions is synchronized with the serial clock generated by the master. Figure 17.3 illustrates the full-duplex operation of an SPI master and an addressed slave.

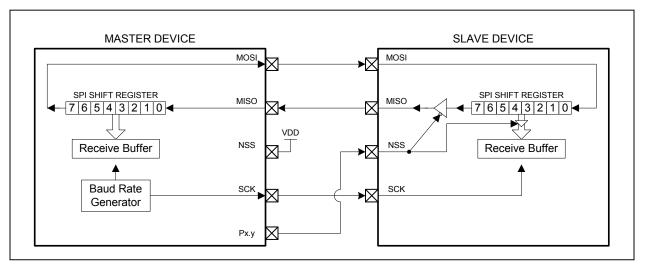


Figure 17.3. Full Duplex Operation

The SPI data register is double buffered on reads, but not on a write. If a write to SPI0DAT is attempted during a data transfer, the WCOL flag (SPI0CN.6) will be set to logic 1 and the write is ignored. The current data transfer will continue uninterrupted. A read of the SPI data register by the system controller actually reads the receive buffer. If the receive buffer still holds unread data from a previous transfer when the last bit of the current transfer is shifted into the SPI shift register, a receive overrun occurs and the RXOVRN flag (SPI0CN.4) is set to logic 1. The new data is not transferred to the receive buffer, allowing the previously received data byte to be read. The data byte causing the overrun is lost.

When the SPI is enabled and not configured as a master, it will operate as an SPI slave. Another SPI device acting as a master will initiate a transfer by driving the NSS signal low. The master then shifts data out of the shift register on the MOSI pin using the its serial clock. The SPIF flag is set to logic 1 at the end of a data transfer (when the NSS signal goes high). The slave can load its shift register for the next data transfer by writing to the SPI data register. The slave must make the write to the data register at least one SPI serial clock cycle before the master starts the next transmission. Otherwise, the byte of data already in the slave's shift register will be transferred.

Multiple masters may reside on the same bus. A Mode Fault flag (MODF, SPI0CN.5) is set to logic 1 when the SPI is configured as a master (MSTEN = 1) and its slave select signal NSS is pulled low. When the Mode Fault flag is set, the MSTEN and SPIEN bits of the SPI control register are cleared by hardware, thereby placing the SPI module



in an "off-line" state. In a multiple-master environment, the system controller should check the state of the SLVSEL flag (SPI0CN.2) to ensure the bus is free before setting the MSTEN bit and initiating a data transfer.

### 17.3. Serial Clock Timing

As shown in Figure 17.4, four combinations of serial clock phase and polarity can be selected using the clock control bits in the SPI Configuration Register (SPI0CFG). The CKPHA bit (SPI0CFG.7) selects one of two clock phases (edge used to latch the data). The CKPOL bit (SPI0CFG.6) selects between an active-high or active-low clock. Both master and slave devices must be configured to use the same clock phase and polarity. Note: the SPI should be disabled (by clearing the SPIEN bit, SPI0CN.0) while changing the clock phase and polarity.

The SPI Clock Rate Register (SPI0CKR) as shown in Figure 17.7 controls the master mode serial clock frequency. This register is ignored when operating in slave mode.

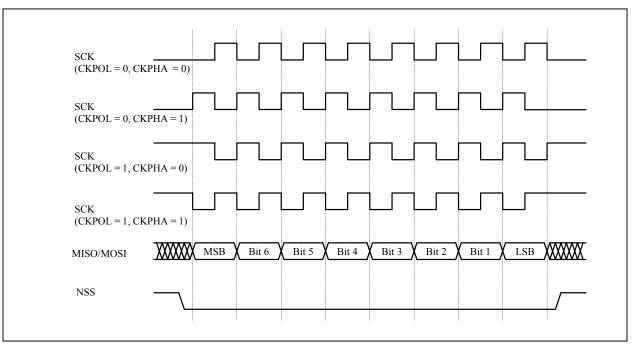


Figure 17.4. Data/Clock Timing Diagram



### 17.4. SPI Special Function Registers

The SPI is accessed and controlled through four special function registers in the system controller: SPI0CN Control Register, SPI0DAT Data Register, SPI0CFG Configuration Register, and SPI0CKR Clock Rate Register. The four special function registers related to the operation of the SPI Bus are described in the following section.

Figure 17.5.	<b>SPI0CFG:</b>	SPI Col	nfiguration	Register

R/W	R/W		R	R	R	R/W	R/W	R/W	Reset Valu
СКРНА	CKPOL		C2	BC1	BC0	SPIFRS2	SPIFRS1	SPIFRS0	0000011
Bit7	Bit6	B	it5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Addres 0x9A
Bit7:	CKPHA: SI	PI Clock	Phase.						
	This bit con			c phase.					
	0: Data sam				iod				
	1: Data sam								
		1		0	L				
Bit6:	CKPOL: SI	PI Clock	Polarity.						
	This bit con			c polarity.					
	0: SCK line	low in i	dle state.						
	1: SCK line	high in i	idle state.						
		~~~~	_						
Bits5-3:	BC2-BC0:				~~~				
	Indicates w	hich of th	ne up to 8	bits of the S	SPI word h	ave been tran	ismitted.		
	B	C2-BC0		Bit Tran	smitted				
	0	0	0	Bit 0 (					
	0	0	1	Bit 1	_~_/				
	0	1	0	Bit 2					
	0	1	1	Bit 3					
	1	0	0	Bit 4					
	1	0	1	Bit 5					
	1	0 1	1 0						
	1 1 1	1 1	0 1	Bit 6 Bit 7 (1	MSB)				
Bits2-0:	1       1       SPIFRS2-S       These three       during a dat	1 1 PIFRS0: bits dete ta transfe	0 1 SPI Fran	Bit 6 Bit 7 (1 ne Size. e number of er mode. Th	bits to shif ney are ign	t in/out of the ored in slave		gister	
Bits2-0:	1       1       SPIFRS2-S       These three       during a date	1 1 PIFRS0: bits dete ta transfe SPIFRS	0 1 SPI Fran ermine the r in maste	Bit 6 Bit 7 (1 ne Size. e number of er mode. Th Bits Shift	bits to shif ney are ign			gister	
Bits2-0:	1       1       1       SPIFRS2-S       These three       during a dat       9       0	1 1 PIFRS0: bits dete ta transfe SPIFRS 0	0 1 SPI Fran ermine the r in maste	Bit 6 Bit 7 (1) ne Size. e number of er mode. Th Bits Shift 1	bits to shif ney are ign			gister	
Bits2-0:	1     1     1     SPIFRS2-S     These three during a date     0     0     0	1 1 PIFRS0: bits dete ta transfe SPIFRS 0 0	0 1 SPI Fran ermine the r in maste 0 1	Bit 6 Bit 7 (1) ne Size. e number of er mode. Th Bits Shift 1 2	bits to shif ney are ign			gister	
Bits2-0:	1       1       1       SPIFRS2-S       These three       during a date       0       0       0       0	1 1 PIFRS0: bits dete ta transfe SPIFRS 0 0 1	0 1 SPI Fram ermine the r in master 0 1 0	Bit 6Bit 7 (1)ne Size.e number ofer mode.ThBits Shift123	bits to shif ney are ign			gister	
Bits2-0:	1     1     1     SPIFRS2-S     These three during a date     0     0     0	11PIFRS0:bits deteta transfeSPIFRS0011	0 1 SPI Fran ermine the r in master 0 1 0 1	Bit 6Bit 7 (1)ne Size.e number ofer mode.ThBits Shift1234	bits to shif ney are ign			gister	
Bits2-0:	1       1       1       SPIFRS2-S       These three       during a date       0       0       0       0       0       0       0	11PIFRS0:bits deteta transfeSPIFRS0010	0 1 SPI Fram ermine the r in master 0 1 0	Bit 6           Bit 7 (1)           ne Size.           e number of           er mode.           Th           Bits Shift           1           2           3           4           5	bits to shif ney are ign			gister	
Bits2-0:	1       1       1       SPIFRS2-S       These three       during a date       0       0       0       0       0       0       0	11PIFRS0:bits deteta transfeSPIFRS0011	0 1 SPI Fran ermine the r in master 0 1 0 1 0 1 0 1	Bit 6           Bit 7 (1)           ne Size.           e number of           er mode.           Th           Bits Shift           1           2           3           4           5           6	bits to shif ney are ign			gister	
Bits2-0:	1       1       1       SPIFRS2-S       These three       during a date       0       0       0       0       0       0       0	11PIFRS0:bits deteta transfeSPIFRS0010	0 1 SPI Fran ermine the r in master 0 1 0 1	Bit 6           Bit 7 (1)           ne Size.           e number of           er mode.           Th           Bits Shift           1           2           3           4           5	bits to shif ney are ign			gister	



R/W	R/W	R/W	R/W	R	R	R/W	R/W	Reset Value
SPIF	WCOL	MODF	RXOVRN	TXBSY	SLVSEL	MSTEN	SPIEN	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (bit addressable)	SFR Address 0xF8
Bit7:	SPIF: SPI Inte This bit is set setting this bit not automatica	to logic 1 by causes the C	CPU to vector	to the SPI0	interrupt serv	vice routine.		
Bit6:	WCOL: Write This bit is set the SPI data re software.	to logic 1 by	hardware (an					
Bit5:	MODF: Mode Fault Flag. This bit is set to logic 1 by hardware (and generates a SPI interrupt) when a master mode collision is detected (NSS is low and MSTEN = 1). This bit is not automatically cleared by hardware. It must be cleared by software.							
Bit4:	RXOVRN: Receive Overrun Flag. This bit is set to logic 1 by hardware (and generates a SPI interrupt) when the receive buffer still holds unread data from a previous transfer and the last bit of the current transfer is shifted into the SPI shift register. This bit is not automatically cleared by hardware. It must be cleared by software.							
Bit3:	TXBSY: Transmit Busy Flag. This bit is set to logic 1 by hardware while a master mode transfer is in progress. It is cleared by hardware at the end of the transfer.							
Bit2:	SLVSEL: Slave Selected Flag. This bit is set to logic 1 whenever the NSS pin is low indicating it is enabled as a slave. It is cleared to logic 0 when NSS is high (slave disabled).							
Bit1:	MSTEN: Master Mode Enable. 0: Disable master mode. Operate in slave mode. 1: Enable master mode. Operate as a master.							
Bit0:	•							

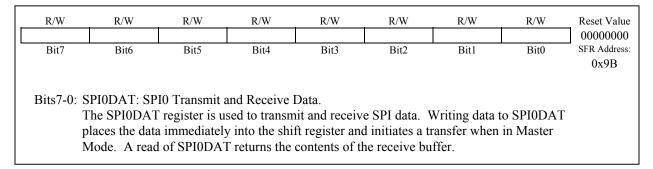
## Figure 17.6. SPI0CN: SPI Control Register



R/W SCR7	R/W SCR6	R/W SCR5	R/W SCR4	R/W SCR3	R/W SCR2	R/W SCR1	R/W SCR0	Reset Value 00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0x9D
These bits determine the frequency of the SCK output when the SPI module is configured for master mode operation. The SCK clock frequency is a divided down version of the system clock, and is given in the following equations: $f_{SCK} = 0.5 * f_{SYSCLK} / (SPI0CKR + 1),$ for $0 \le SPI0CKR \le 255$ ,								
1	$SCK = 0.3 + 1_S$	YSCLK / (SF10	CKK + 1 <i>)</i> ,	101 0	$\leq$ SPI0CKI	X ≤ 233,		

### Figure 17.7. SPI0CKR: SPI Clock Rate Register





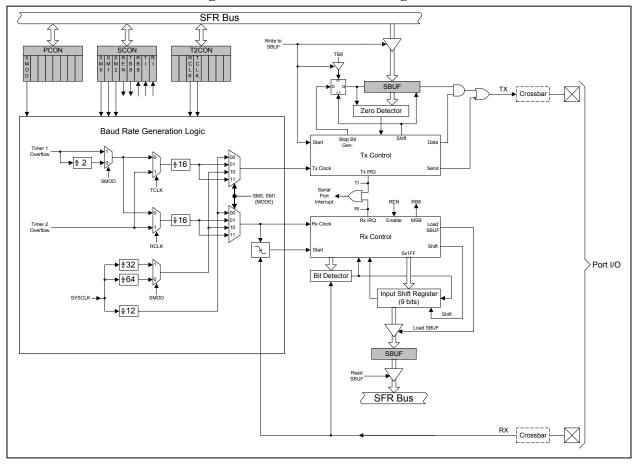


## **18. UART**

The UART is a serial port capable of asynchronous transmission. The UART can function in full duplex mode. In all modes, receive data is buffered in a holding register. This allows the UART to start reception of a second incoming data byte before software has finished reading the previous data byte.

The UART has an associated Serial Control Register (SCON) and a Serial Data Buffer (SBUF) in the SFRs. The single SBUF location provides access to both transmit and receive registers. Reads access the Receive register and writes access the Transmit register automatically.

The UART is capable of generating interrupts if enabled. The UART has two sources of interrupts: a Transmit Interrupt flag, TI (SCON.1) set when transmission of a data byte is complete, and a Receive Interrupt flag, RI (SCON.0) set when reception of a data byte is complete. The UART interrupt flags are not cleared by hardware when the CPU vectors to the interrupt service routine. They must be cleared manually by software. This allows software to determine the cause of the UART interrupt (transmit complete or receive complete).







### 18.1. UART Operational Modes

The UART provides four operating modes (one synchronous and three asynchronous) selected by setting configuration bits in the SCON register. These four modes offer different baud rates and communication protocols. The four modes are summarized in Table 18.1 below. Detailed descriptions follow.

Mode	Synchronization	Baud Clock	Data Bits	Start/Stop Bits
0	Synchronous	SYSCLK/12	8	None
1	Asynchronous	Timer 1 or Timer 2 Overflow	8	1 Start, 1 Stop
2	Asynchronous	SYSCLK/32 or SYSCLK/64	9	1 Start, 1 Stop
3	Asynchronous	Timer 1 or Timer 2 Overflow	9	1 Start, 1 Stop

#### Table 18.1. UART Modes

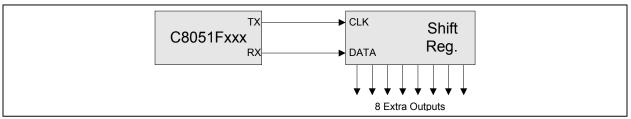
#### 18.1.1. Mode 0: Synchronous Mode

Mode 0 provides synchronous, half-duplex communication. Serial data is transmitted and received on the RX pin. The TX pin provides the shift clock for both transmit and receive. The MCU must be the master since it generates the shift clock for transmission in both directions (see the interconnect diagram in Figure 18.2).

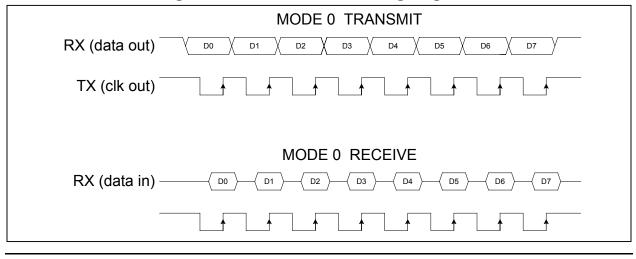
Eight data bits are transmitted/received, LSB first (see the timing diagram in Figure 18.3). Data transmission begins when an instruction writes a data byte to the SBUF register. The TI Transmit Interrupt Flag (SCON.1) is set at the end of the eighth bit time. Data reception begins when the REN Receive Enable bit (SCON.4) is set to logic 1 and the RI Receive Interrupt Flag (SCON.0) is cleared. One cycle after the eighth bit is shifted in, the RI flag is set and reception stops until software clears the RI bit. An interrupt will occur if enabled when either TI or RI is set.

The Mode 0 baud rate is the system clock frequency divided by twelve. RX is forced to open-drain in mode 0, and an external pull-up will typically be required.





#### Figure 18.3. UART Mode 0 Timing Diagram





Mode 1 provides standard asynchronous, full duplex communication using a total of 10 bits per data byte: one start bit, eight data bits (LSB first), and one stop bit (see the timing diagram in Figure 18.4). Data are transmitted from the TX pin and received at the RX pin (see the interconnection diagram in Figure 18.5). On receive, the eight data bits are stored in SBUF and the stop bit goes into RB8 (SCON.2).

Data transmission begins when an instruction writes a data byte to the SBUF register. The TI Transmit Interrupt Flag (SCON.1) is set at the end of the transmission (the beginning of the stop-bit time). Data reception can begin any time after the REN Receive Enable bit (SCON.4) is set to logic 1. After the stop bit is received, the data byte will be loaded into the SBUF receive register if the following conditions are met: RI must be logic 0, and if SM2 is logic 1, the stop bit must be logic 1.

If these conditions are met, the eight bits of data are stored in SBUF, the stop bit is stored in RB8, and the RI flag is set. If these conditions are not met, SBUF and RB8 will not be loaded and the RI flag will not be set. An interrupt will occur if enabled when either TI or RI is set.

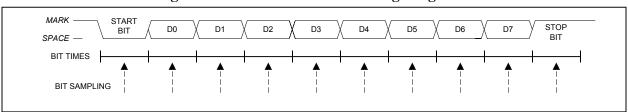


Figure 18.4. UART Mode 1 Timing Diagram

The baud rate generated in Mode 1 is a function of timer overflow. The UART can use Timer 1 operating in *8-bit Counter/Timer with Auto-Reload Mode*, or Timer 2 operating in *Baud Rate Generator Mode* to generate the baud rate (note that the TX and RX clock sources are selected separately). On each timer overflow event (a rollover from all ones (0xFF for Timer 1, 0xFFFF for Timer 2) to zero), a clock is sent to the baud rate logic.

When Timer 1 is selected as a baud rate source, the SMOD bit (PCON.7) selects whether or not to divide the Timer 1 overflow rate by two. On reset, the SMOD bit is logic 0, thus selecting the lower speed baud rate by default. The SMOD bit affects the baud rate generated by Timer 1 as follows:

Mode 1 Baud Rate =  $(1/32) * T1_OVERFLOWRATE$  (when the SMOD bit is set to logic 0). Mode 1 Baud Rate =  $(1/16) * T1_OVERFLOWRATE$  (when the SMOD bit is set to logic 1).

When Timer 2 is selected as a baud rate source, the baud rate generated by Timer 2 is as follows:

Mode 1 Baud Rate =  $(1 / 16) * T2_OVERFLOWRATE$ .

The Timer 1 overflow rate is determined by the Timer 1 clock source (T1CLK) and reload value (TH1). The frequency of T1CLK can be selected as SYSCLK, SYSCLK/12, or an external clock source. The Timer 1 overflow rate can be calculated as follows:

$$T1_OVERFLOWRATE = T1CLK / (256 - TH1).$$

For example, assume TMOD = 0x20. If T1M (CKCON.4) is logic 1, then the above equation becomes:

T1\_OVERFLOWRATE = (SYSCLK) / (256 - TH1).

If T1M (CKCON.4) is logic 0, then the above equation becomes:

 $T1_OVERFLOWRATE = (SYSCLK/12) / (256 - TH1).$ 

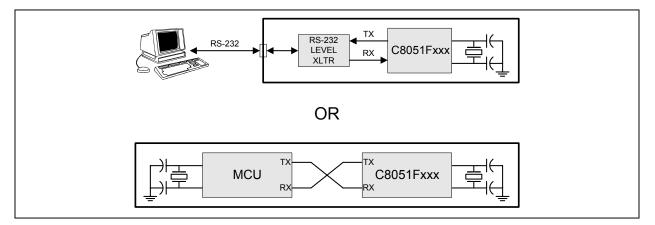


The Timer 2 overflow rate, when in *Baud Rate Generator Mode* and using an internal clock source, is determined solely by the Timer 2 16-bit reload value (RCAP2H:RCAP2L). The Timer 2 clock source is fixed at SYSCLK/2. The Timer 2 overflow rate can be calculated as follows:

T2 OVERFLOWRATE = (SYSCLK/2) / (65536 - [RCAP2H:RCAP2L]).

Timer 2 can be selected as the baud rate generator for RX and/or TX by setting RCLK (T2CON.5) and/or TCLK (T2CON.4), respectively. When either RCLK or TCLK is set to logic 1, Timer 2 interrupts are automatically disabled and the timer is forced into *Baud Rate Generator Mode* with SYSCLK/2 as its clock source. If a different timebase is required, setting the C/T2 bit (T2CON.1) to logic 1 will allow Timer 2 to be clocked from the external input pin T2. See the Timers section for complete timer configuration details.

Figure 18.5. UART Modes 1, 2, and 3 Interconnect Diagram





#### 18.1.3. Mode 2: 9-Bit UART, Fixed Baud Rate

Mode 2 provides asynchronous, full-duplex communication using a total of eleven bits per data byte: a start bit, 8 data bits (LSB first), a programmable ninth data bit, and a stop bit (see timing diagram in Figure 18.6). On transmit, the ninth data bit is determined by the value in TB8 (SCON.3). It can be assigned the value of the parity flag P in the PSW or used in multiprocessor communications. On receive, the ninth data bit goes into RB8 (SCON.2) and the stop bit is ignored.

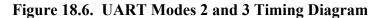
Data transmission begins when an instruction writes a data byte to the SBUF register. The TI Transmit Interrupt Flag (SCON.1) is set at the end of the transmission (the beginning of the stop-bit time). Data reception can begin any time after the REN Receive Enable bit (SCON.4) is set to logic 1. After the stop bit is received, the data byte will be loaded into the SBUF receive register if the following conditions are met: RI must be logic 0, and if SM2 is logic 1, the 9<sup>th</sup> bit must be logic 1.

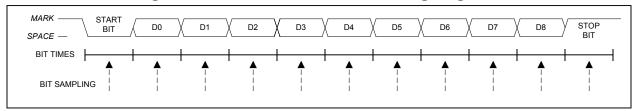
If these conditions are met, the eight bits of data are stored in SBUF, the ninth bit is stored in RB8 and the RI flag is set. If these conditions are not met, SBUF and RB8 will not be loaded and the RI flag will not be set. An interrupt will occur if enabled when either TI or RI are set.

The baud rate in Mode 2 is a direct function of the system clock frequency as follows:

Mode 2 Baud Rate =  $2^{SMOD} * (SYSCLK / 64)$ .

The SMOD bit (PCON.7) selects whether to divide SYSCLK by 32 or 64. In the formula, 2 is raised to the power SMOD, resulting in a baud rate of either 1/32 or 1/64 of the system clock frequency. On reset, the SMOD bit is logic 0, thus selecting the lower speed baud rate by default.





#### 18.1.4. Mode 3: 9-Bit UART, Variable Baud Rate

Mode 3 is the same as Mode 2 in all respects except the baud rate is variable. The baud rate is determined in the same manner as for Mode 1. Mode 3 operation transmits 11 bits: a start bit, 8 data bits (LSB first), a programmable ninth data bit, and a stop bit. Timer 1 or Timer 2 overflows generate the baud rate just as with Mode 1. In summary, Mode 3 transmits using the same protocol as Mode 2 but with Mode 1 baud rate generation.



### 18.2. Multiprocessor Communications

Modes 2 and 3 support multiprocessor communication between a master processor and one or more slave processors by special use of the ninth data bit. When a master processor wants to transmit to one or more slaves, it first sends an address byte to select the target(s). An address byte differs from a data byte in that its ninth bit is logic 1; in a data byte, the ninth bit is always set to logic 0.

Setting the SM2 bit (SCON.5) of a slave processor configures its UART such that when a stop bit is received, the UART will generate an interrupt only if the ninth bit is logic one (RB8 = 1) signifying an address byte has been received. In the UART's interrupt handler, software will compare the received address with the slave's own assigned 8-bit address. If the addresses match, the slave will clear its SM2 bit to enable interrupts on the reception of the following data byte(s). Slaves that weren't addressed leave their SM2 bits set and do not generate interrupts on the received, the addressed slave resets its SM2 bit to ignore all transmissions until it receives the next address byte.

Multiple addresses can be assigned to a single slave and/or a single address can be assigned to multiple slaves, thereby enabling "broadcast" transmissions to more than one slave simultaneously. The master processor can be configured to receive all transmissions or a protocol can be implemented such that the master/slave role is temporarily reversed to enable half-duplex transmission between the original master and slave(s).

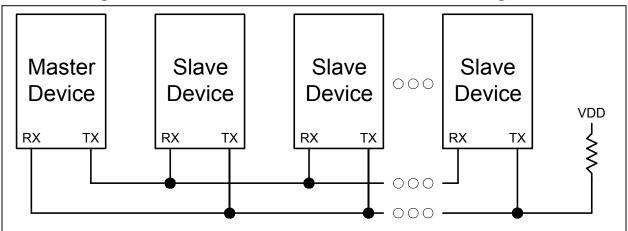


Figure 18.7. UART Multi-Processor Mode Interconnect Diagram



Oscillator Frequency (MHz)	<b>Divide Factor</b>	Timer 1 Load Value*	<b>Resulting Baud Rate**</b>
24.0	208	0xF3	115200 (115384)
23.592	205	0xF3	115200 (113423)
22.1184	192	0xF4	115200
18.432	160	0xF6	115200
16.5888	144	0xF7	115200
14.7456	128	0xF8	115200
12.9024	112	0xF9	115200
11.0592	96	0xFA	115200
9.216	80	0xFB	115200
7.3728	64	0xFC	115200
5.5296	48	0xFD	115200
3.6864	32	0xFE	115200
1.8432	16	0xFF	115200
24.576	320	0xEC	76800
25.0	434	0xE5	57600 (57870)
25.0	868	0xCA	28800
24.576	848	0xCB	28800 (28921)
24.0	833	0xCC	28800 (28846)
23.592	819	0xCD	28800 (28911)
22.1184	768	0xD0	28800
18.432	640	0xD8	28800
16.5888	576	0xDC	28800
14.7456	512	0xE0	28800
12.9024	448	0xE4	28800
11.0592	384	0xE8	28800
9.216	320	0xEC	28800
7.3728	256	0xF0	28800
5.5296	192	0xF4	28800
3.6864	128	0xF8	28800
1.8432	64	0xFC	28800

 Table 18.2. Oscillator Frequencies for Standard Baud Rates

\* Assumes SMOD=1 and T1M=1.

\*\* Numbers in parenthesis show the actual baud rate.



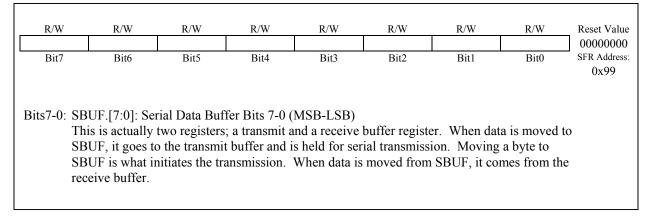




Figure 18.9.	SCON: Serial Port Control Register
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R/W	R/W		/W	R/W	R/W	R/W	R/W	R/W	Reset Valu
SM0	SM1		M2	REN	TB8	RB8	TI	RI	0000000
Bit7	Bit6	В	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (bit addressable)	SFR Addres 0x98
Bits7-6	: SM0-SM1	: Serial P	ort Operati	on Mode					
			Serial Por						
	SM0	SM1	Mode						
	0	0			nous Mode				
	0	1			RT, Variable				
	1	0			RT, Fixed B				
	1	1	Mode 3:	9-Bit UA	RT, Variable	e Baud Rate			
D: 6			G	· .· -					
Bit5:			or Commu				N 1		
	Mode 0: N		bit is depe	endent on	the Serial Po	ort Operation	Mode.		
			valid stop	hit					
			vel of stop		ored				
					stop bit is log	tic level 1			
					nications Ena				
			vel of nint						
						ly when the n	inth bit is lo	gic 1.	
Bit4:	REN: Rec								
			ables the U	ART rec	eiver.				
	0: UART								
	I: UARI	reception	enabled.						
Bit3:	TB8: Nint	th Transmi	ission Bit.						
	The logic	level of th	nis bit will	be assign	ed to the nin	th transmissic	on bit in Mo	des 2 and 3. It	ţ
						ware as requi			
Bit2:	RB8: Nin								
								In Mode 1, if	
		gic 0, RB8	s is assigne	ed the log	ic level of th	e received sto	p bit. RB8	is not used in	
	Mode 0.								
Bit1:	TI: Transı	nit Interru	int Flag						
DITI.			1 0	of data ha	s heen transr	nitted by the l	I ART (afte	r the 8 <sup>th</sup> bit in	
						nodes). When			
						the UART int			
			ared manu				·····		
Bit0:	RI: Receiv							41-	
						ed by the UA			
						12 bit for exc			
							tor to the U	ART interrupt	
	service ro	utine. Thi	is bit must	be cleare	d manually b	y software.			



### **19. TIMERS**

Each MCU implements four counter/timers: three are 16-bit counter/timers compatible with those found in the standard 8051, and one is a 16-bit timer for use with the ADC, SMBus, or for general purpose use. These can be used to measure time intervals, count external events and generate periodic interrupt requests. Timer 0 and Timer 1 are nearly identical and have four primary modes of operation. Timer 2 offers additional capabilities not available in Timers 0 and 1. Timer 3 is similar to Timer 2, but without the capture or Baud Rate Generator modes.

Timer 0 and Timer 1:	<u>Timer 2:</u>	<u>Timer 3:</u>
13-bit counter/timer	16-bit counter/timer with auto-reload	16-bit timer with auto-reload
16-bit counter/timer	16-bit counter/timer with capture	
8-bit counter/timer with auto-reload	Baud rate generator	
Two 8-bit counter/timers (Timer 0 only)		

When functioning as a timer, the counter/timer registers are incremented on each clock tick. Clock ticks are derived from the system clock divided by either one or twelve as specified by the Timer Clock Select bits (T2M-T0M) in CKCON. The twelve-clocks-per-tick option provides compatibility with the older generation of the 8051 family. Applications that require a faster timer can use the one-clock-per-tick option.

When functioning as a counter, a counter/timer register is incremented on each high-to-low transition at the selected input pin for T0, T1, or T2. Events with a frequency of up to one-fourth the system clock's frequency can be counted. The input signal need not be periodic, but it should be held at a given level for at least two full system clock cycles to ensure the level is sampled.

### **19.1.** Timer 0 and Timer 1

Timer 0 and Timer 1 are accessed and controlled through SFRs. Each counter/timer is implemented as a 16-bit register accessed as two separate bytes: a low byte (TL0 or TL1) and a high byte (TH0 or TH1). The Counter/Timer Control (TCON) register is used to enable Timer 0 and Timer 1 as well as indicate their status. Both counter/timers operate in one of four primary modes selected by setting the Mode Select bits M1-M0 in the Counter/Timer Mode (TMOD) register. Each timer can be configured independently. Following is a detailed description of each operating mode.

#### 19.1.1. Mode 0: 13-bit Counter/Timer

Timer 0 and Timer 1 operate as a 13-bit counter/timer in Mode 0. The following describes the configuration and operation of Timer 0. However, both timers operate identically and Timer 1 is configured in the same manner as described for Timer 0.

The TH0 register holds the eight MSBs of the 13-bit counter/timer. TL0 holds the five LSBs in bit positions TL0.4-TL0.0. The three upper bits of TL0 (TL0.7-TL0.5) are indeterminate and should be masked out or ignored when reading. As the 13-bit timer register increments and overflows from 0x1FFF (all ones) to 0x0000, the timer overflow flag TF0 (TCON.5) is set and an interrupt will occur if enabled.

The C/T0 bit (TMOD.2) selects the counter/timer's clock source. Clearing C/T selects the system clock as the input for the timer. When C/T0 is set to logic 1, high-to-low transitions at the selected input pin increment the timer register. (Refer to Port I/O Section 15.1 for information on selecting and configuring external I/O pins.)



Setting the TR0 bit (TCON.4) enables the timer when either GATE0 (TMOD.3) is 0 or the input signal /INT0 is logic-level one. Setting GATE0 to logic 1 allows the timer to be controlled by the external input signal /INT0, facilitating pulse width measurements.

TR0	GATE0	/INT0	<b>Counter/Timer</b>
0	Х	Х	Disabled
1	0	Х	Enabled
1	1	0	Disabled
1	1	1	Enabled
X = D	on't Care		

Setting TR0 does not reset the timer register. The timer register should be initialized to the desired value before enabling the timer.

TL1 and TH1 form the 13-bit register for Timer 1 in the same manner as described above for TL0 and TH0. Timer 1 is configured and controlled using the relevant TCON and TMOD bits just as with Timer 0.

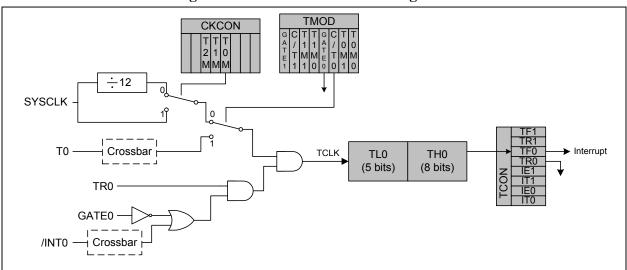


Figure 19.1. T0 Mode 0 Block Diagram

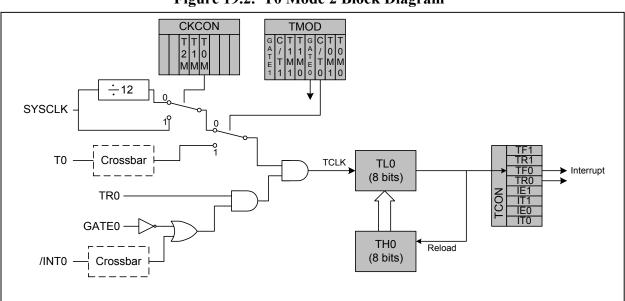
#### 19.1.2. Mode 1: 16-bit Counter/Timer

Mode 1 operation is the same as Mode 0, except that the counter/timer registers use all 16 bits. The counter/timers are enabled and configured in Mode 1 in the same manner as for Mode 0.



#### 19.1.3. Mode 2: 8-bit Counter/Timer with Auto-Reload

Mode 2 configures Timer 0 and Timer 1 to operate as 8-bit counter/timers with automatic reload of the start value. The TL0 holds the count and TH0 holds the reload value. When the count in TL0 overflows from all ones to 0x00, the timer overflow flag TF0 (TCON.5) is set and the counter in TL0 is reloaded from TH0. If enabled, an interrupt will occur when the TF0 flag is set. The reload value in TH0 is not changed. TL0 must be initialized to the desired value before enabling the timer for the first count to be correct. When in Mode 2, Timer 1 operates identically to Timer 0. Both counter/timers are enabled and configured in Mode 2 in the same manner as Mode 0.







### 19.1.4. Mode 3: Two 8-bit Counter/Timers (Timer 0 Only)

Timer 0 and Timer 1 behave differently in Mode 3. Timer 0 is configured as two separate 8-bit counter/timers held in TL0 and TH0. The counter/timer in TL0 is controlled using the Timer 0 control/status bits in TCON and TMOD: TR0, C/T0, GATE0 and TF0. It can use either the system clock or an external input signal as its timebase. The TH0 register is restricted to a timer function sourced by the system clock. TH0 is enabled using the Timer 1 run control bit TR1. TH0 sets the Timer 1 overflow flag TF1 on overflow and thus controls the Timer 1 interrupt.

Timer 1 is inactive in Mode 3, so with Timer 0 in Mode 3, Timer 1 can be turned off and on by switching it into and out of its Mode 3. When Timer 0 is in Mode 3, Timer 1 can be operated in Modes 0, 1 or 2, but cannot be clocked by external signals nor set the TF1 flag and generate an interrupt. However, the Timer 1 overflow can be used for baud rate generation. Refer to Section 18 (UART) for information on configuring Timer 1 for baud rate generation.

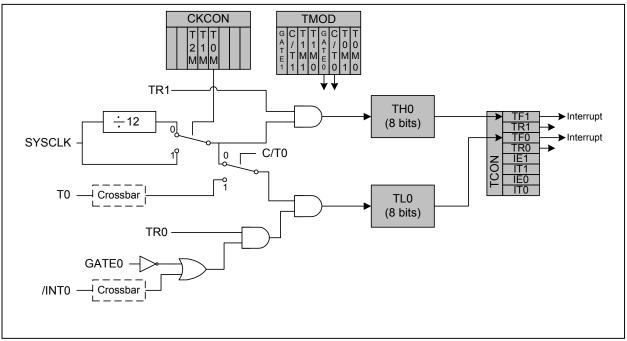


Figure 19.3. T0 Mode 3 Block Diagram



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value		
TF1 Bit7	TR1 Bit6	TF0 Bit5	TR0 Bit4	IE1 Bit3	IT1 Bit2	IE0 Bit1	IT0 Bit0	00000000 SFR Address		
Bit7:	TF1: Timer 1 of Set by hardwa automatically 0: No Timer 1 1: Timer 1 ha	re when Tim cleared when overflow do	er 1 overflow the CPU ve etected.					0x88		
Bit6:	TR1: Timer 1 0: Timer 1 dis 1: Timer 1 en	Run Control abled.								
Bit5:	TF0: Timer 0 Set by hardwa automatically 0: No Timer 0 1: Timer 0 has	re when Tim cleared wher overflow de	her 0 overflow the CPU ve etected.							
Bit4:	<ul><li>TR0: Timer 0 Run Control.</li><li>0: Timer 0 disabled.</li><li>1: Timer 0 enabled.</li></ul>									
Bit3:	IE1: External Interrupt 1. This flag is set by hardware when an edge/level of type defined by IT1 is detected. It can be cleared by software but is automatically cleared when the CPU vectors to the External Interrupt 1 service routine if IT1 = 1. This flag is the inverse of the /INT1 input signal's logic level when IT1 = 0.									
Bit2:	<ul> <li>IT1: Interrupt 1 Type Select.</li> <li>This bit selects whether the configured /INT1 signal will detect falling edge or active-low level-sensitive interrupts.</li> <li>0: /INT1 is level triggered.</li> <li>1: /INT1 is edge triggered.</li> </ul>									
Bit1:	IE0: External Interrupt 0. This flag is set by hardware when an edge/level of type defined by IT0 is detected. It can be cleared by software but is automatically cleared when the CPU vectors to the External Interrupt 0 service routine if IT0 = 1. This flag is the inverse of the /INT0 input signal's logic level when IT0 = 0.									
Bit0:	<ul> <li>IT0: Interrupt 0 Type Select.</li> <li>This bit selects whether the configured /INT0 signal will detect falling edge or active-low level-sensitive interrupts.</li> <li>0: /INT0 is level triggered.</li> <li>1: /INT0 is edge triggered.</li> </ul>									

## Figure 19.4. TCON: Timer Control Register



			0				9					
R/W	R/W		/W	R/W	R/W	R/W	R/W	R/W	Reset Value			
GATE1	C/T1	T1	M1	T1M0	GATE0	C/T0	T0M1	T0M0	0000000			
Bit7	Bit6	В	sit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address 0x89			
Bit7:	<ul> <li>GATE1: Timer 1 Gate Control.</li> <li>0: Timer 1 enabled when TR1 = 1 irrespective of /INT1 logic level.</li> <li>1: Timer 1 enabled only when TR1 = 1 AND /INT1 = logic level one.</li> </ul>											
Bit6:	<ul> <li>C/T1: Counter/Timer 1 Select.</li> <li>0: Timer Function: Timer 1 incremented by clock defined by T1M bit (CKCON.4).</li> <li>1: Counter Function: Timer 1 incremented by high-to-low transitions on external input pin (T1).</li> </ul>											
Bits5-4:	T1M1-T1 These bits			de Select. 1 operation	mode.							
	T1M1	T1M0	Mode	Mode								
	0	0	Mode	Mode 0: 13-bit counter/timer								
	0	1	Mode	1: 16-bit co	unter/timer							
	1	0	Mode	Mode 2: 8-bit counter/timer with auto-reload								
	1	1	Mode 3: Timer 1 Inactive/stopped									
Bit3: Bit2: Bits1-0:	<ul> <li>GATE0: Timer 0 Gate Control.</li> <li>0: Timer 0 enabled when TR0 = 1 irrespective of /INT0 logic level.</li> <li>1: Timer 0 enabled only when TR0 = 1 AND /INT0 = logic level one.</li> <li>C/T0: Counter/Timer Select.</li> <li>0: Timer Function: Timer 0 incremented by clock defined by T0M bit (CKCON.3).</li> <li>1: Counter Function: Timer 0 incremented by high-to-low transitions on external input pin (T0).</li> <li>0: T0M1-T0M0: Timer 0 Mode Select. These bits select the Timer 0 operation mode.</li> </ul>											
	T0M1	TOMO	Mode	2								
	0	0			unter/timer							
	0	1		Iode 0: 13-bit counter/timer       Iode 1: 16-bit counter/timer								
	1	1 0 Mode 2: 8-bit counter/timer with auto-reload										
	1	1			it counter/tin		*					
	<u>`</u>	· ·	1.1040	2. 1.000 01			]					

## Figure 19.5. TMOD: Timer Mode Register



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value			
-	-	T2M	T1M	T0M	Reserved	Reserved	Reserved	00000000			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address			
Bits7-6:	UNUSED. Re	ead = 00b, W	vrite = don't c	are.				0x8E			
Bit5:	T2M <sup>·</sup> Timer 2	Clock Selec	t								
Dito.	This bit controls the division of the system clock supplied to Timer 2. This bit is ignored										
	when the timer is in baud rate generator mode or counter mode (i.e. $C/T2 = 1$ ).										
	0: Timer 2 uses the system clock divided by 12.										
	1: Timer 2 uses the system clock.										
		5									
Bit4:	T1M: Timer 1	Clock Selec	t.								
	This bit controls the division of the system clock supplied to Timer 1.										
	0: Timer 1 uses the system clock divided by 12.										
	1: Timer 1 uses the system clock.										
Bit3:	TOM: Timer 0	Clock Salar	4								
DILJ.	T0M: Timer 0 Clock Select. This bit controls the division of the system clock supplied to Counter/Timer 0.										
	0: Counter/Timer uses the system clock divided by 12.										
	1: Counter/Timer uses the system clock.										
			5								
Bits2-0	Reserved. Rea	ad = 000b, N	fust Write = (	)00.							

## Figure 19.6. CKCON: Clock Control Register



### Figure 19.7. TL0: Timer 0 Low Byte

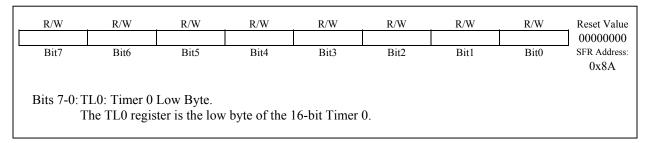


Figure 19.8. TL1: Timer 1 Low Byte

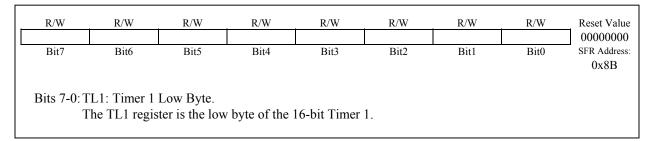
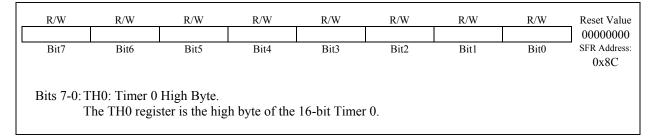
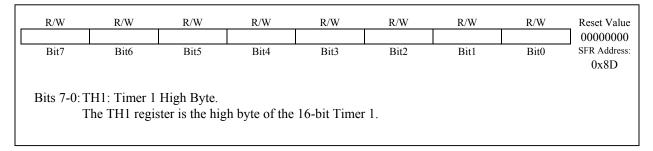


Figure 19.9. TH0: Timer 0 High Byte



### Figure 19.10. TH1: Timer 1 High Byte





### **19.2.** Timer **2**

Timer 2 is a 16-bit counter/timer formed by the two 8-bit SFRs: TL2 (low byte) and TH2 (high byte). As with Timers 0 and 1, Timer 2 can use either the system clock or transitions on an external input pin as its clock source. The Counter/Timer Select bit C/T2 bit (T2CON.1) selects the clock source for Timer 2. Clearing C/T2 selects the system clock as the input for the timer (divided by either one or twelve as specified by the Timer Clock Select bit T2M in CKCON). When C/T2 is set to 1, high-to-low transitions at the T2 input pin increment the counter/timer register. (Refer to Section 14 for information on selecting and configuring external I/O pins.) Timer 2 can also be used to start an ADC Data Conversion.

Timer 2 offers capabilities not found in Timer 0 and Timer 1. It operates in one of three modes: 16-bit Counter/Timer with Capture, 16-bit Counter/Timer with Auto-Reload or Baud Rate Generator Mode. Timer 2's operating mode is selected by setting configuration bits in the Timer 2 Control (T2CON) register. Below is a summary of the Timer 2 operating modes and the T2CON bits used to configure the counter/timer. Detailed descriptions of each mode follow.

RCLK	TCLK	CP/RL2	TR2	Mode
0	0	1	1	16-bit Counter/Timer with Capture
0	0	0	1	16-bit Counter/Timer with Auto-Reload
0	1	Х	1	Baud Rate Generator for TX
1	0	Х	1	Baud Rate Generator for RX
1	1	Х	1	Baud Rate Generator for TX and RX
Х	Х	Х	0	Off



#### 19.2.1. Mode 0: 16-bit Counter/Timer with Capture

In this mode, Timer 2 operates as a 16-bit counter/timer with capture facility. A high-to-low transition on the T2EX input pin causes the 16-bit value in Timer 2 (TH2, TL2) to be loaded into the capture registers (RCAP2H, RCAP2L).

Timer 2 can use either SYSCLK, SYSCLK divided by 12, or high-to-low transitions on the external T2 pin as its clock source when operating in Counter/Timer with Capture mode. Clearing the C/T2 bit (T2CON.1) selects the system clock as the input for the timer (divided by one or twelve as specified by the Timer Clock Select bit T2M in CKCON). When C/T2 is set to logic 1, a high-to-low transition at the T2 input pin increments the counter/timer register. As the 16-bit counter/timer register increments and overflows from 0xFFFF to 0x0000, the TF2 timer overflow flag (T2CON.7) is set and an interrupt will occur if the interrupt is enabled.

Counter/Timer with Capture mode is selected by setting the Capture/Reload Select bit CP/RL2 (T2CON.0) and the Timer 2 Run Control bit TR2 (T2CON.2) to logic 1. The Timer 2 External Enable EXEN2 (T2CON.3) must also be set to logic 1 to enable a capture. If EXEN2 is cleared, transitions on T2EX will be ignored.

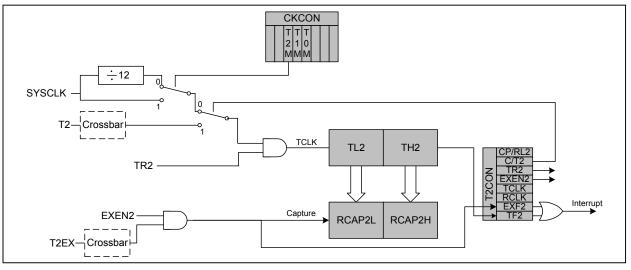


Figure 19.11. T2 Mode 0 Block Diagram



#### 19.2.2. Mode 1: 16-bit Counter/Timer with Auto-Reload

The Counter/Timer with Auto-Reload mode sets the TF2 timer overflow flag when the counter/timer register overflows from 0xFFFF to 0x0000. An interrupt is generated if enabled. On overflow, the 16-bit value held in the two capture registers (RCAP2H, RCAP2L) is automatically loaded into the counter/timer register and the timer is restarted.

Counter/Timer with Auto-Reload mode is selected by clearing the CP/RL2 bit. Setting TR2 to logic 1 enables and starts the timer. Timer 2 can use either the system clock or transitions on an external input pin as its clock source, as specified by the C/T2 bit. If EXEN2 is set to logic 1, a high-to-low transition on T2EX will also cause Timer 2 to be reloaded. If EXEN2 is cleared, transitions on T2EX will be ignored.

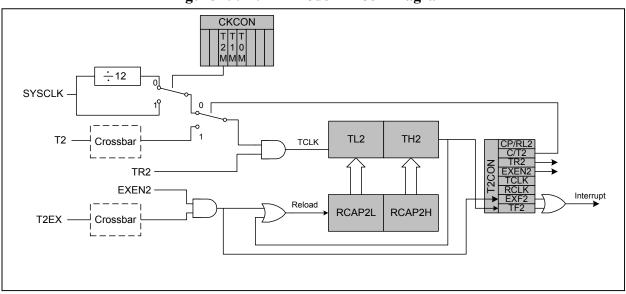


Figure 19.12. T2 Mode 1 Block Diagram



#### 19.2.3. Mode 2: Baud Rate Generator

Timer 2 can be used as a baud rate generator for the serial port (UART) when the UART is operated in modes 1 or 3 (refer to Section 18.1 for more information on UART operational modes). In Baud Rate Generator mode, Timer 2 works similarly to the auto-reload mode. On overflow, the 16-bit value held in the two capture registers (RCAP2H, RCAP2L) is automatically loaded into the counter/timer register. However, the TF2 overflow flag is not set and no interrupt is generated. Instead, the overflow event is used as the input to the UART's shift clock. Timer 2 overflows can be used to generate baud rates for transmit and/or receive independently.

The Baud Rate Generator mode is selected by setting RCLK (T2CON.5) and/or TCLK (T2CON.4) to logic one. When RCLK or TCLK is set to logic 1, Timer 2 operates in the auto-reload mode regardless of the state of the CP/RL2 bit. The baud rate for the UART, when operating in mode 1 or 3, is determined by the Timer 2 overflow rate:

Baud Rate = Timer 2 Overflow Rate / 16.

Note, in all other modes, the timebase for the timer is the system clock divided by one or twelve as selected by the T2M bit in CKCON. However, in Baud Rate Generator mode, the timebase is the system clock divided by two. No other divisor selection is possible. If a different time base is required, setting the C/T2 bit to logic 1 will allow the timebase to be derived from the external input pin T2. In this case, the baud rate for the UART is calculated as:

*Baud Rate = FCLK / [32 \* (65536 – [RCAP2H:RCAP2L]) ]* 

Where FCLK is the frequency of the signal supplied to T2 and [RCAP2H:RCAP2L] is the 16-bit value held in the capture registers.

As explained above, in Baud Rate Generator mode, Timer 2 does not set the TF2 overflow flag and therefore cannot generate an interrupt. However, if EXEN2 is set to logic 1, a high-to-low transition on the T2EX input pin will set the EXF2 flag and a Timer 2 interrupt will occur if enabled. Therefore, the T2EX input may be used as an additional external interrupt source.

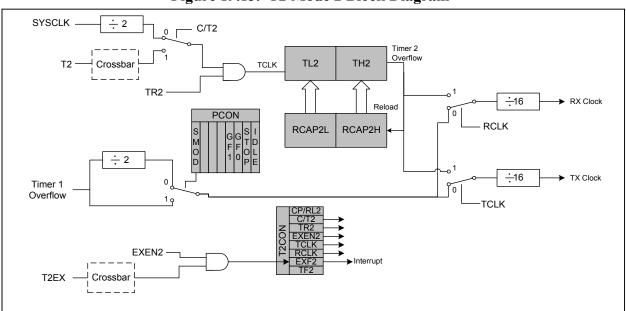


Figure 19.13. T2 Mode 2 Block Diagram

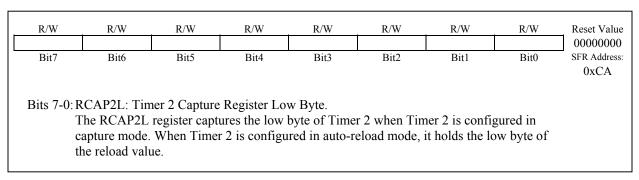


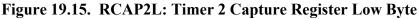
149

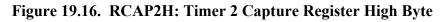
		2				0			
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value	
TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/T2	CP/RL2	00000000	
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (bit addressable)	SFR Address: 0xC8	
Bit7:	TF2: Timer 2 Set by hardwa the Timer 2 in interrupt servi cleared by sof	re when Tim terrupt is ena ce routine. T	er 2 overflo bled, setting this bit is no	this bit cause t automaticall	es the CPU to y cleared by	o vector to th hardware an	ne Timer 2 nd must be		
Bit6:	EXF2: Timer Set by hardwa the T2EX input this bit causes automatically	re when eith at pin and EX the CPU to y	er a capture XEN2 is logi vector to the	c 1. When the Timer 2 Inter	e Timer 2 int rupt service	terrupt is ena routine. Thi	bled, setting		
Bit5:	RCLK: Receip Selects which 0: Timer 1 ovo 1: Timer 2 ovo	timer is used erflows used	for the UA	clock.	clock in mod	les 1 or 3.			
Bit4:	<ul> <li>TCLK: Transmit Clock Flag.</li> <li>Selects which timer is used for the UART's transmit clock in modes 1 or 3.</li> <li>0: Timer 1 overflows used for transmit clock.</li> <li>1: Timer 2 overflows used for transmit clock.</li> </ul>								
Bit3:	EXEN2: Time Enables high- operating in B 0: High-to-low 1: High-to-low	to-low transit aud Rate Get v transitions	tions on T2E nerator mode on T2EX ign	e. nored.	-	eloads when	Timer 2 is not		
Bit2:	TR2: Timer 2 This bit enable 0: Timer 2 dis 1: Timer 2 ena	es/disables T abled.							
Bit1:	<ul> <li>C/T2: Counter/Timer Select.</li> <li>0: Timer Function: Timer 2 incremented by clock defined by T2M (CKCON.5).</li> <li>1: Counter Function: Timer 2 incremented by high-to-low transitions on external input pin (T2).</li> </ul>								
Bit0:	CP/RL2: Capt This bit select be logic 1 for captures or rel in auto-reload 0: Auto-reload 1: Capture on	s whether Tin high-to-low t oads. If RC mode. I on Timer 2	mer 2 function ransitions of LK or TCLI overflow or	n T2EX to be K is set, this b high-to-low t	recognized a it is ignored ransition at 7	and used to t and Timer 2	rigger will function		

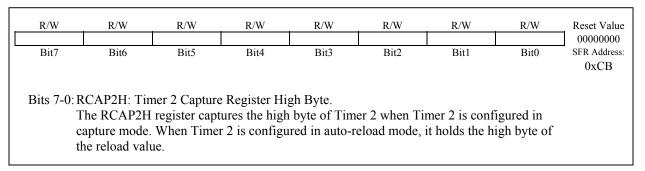




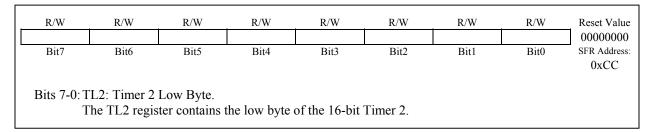




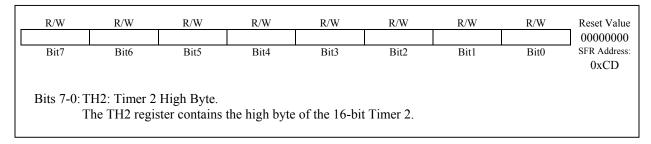




### Figure 19.17. TL2: Timer 2 Low Byte



### Figure 19.18. TH2: Timer 2 High Byte

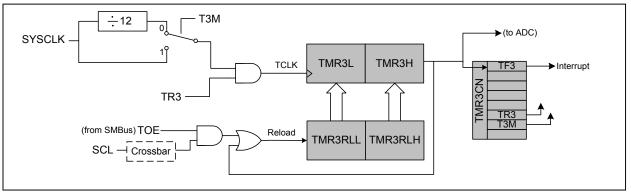




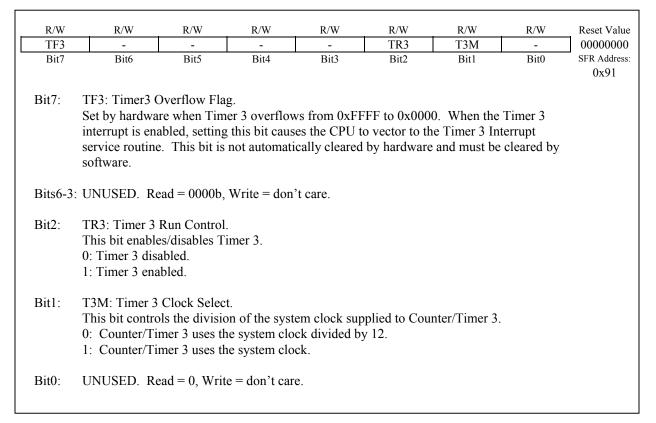
### 19.3. Timer 3

Timer 3 is a 16-bit timer formed by the two 8-bit SFRs, TMR3L (low byte) and TMR3H (high byte). The input for Timer 3 is the system clock (divided by either one or twelve as specified by the Timer 3 Clock Select bit T3M in the Timer 3 Control Register TMR3CN). Timer 3 is always configured as an auto-reload timer, with the reload value held in the TMR3RLL (low byte) and TMR3RLH (high byte) registers. Timer 3 can be used to start an ADC Data Conversion, for SMBus timing (see Section 16.5), or as a general-purpose timer. Timer 3 does not have a counter mode.

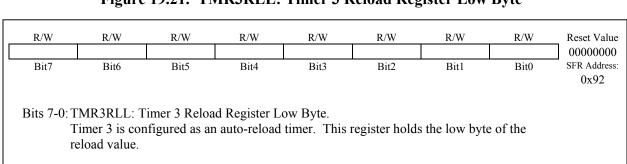




### Figure 19.20. TMR3CN: Timer 3 Control Register

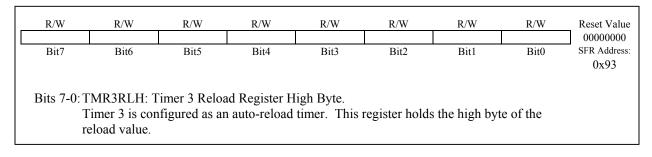




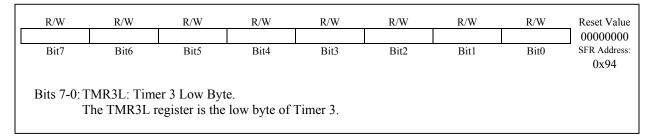


### Figure 19.21. TMR3RLL: Timer 3 Reload Register Low Byte

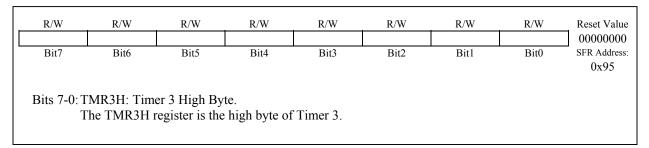




### Figure 19.23. TMR3L: Timer 3 Low Byte



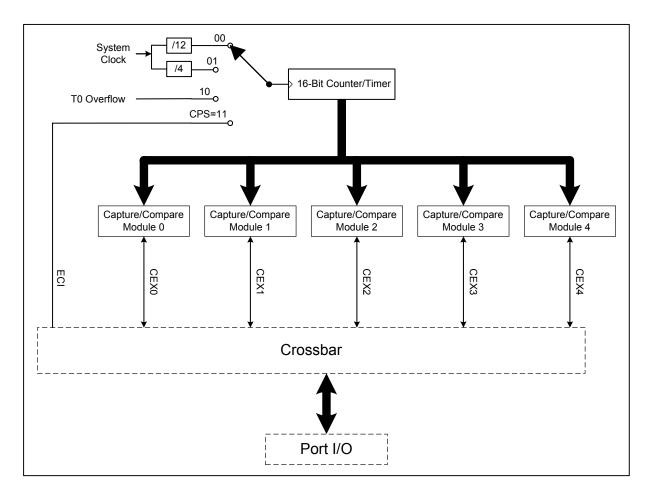






## 20. PROGRAMMABLE COUNTER ARRAY

The Programmable Counter Array (PCA) provides enhanced timer functionality while requiring less CPU intervention than the standard 8051 counter/timers. The PCA consists of a dedicated 16-bit counter/timer and five 16-bit capture/compare modules. Each capture/compare module has its own associated I/O line (CEXn) which is routed through the Crossbar to Port I/O when enabled (see Section 15.1 for details on configuring the Crossbar). The counter/timer is driven by a configurable timebase that can select between four inputs as its source: system clock divided by twelve, system clock divided by four, Timer 0 overflow, or an external clock signal on the ECI line. The PCA is configured and controlled through the system controller's Special Function Registers. The basic PCA block diagram is shown in Figure 20.1.







### 20.1. Capture/Compare Modules

Each module can be configured to operate independently in one of four operation modes: Edge-triggered Capture, Software Timer, High Speed Output, or Pulse Width Modulator. Each module has Special Function Registers (SFRs) associated with it in the CIP-51 system controller. These registers are used to exchange data with a module and configure the module's mode of operation.

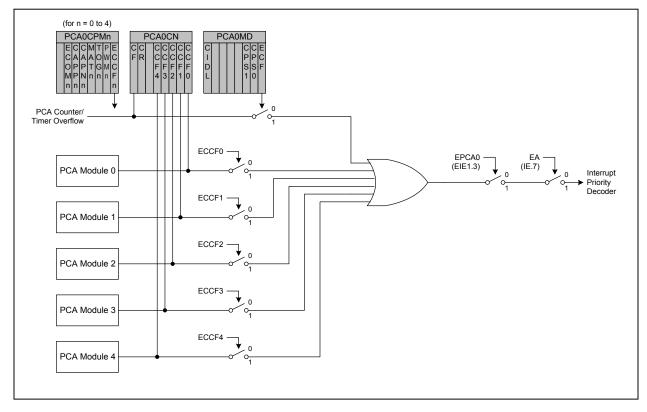
Table 20.1 summarizes the bit settings in the PCA0CPMn registers used to place the PCA capture/compare modules into different operating modes. Setting the ECCFn bit in a PCA0CPMn register enables the module's CCFn interrupt. Note: PCA0 interrupts must be globally enabled before individual CCFn interrupts are recognized. PCA0 interrupts are globally enabled by setting the EA bit (IE.7) and the EPCA0 bit (EIE1.3) to logic 1. See Figure 20.2 for details on the PCA interrupt configuration.

Table 20.1. PCA0CPM Register Settings for PCA Capture/Compare Module	<b>Table 20.1.</b>	PCA0CPM Register	<b>Settings for PCA</b>	Capture/Compa	re Modules
----------------------------------------------------------------------	--------------------	------------------	-------------------------	---------------	------------

ECOM	CAPP	CAPN	MAT	TOG	PWM	ECCF	Operation Mode
Х	1	0	0	0	0	Х	Capture triggered by positive edge on
							CEXn
Х	0	1	0	0	0	Х	Capture triggered by negative edge on
							CEXn
Х	1	1	0	0	0	Х	Capture triggered by transition on CEXn
1	0	0	1	0	0	Х	Software Timer
1	0	0	1	1	0	Х	High Speed Output
1	0	0	Х	0	1	Х	Pulse Width Modulator

X = Don't Care



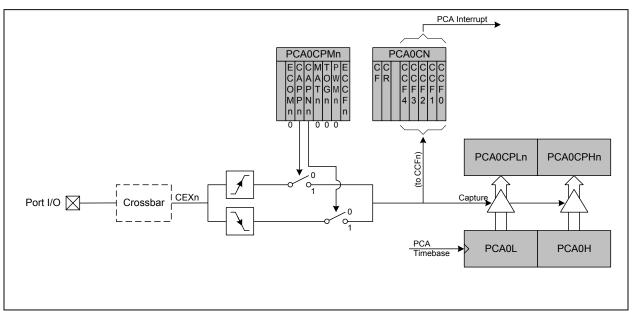




#### 20.1.1. Edge-triggered Capture Mode

In this mode, a valid transition on the CEXn pin causes the PCA to capture the value of the PCA counter/timer and load it into the corresponding module's 16-bit capture/compare register (PCA0CPLn and PCA0CPHn). The CAPPn and CAPNn bits in the PCA0CPMn register are used to select the type of transition that triggers the capture: low-to-high transition (positive edge), high-to-low transition (negative edge), or either transition (positive or negative edge). When a capture occurs, the Capture/Compare Flag (CCFn) in PCA0CN is set to logic 1 and an interrupt request is generated if CCF interrupts are enabled. The CCFn bit is not automatically cleared by hardware when the CPU vectors to the interrupt service routine, and must be cleared by software.

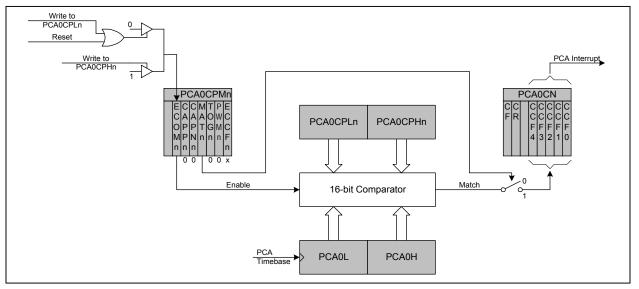


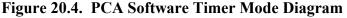




#### 20.1.2. Software Timer (Compare) Mode

In Software Timer mode, the PCA counter/timer is compared to the module's 16-bit capture/compare register (PCA0CPHn and PCA0CPLn). When a match occurs, the Capture/Compare Flag (CCFn) in PCA0CN is set to logic 1 and an interrupt request is generated if CCF interrupts are enabled. The CCFn bit is not automatically cleared by hardware when the CPU vectors to the interrupt service routine, and must be cleared by software. Setting the ECOMn and MATn bits in the PCA0CPMn register enables Software Timer mode.

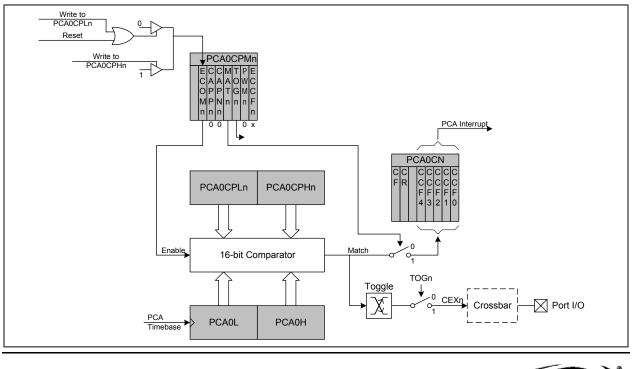




### 20.1.3. High Speed Output Mode

In this mode, each time a match occurs between the PCA Timer Counter and a module's 16-bit capture/compare register (PCA0CPHn and PCA0CPLn) the logic level on the module's associated CEXn pin will toggle. Setting the TOGn, MATn, and ECOMn bits in the PCA0CPMn register enables the High-Speed Output mode.

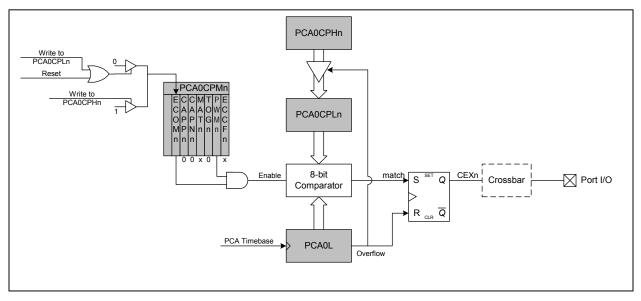
Figure 20.5. PCA High Speed Output Mode Diagram





#### 20.1.4. Pulse Width Modulator Mode

All of the modules can be used independently to generate pulse width modulated (PWM) outputs on their respective CEXn pin. The frequency of the output is dependent on the timebase for the PCA counter/timer. The duty cycle of the PWM output signal is varied using the module's PCA0CPLn capture/compare register. When the value in the low byte of the PCA counter/timer (PCA0L) is equal to the value in PCA0CPLn, the output on the CEXn pin will be set. When the count value in PCA0L overflows, the CEXn output will be reset (see Figure 20.6). Also, when the counter/timer low byte (PCA0L) overflows from 0xFF to 0x00, PCA0CPLn is reloaded automatically with the value stored in the PCA0CPHn without software intervention. It is good practice to write to PCA0CPHn instead of PCA0CPLn to avoid glitches in the digital comparator. Setting the ECOMn and PWMn bits in the PCA0CPMn register enables Pulse Width Modulator mode.







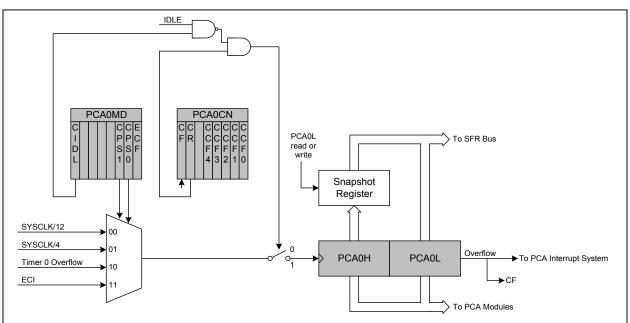
### 20.2. PCA Counter/Timer

The 16-bit PCA counter/timer consists of two 8-bit SFRs: PCA0L and PCA0H. PCA0H is the high byte (MSB) of the 16-bit counter/timer and PCA0L is the low byte (LSB). Reading PCA0L automatically latches the value of PCA0H at the same time. By reading the PCA0L Register first, this allows the PCA0H value to be held (at the time PCA0L was read) until the user reads the PCA0H Register. Reading PCA0H or PCA0L does not disturb the counter operation. The CPS1 and CPS0 bits in the PCA0MD register select the timebase for the counter/timer as shown in Table 20.2.

When the counter/timer overflows from 0xFFFF to 0x0000, the Counter Overflow Flag (CF) in PCA0MD is set to logic 1 and an interrupt request is generated if CF interrupts are enabled. Setting the ECF bit in PCA0MD to logic 1 enables the CF flag to generate an interrupt request. The CF bit is not automatically cleared by hardware when the CPU vectors to the interrupt service routine, and must be cleared by software. (Note: PCA0 interrupts must be globally enabled before CF interrupts are recognized. PCA0 interrupts are globally enabled by setting the EA bit (IE.7) and the EPCA0 bit in EIE1 to logic 1.) Clearing the CIDL bit in the PCA0MD register allows the PCA to continue normal operation while the microcontroller core is in Idle mode.

CPS1	CPS0	Timebase
0	0	System clock divided by 12
0	1	System clock divided by 4
1	0	Timer 0 overflow
1	1	High-to-low transitions on ECI (max rate = system clock divided by 4)

 Table 20.2.
 PCA Timebase Input Options



### Figure 20.7. PCA Counter/Timer Block Diagram



### 20.3. Register Descriptions for PCA

The system device may implement one or more Programmable Counter Arrays. Following are detailed descriptions of the special function registers related to the operation of the PCA. The CIP-51 System Controller section of the datasheet provides additional information on the SFRs and their use.

### Figure 20.8. PCA0CN: PCA Control Register

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu
CF	CR	-	CCF4	CCF3	CCF2	CCF1	CCF0	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (bit addressable)	SFR Address 0xD8
Bit7:	CF: PCA Courses Set by hardwa the Counter/Tivector to the C hardware and the C	re when the mer Overflo F interrupt s	PCA Counte ow (CF) inter service routin	r/Timer over rupt is enable e. This bit is	ed, setting this	s bit causes	the CPU to	
Bit6:	CR: PCA Cou This bit enable 0: PCA Counte 1: PCA Counte	es/disables th er/Timer disa	ne PCA Coun abled.	ter/Timer.				
Bit5:	UNUSED. Re	ead = 0, Writ	te = don't car	e.				
Bit4:	CCF4: PCA M This bit is set I enabled, settin bit is not autor	by hardware g this bit cau	when a matc uses the CPU	h or capture to vector to	the CCF inter	rrupt service	e routine. This	
Bit3:	CCF3: PCA M This bit is set l enabled, settin bit is not autor	by hardware g this bit cau	when a matc uses the CPU	to vector to	the CCF inter	rrupt service	e routine. This	
Bit2:	CCF2: PCA M This bit is set I enabled, settin bit is not autor	by hardware g this bit cau	when a matc uses the CPU	to vector to	the CCF inter	rrupt service	e routine. This	
Bit1:	CCF1: PCA M This bit is set I enabled, settin bit is not autor	by hardware g this bit cau	when a matcuses the CPU	h or capture to vector to	the CCF inter	rrupt service	e routine. This	
Bit0:	CCF0: PCA M This bit is set I enabled, settin	by hardware	when a mate	h or capture				



Figure 20.9	PCA0MD:	PCA Mode	Register
-------------	---------	----------	----------

R/W	R/W	/ F	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
CIDL	-		-	-	-	CPS1	CPS0	ECF	00000000
Bit7	Bite	5 I	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address
									0xD9
Bit7:	CIDL: PO	CA Counte	er/Timer	Idle Control	1.				
	Specifies	PCA beha	avior wł	nen CPU is ir	n Idle Mode.				
							er is in Idle N	Aode.	
	1: PCA (	operation i	s susper	nded while th	ne system cor	troller is in I	dle Mode.		
Bits6-3	: UNUSEI	D. Read $=$	0000b,	Write $=$ don	't care.				
Dito? 1			Counter	Timer Dulce	Select				
Bits2-1				/Timer Pulse					
Bits2-1					Select. r the PCA co	unter.			
Bits2-1	These bit	s select the	e timeba	ise source for		unter.			
Bits2-1	These bit	CPS0	e timeba	use source for <b>base</b>	r the PCA co	unter.			_
Bits2-1	These bit CPS1 0	s select the	e timeba Time Syster	use source for base m clock divid	the PCA co ded by 12	unter.			
Bits2-1	These bit	<b>CPS0</b> 0 1	e timeba Time Syster Syster	base m clock divid m clock divid	the PCA co ded by 12	unter.			
Bits2-1	These bit CPS1 0	CPS0	Time Syster Syster Time	base m clock divid clock divid clock divid	ded by 12 ded by 4				
Bits2-1	These bit CPS1 0	<b>CPS0</b> 0 1	Time Syster Syster Time	base m clock divid clock divid clock divid	ded by 12 ded by 4		system clock	divided by 4	)
Bits2-1	These bit CPS1 0	<b>CPS0</b> 0 1	Time Syster Syster Time	base m clock divid clock divid clock divid	ded by 12 ded by 4		system clock	divided by 4	)
	These bit CPS1 0 0 1 1	CPS0 0 1 0 1	Time Syster Syster Timer High-	base m clock divid m clock divid c 0 overflow to-low transi	ded by 12 ded by 4 itions on ECI	(max rate =	system clock	divided by 4	)
Bits2-1 Bit0:	These bit CPS1 0 0 1 1 ECF: PC	CPS0 0 1 0 1 A Counter	Time Syster Syster Timer High-	base m clock divid m clock divid clock divid clock divid clock divid coverflow to-low transi	ded by 12 ded by 4 itions on ECI errupt Enable	(max rate =	2	divided by 4	)
	These bit CPS1 0 0 1 1 ECF: PC This bit s	CPS0 0 1 0 1 A Counter iets the ma	Time Syster Syster Timer High- /Timer of sking of	base m clock divid m clock divid c 0 overflow to-low transi Overflow Int f the PCA Co	ded by 12 ded by 4 itions on ECI	(max rate =	2	divided by 4	)
	These bit CPS1 0 0 1 1 ECF: PC This bit s 0: Disab	CPS0 0 1 0 1 A Counter ets the ma le the CF i	e timeba Time Syster Syster Timer High- /Timer ( sking of nterrupt	base m clock divid m clock divid c 0 overflow to-low transi Overflow Int f the PCA Co	ded by 12 ded by 4 itions on ECI errupt Enable punter/Timer	(max rate = e. Overflow (C	F) interrupt.		
	These bit CPS1 0 0 1 1 ECF: PC This bit s 0: Disab	CPS0 0 1 0 1 A Counter ets the ma le the CF i	e timeba Time Syster Syster Timer High- /Timer ( sking of nterrupt	base m clock divid m clock divid c 0 overflow to-low transi Overflow Int f the PCA Co	ded by 12 ded by 4 itions on ECI errupt Enable punter/Timer	(max rate = e. Overflow (C	2		



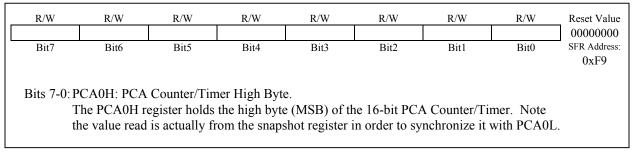
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Valu
-	ECOMn	CAPPn	CAPNn	MATn	TOGn	PWMn	ECCFn	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Addres 0xDA-0xD
PCA0C	PMn Address:							
			1 = 0xDB (n	· · ·				
			2 = 0 xDC (n	/				
			3 = 0xDD (n					
		PCA0CPM	4 = 0 xDE (n	= 4)				
Bit7:	UNUSED. Re	ead = 0, Writ	e = don't car	e.				
Bit6:	ECOMn: Com							
	This bit enable	es/disables th	e comparato	r function for	PCA modul	e <i>n</i> .		
	0: Disabled.							
	1: Enabled.							
Bit5:	CAPPn: Captu							
	This bit enable	es/disables th	e positive ed	ge capture fo	or PCA modu	ıle <i>n</i> .		
	0: Disabled.							
	1: Enabled.							
Bit4:	CAPNn: Captu							
	This bit enable	es/disables th	e negative ed	lge capture f	or PCA mod	ule <i>n</i> .		
	0: Disabled.							
DUA	1: Enabled.							
Bit3:	MATn: Match				1 1	xx71 11	1 , 1 ,	c
	This bit enable							[
	the PCA count		-	re/compare r	egister cause	the CCFn bli	. IN	
	PCA0MD regi	ister to be set	Γ.					
	0: Disabled. 1: Enabled.							
Bit2:	TOGn: Toggle	Function F	nabla					
DIL2.	This bit enable			ption for PC	module n	When enable	d matches	
	of the PCA co							
	CEXn pin to to		module s cap	inter compar	e register eat	ise the logic i	ever on the	
	0: Disabled.	55510.						
	1: Enabled.							
Bit1:	PWMn: Pulse	Width Modu	ulation Mode	Enable.				
	This bit enable				PCA modul	e n. When er	nabled, a	
	pulse width me							
	0: Disabled.	e	1		1			
	1: Enabled.							
Bit0:	ECCFn: Captu	ire/Compare	Flag Interrup	ot Enable.				
	This bit sets th				ag (CCFn) ir	nterrupt.		
	0: Disable CC			-	- ` /			
		apture/Comp						

## Figure 20.10. PCA0CPMn: PCA Capture/Compare Registers

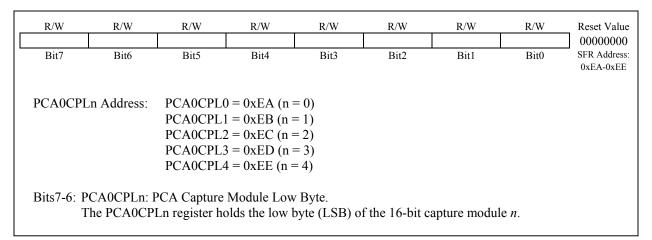


R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value 00000000			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xE9			
	Bits 7-0: PCA0L: PCA Counter/Timer Low Byte. The PCA0L register holds the low byte (LSB) of the 16-bit PCA Counter/Timer.										

### Figure 20.12. PCA0H: PCA Counter/Timer High Byte



### Figure 20.13. PCA0CPLn: PCA Capture Module Low Byte



### Figure 20.14. PCA0CPHn: PCA Capture Module High Byte

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value 00000000		
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address: 0xFA-0xFE		
	PCA0CPHn Address: PCA0CPH0 = $0xFA$ (n = 0) PCA0CPH1 = $0xFB$ (n = 1) PCA0CPH2 = $0xFC$ (n = 2) PCA0CPH3 = $0xFD$ (n = 3) PCA0CPH4 = $0xFE$ (n = 4)									
	CA0CPHn: I The PCA0CPI	-	-	•	of the 16-bit	capture mod	ule n.			



## 21. JTAG (IEEE 1149.1)

Each MCU has an on-chip JTAG interface and logic to support boundary scan for production and in-system testing, Flash read and write operations, and non-intrusive in-circuit debug. The JTAG interface is fully compliant with the IEEE 1149.1 specification. Refer to this specification for detailed descriptions of the Test Interface and Boundary-Scan Architecture. Access of the JTAG Instruction Register (IR) and Data Registers (DR) are as described in the Test Access Port and Operation of the IEEE 1149.1 specification.

The JTAG interface is via four dedicated pins on the MCU, which are TCK, TMS, TDI, and TDO. These pins are all 5V tolerant.

Through the 16-bit JTAG Instruction Register (IR), any of the eight instructions shown in Figure 21.1 can be commanded. There are three Data Registers (DR's) associated with JTAG Boundary-Scan, and four associated with Flash read/write operations on the MCU.

		0x0004									
3it15		Bit0									
ID 1	<b>T T T T</b>										
IR value	Instruction	Description									
0x0000	EXTEST	Selects the Boundary Data Register for control and observability of all									
		device pins									
0x0002	SAMPLE/	Selects the Boundary Data Register for observability and presetting the									
	PRELOAD	scan-path latches									
0x0004	IDCODE	Selects device ID Register									
0xFFFF	BYPASS	Selects Bypass Data Register									
0x0082	Flash Control	Selects FLASHCON Register to control how the interface logic responds to									
		reads and writes to the FLASHDAT Register									
0x0083	Flash Data	Selects FLASHDAT Register for reads and writes to the Flash memory									
0x0084	Flash Address	Selects FLASHADR Register which holds the address of all Flash read,									
		write, and erase operations									
0x0085	Flash Scale	Selects FLASHSCL Register which controls the prescaler used to generate									
		timing signals for Flash operations									

Figure 21.1.	IR: JTAG	Instruction	Register
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### 21.1. Boundary Scan

The Data Register in the Boundary Scan path is an 87-bit shift register. The Boundary DR provides control and observability of all the device pins as well as the SFR bus and Weak Pullup feature via the EXTEST and SAMPLE commands.

#### Table 21.1. Boundary Data Register Bit Definitions

EXTEST provides access to both capture and update actions, while Sample only performs a capture.

Bit	Action	Target
0	Capture	Reset Enable from MCU
0	Update	Reset Enable to /RST pin
1	Capture	Reset input from /RST pin
1	Update	Reset output to /RST pin
2	Capture	External Clock from XTAL1 pin
2	Update	Not used
2	Capture	Weak pullup enable from MCU
3	Update	Weak pullup enable to Port Pins
4-11	Capture	SFR Address Bus bit from CIP-51 (e.g. Bit4=SFRA0, Bit5=SFRA1)
4-11	Update	SFR Address Bus bit to SFR Address Bus (e.g. Bit4=XSFRA0, Bit5=XSFRA1)
12.10	Capture	SFR Data Bus bit read from SFR (e.g. Bit12=SFRD0, Bit13=SFRD1)
12-19	Update	SFR Data Bus bit written to SFR (e.g. Bit12=SFRD0, Bit13=SFRD1)
20	Capture	SFR Write Strobe from CIP-51
20	Update	SFR Write Strobe to SFR Bus
21	Capture	SFR Read Strobe from CIP-51
21	Update	SFR Read Strobe to SFR Bus
22	Capture	SFR Read/Modify/Write Strobe from CIP-51
22	Update	SFR Read/Modify/Write Strobe to SFR Bus
23,25,27,29,	Capture	P0.n output enable from MCU (e.g. Bit23=P0.0, Bit25=P0.1, etc.)
31,33,35,37	Update	P0.n output enable to pin (e.g. Bit23=P0.00e, Bit25=P0.10e, etc.)
24,26,28,30,	Capture	P0.n input from pin (e.g. Bit24=P0.0, Bit26=P0.1, etc.)
32,34,36,38	Update	P0.n output to pin (e.g. Bit24=P0.0, Bit26=P0.1, etc.)
39,41,43,45,	Capture	P1.n output enable from MCU (e.g. Bit39=P1.0, Bit41=P1.1, etc.)
47,49,51,53	Update	P1.n output enable to pin (e.g. Bit39=P1.00e, Bit41=P1.10e, etc.)
40,42,44,46,	Capture	P1.n input from pin (e.g. Bit40=P1.0, Bit42=P1.1, etc.)
48,50,52,54	Update	P1.n output to pin (e.g. Bit40=P1.0, Bit42=P1.1, etc.)
55,57,59,61,	Capture	P2.n output enable from MCU (e.g. Bit55=P2.0, Bit57=P2.1, etc.)
63,65,67,69	Update	P2.n output enable to pin (e.g. Bit55=P2.00e, Bit57=P2.10e, etc.)
56,58,60,62,	Capture	P2.n input from pin (e.g. Bit56=P2.0, Bit58=P2.1, etc.)
64,66,68,70	Update	P2.n output to pin (e.g. Bit56=P2.0, Bit58=P2.1, etc.)
71,73,75,77,	Capture	P3.n output enable from MCU (e.g. Bit71=P3.0, Bit73=P3.1, etc.)
79,81,83,85	Update	P3.n output enable to pin (e.g. Bit71=P3.0oe, Bit73=P3.1oe, etc.)
72,74,76,78,	Capture	P3.n input from pin (e.g. Bit72=P3.0, Bit74=P3.1, etc.)
80,82,84,86	Update	P3.n output to pin (e.g. Bit72=P3.0, Bit74=P3.1, etc.)



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#### **21.1.1. EXTEST Instruction**

The EXTEST instruction is accessed via the IR. The Boundary DR provides control and observability of all the device pins as well as the SFR bus and Weak Pullup feature. All inputs to on-chip logic are set to one.

#### **21.1.2. SAMPLE Instruction**

The SAMPLE instruction is accessed via the IR. The Boundary DR provides observability and presetting of the scan-path latches.

#### 21.1.3. BYPASS Instruction

The BYPASS instruction is accessed via the IR. It provides access to the standard 1-bit JTAG Bypass data register.

#### 21.1.4. IDCODE Instruction

The IDCODE instruction is accessed via the IR. It provides access to the 32-bit Device ID register.

### Figure 21.2. DEVICEID: JTAG Device ID Register

Ver	sion	Part N	lumber		Manufacturer ID		1	Reset Value (Varies)
Bit31	Bit28	Bit27	Bit12	Bit11		Bit1	Bit0	
	000b (Revisi 001b (Revisi							
Part Numbe		0 0000 0000b d 0 0000 0010b	or					
Manufactur	er ID = 0010	0100 001b (Sili	con Laboratorie	s)				



#### 21.2. Flash Programming Commands

The Flash memory can be programmed directly over the JTAG interface using the Flash Control, Flash Data, Flash Address, and Flash Scale registers. These Indirect Data Registers are accessed via the JTAG Instruction Register. Read and write operations on indirect data registers are performed by first setting the appropriate DR address in the IR register. Each read or write is then initiated by writing the appropriate Indirect Operation Code (IndOpCode) to the selected data register. Incoming commands to this register have the following format:

19:18	17:0
IndOpCode	WriteData

IndOpCode: These bit set the operation to perform according to the following table:

IndOpCode	Operation
0x	Poll
10	Read
11	Write

The Poll operation is used to check the Busy bit as described below. Although a Capture-DR is performed, no Update-DR is allowed for the Poll operation. Since updates are disabled, polling can be accomplished by shifting in/out a single bit.

The Read operation initiates a read from the register addressed by the IR. Reads can be initiated by shifting only 2 bits into the indirect register. After the read operation is initiated, polling of the Busy bit must be performed to determine when the operation is complete.

The write operation initiates a write of WriteData to the register addressed by the IR. Registers of any width up to 18 bits can be written. If the register to be written contains fewer than 18 bits, the data in WriteData should be left-justified, i.e. its MSB should occupy bit 17 above. This allows shorter registers to be written in fewer JTAG clock cycles. For example, an 8-bit register could be written by shifting only 10 bits. After a Write is initiated, the Busy bit should be polled to determine when the next operation can be initiated. The contents of the Instruction Register should not be altered while either a read or write operation is in progress.

Outgoing data from the indirect Data Register has the following format:

19	18:1	0	
0	ReadData	Busy	

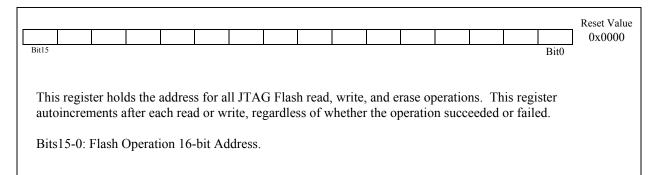
The Busy bit indicates that the current operation is not complete. It goes high when an operation is initiated and returns low when complete. Read and Write commands are ignored while Busy is high. In fact, if polling for Busy to be low will be followed by another read or write operation, JTAG writes of the next operation can be made while checking for Busy to be low. They will be ignored until Busy is read low, at which time the new operation will initiate. This bit is placed at bit 0 to allow polling by single-bit shifts. When waiting for a Read to complete and Busy is 0, the following 18 bits can be shifted out to obtain the resulting data. ReadData is always right-justified. This allows registers shorter than 18 bits to be read using a reduced number of shifts. For example, the result from a byte-read requires 9 bit shifts (Busy + 8 bits).



WRMD3	WRMD2	WRMD1	WRMD0	RDMD3	RDMD2	RDMD1	RDMD0	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
	ter determine AT Register.	s how the Fla	ash interface	logic will res	pond to read	s and writes	to the	
	WRMD3-0: W				1 .	1	1	
	The Write Mo TLASHDAT I				e logic respo	nds to writes	to the	
	000: A FLA				FLASHDAT	register, but	is otherwise	
	ignored		· · F · · · · · ·			,		
0	001: A FLA							
		•	ASHADR re	gister. FLAS	SHADR is in	cremented by	y one when	
0	comple 010: A FLA		e initiates an	eracure (ceta	all bytes to (	)vFF) of the	Flach nage	
0			ess in FLASH					
							OFF, the entir	e
			rased (i.e. ent	ire Flash mei	mory except f	for Reserved	area 0x7E00	_
	0x7FFF	/		1)				
(.	All other valu	les for WRM	ID3-0 are res	erved.)				
Bits3-0: F	RDMD3-0: R	ead Mode Se	lect Bits.					
	The Read Mo				e logic respor	nds to reads t	o the	
	LASHDAT 1 000: A FLA					aistor but is	othorwise	
0	ignored		i provides die	cuata ili tile r	ASHDATIC	gister, but is	otherwise	
0			l initiates a re	ad of the byt	e addressed b	by the FLAS	HADR registe	er
			rrently active				-	
0							DR only if no	
			nd any data f mode allows					
		t initiating an		single bytes	to be read (bi	i ille last bytt		

### Figure 21.3. FLASHCON: JTAG Flash Control Register







### Figure 21.5. FLASHDAT: JTAG Flash Data Register

	÷								•	Reset Value
DATA7	DATA6	DATA5	DATA4	DATA3	DATA2	DATA1	DATA0	FAIL	FBUSY	0000000000
Bit9	Bit8	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
	gister is us			ita to the F	lash mem	ory across	the JTAG	interface.		
Bit1:	0: Pr 1: Pr	ash Fail Bi evious Fla evious Fla cation was	sh memory sh memory	1			icates the a	ssociated	memory	
Bit0:	0: Fla 1: Fla	Flash Bus ash interfa ash interfa t initiate a	ce logic is ce logic is	processin	g a request	. Reads o	r writes wh	ile FBUS	Y = 1 will	

## Figure 21.6. FLASHSCL: JTAG Flash Scale Register

								Reset Valu
FOSE	FRAE	-	-	FLSCL3	FLSCL2	FLSCL1	FLSCL0	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	
	ster controls the Flash operation		timing circu	it and the pre	scaler require	ed to generat	e the correct	
(	FOSE: Flash ( ): Flash read : 1: Flash read :	strobe is a fu	ll clock-cycl	e wide.				
(		output enable ory.	and sense and and sense and gital supply	mplifier enab	le are always	on. This ca	n be used to	
Bits5-4: U	JNUSED. Re	ead = 00b, W	rite = don't o	care.				
Rits3-0. I	FLSCL3-0: FL	ash Prescaler	Control Bits	2				
	The FLSCL3-0. 11				erate timing	signals for Fl	ash	
	operations. Its							e
	written should						u. The full	•
	FLSC	CL[3:0] > log	2(f <sub>SYSCLK</sub> / 50	)kHz)				
	Whome f	•	1 1. fr	A 11 E1	1 1/	e/erase opera		



### 21.3. Debug Support

Each MCU has on-chip JTAG and debug circuitry that provide *non-intrusive, full speed, in-circuit debug using the production part installed in the end application* using the four pin JTAG I/F. Silicon Labs' debug system supports inspection and modification of memory and registers, setting breakpoints, watchpoints, single stepping, and run and halt commands. No additional target RAM, program memory, or communications channels are required. All the digital and analog peripherals are functional and work correctly (remain in sync) while debugging. The WDT is disabled when the MCU is halted during single stepping or at a breakpoint.

The C8051F000DK, C8051F005DK, C8051F010DK, and C8051F015DK are development kits with all the hardware and software necessary to develop application code and perform in-circuit debugging with each MCU in the C8051F000 family. Each kit includes an Integrated Development Environment (IDE) which has a debugger and integrated 8051 assembler. It has an RS-232 to JTAG protocol translator module referred to as the EC. There is also a target application board with a C8051F000, F005, F010, or F015 installed and with a large prototyping area. The kit also includes RS-232 and JTAG cables, and wall-mount power supply.



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